MCXW71

MCX W71 Product Family

Rev. 3 — 29 September 2026

Product data sheet

1 Introduction

Features

- The MCX W71 product family is a low-power, highly secure, single chip multiprotocol wireless MCU that integrates a high performance Bluetooth Low Energy version 6.3 radio and an IEEE 802.15.4 radio supporting Thread, Matter and Zigbee and CAN FD for Industrial applications. The MCX W71 implements a tri-core architecture to isolate the connectivity, computing and security capabilities.
- An integrated FlexCAN supporting CAN and CAN FD compliant with the ISO 11898-1 standard.
- The multiprotocol radio is energy efficient, supports full simultaneous dual-PAN to enable Thread and Zigbee, and designed for Wi-Fi coexistence. The radio is supported with tested software stacks for Matter, Thread, Zigbee and Bluetooth Low Energy for standalone and hosted applications to enable a range of IoT and industrial applications.
- The MCX W71 integrates a state-of-the-art, scalable security architecture including Arm® TrustZone®-M, a resource domain controller and an isolated EdgeLock™ Secure Enclave supporting hardware cryptographic accelerators, random number generators, key generation, storage and management, and secure debug. Flash memory contents can optionally be stored as encrypted data and then decrypted on-the-fly enabling protection of sensitive data and algorithms.
- The MCX W71 implements a flexible power efficient architecture to extend battery life and reduce energy footprint in IoT devices.
- The MCX W71 integrates with a Narrowband Unit (NBU), a dedicated wireless subsystem with an Arm Cortex-M3 core and dedicated memory resources that implements Bluetooth LE and IEEE 802.15.4 radio functionality independently of the application processor.

Application core

- Up to 96 MHz Arm Cortex®-M33 core
- TrustZone-M, IEEE 754 FPU, DSP, MPU, NVIC, SysTick
- 8 KB Code Cache to improve performance and efficiency
- 1 MB flash memory
- 128 KB SRAM
- Secure Boot ROM
- Bluetooth LE Controller stack and transceiver drivers contained in on-chip radio memory, preserving more on-chip system memory for host stack and application space

Low-power consumption (DCDC 3.6 V, 25 ºC)

- Typical active core current: < 5.3 mA at 96 MHz (< 55 µA/MHz)
- Transceiver current (DC-DC buck mode, 3.3 V supply)
  - Typical RX: 4.7 mA
  - Typical TX at 0 dBm: 4.6 mA
  - Typical TX at 10 dBm: 18.7 mA
- Less than 3 µA in Power-down mode with real-time clock (RTC) active and 32 KB SRAM retention

EdgeLock Secure Enclave

- Secure boot and debug
- Trusted Resource Domain Controller (TRDC) providing programmable control mechanisms for independent processing domains including embedded memory and peripherals
  - Privilege/user
  - Data only
  - Execute only
  - Read-only access
  - Secure/Non-secure
- Advanced flash access protection
  - Write/Erase protection, Execute only, Data only access control
  - Optional encryption and on-the-fly decryption using a PRINCE XEX block cipher mode
- Hardware encryption and decryption
  - Symmetric Key Encryption
    - AES-128/192/256

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- Less than 1.5 µA in Deep Power-down mode with RTC active
- Multiple power-down modes supporting currents as low as 300 nA
- Ultra-low leakage Smart Power Switch with less than 100 nA sleep current with exit from internal timer or GPIO.

Clocks

- 32 MHz RF crystal oscillator
- 32.768 kHz crystal oscillator
- Internal 192 MHz high frequency free running oscillator providing 48/64/96 MHz clock
- Internal low frequency free running oscillator providing 6 MHz clock
- Internal low-power free running oscillator providing 32 kHz clock

Communication interfaces

- FlexCAN with CAN and CAN FD supporting the full implementation of the CAN Specification Version 2.0, Part B. FD Support
- Two Low Power UART (LPUART) modules
- Two Low Power SPI modules and one MIPI-I3C module
- Two Low Power I2C (LPI2C) modules supporting the System Management Bus (SMBus) Specification, version 2
- One programmable FlexIO module supporting emulation of UART, I2C, I2S, SPI, Camera IF, LCD RGB, PWM/ Waveform generation

Analog modules

- 16-bit single ended SAR Analog-to-digital converter (ADC) up to 2 Msps
- Two 6-bit High-speed analog comparators (CMP) with 8-bit digital-to-analog converter (DAC)
- 1.0 V to 2.1 V Voltage Reference (Vref)

Timers

- One 2-channel 32-bit timers (LPTPM)
- Two 6-channel 32-bit timers (LPTPM) with PWM capability and DMA support
- Two 32-bit low-power timers (LPTMR) or pulse counters with compare features
- 4-channel 32-bit low-power periodic interrupt timer (LPIT) with DMA support
    - ECB, CBC, CFB, OFB, CTR, GCM, CMAC, and CCM Modes
    - ChaCha20
  - Asymmetric Key Encryption
    - RSA-2048/3072/4096
    - ECC NIST P–192/224/256/384/521
    - Curve25519
  - Key Exchange Algorithms
    - ECDH(E)
    - SPAKE2+
    - JPAKE
  - Digital Signature Algorithms
    - ECDSA
    - Ed25519
  - Hash Algorithms
    - SHA2-224/256/384/512
    - Poly1305
- Secure key generation, storage, and management
- Pseudo (PRNG) and True Random Number Generator (TRNG) with 512-bits entropy supporting NIST SP 800-90A and SP 800-90B
- Support for secure over-the-air (OTA) firmware updates
- Four digital tamper pins with optional interrupt and seconds timestamp upon trigger
- Universally Unique ID (UUID) programmed by NXP during factory programming
- Factory Root of Trust programming

Input supply voltage options:

- Integrated DCDC regulator 1.71 V–3.6 V providing power to Core_LDO regulator, SYS_LDO regulators, and Radio
- Integrated Core_LDO regulator 1.2 V–3.6 V powering the core digital domain
- Integrated SYS_LDO regulator 1.71 V to 3.6 V powering the SYS domain
- DCDC and Core_LDO regulators can support bypass modes
- Radio Analog: 1.2 V–3.6 V
- Radio PA: 0.9 V–2.4 V

Target applications

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- One 56-bit timestamp timer
- 32-bit seconds real time counter (RTC) with 32-bit alarm and independent power supply
- Signal frequency analyzer (SFA) provides facilities for measurement of clock period/frequency as well as time between triggers

Narrow Band Radio Unit

- Dedicated CM3 core running at up to 64 MHz
- 256 kB Flash supporting upgradable software radio
- 88 KB SRAM optimized for link layer support
- IEEE 802.15.4 Radio
  - IEEE 802.15.4–2015 compliant radio
  - –103 dBm 250 kbps Receive Sensitivity
  - Programmable Transmit Output Power up to +10 dBm
  - Improved Enhanced ACK timing support in the 802.15.4 hardware which enables synchronized broadcasts to a larger number of sleepy end devices – for example, synchronous window blinds actuation
  - Supports Dual PAN which allows a single radio to participate in two 802.15.4 Personal Area Networks
  - Modulation Types: 2 Level FSK, GFSK, MSK, GMSK
  - Single ended bidirectional RF port
  - Low external component counts for low cost, small form-factor designs
- Bluetooth Low Energy radio core
  - Up to 24 simultaneous connections
  - –106 dBm 125 kbps Long Range Receive Sensitivity
  - –102 dBm 500 kbps Long Range Receive Sensitivity
  - –97.5 dBm 1 Mbps Receive Sensitivity
  - –95 dBm 2 Mbps Receiver Sensitivity
  - Programmable Transmit Output Power up to +10 dBm
  - Data Rates: 125 kbps, 500 kbps, 1 Mbps, and 2 Mbps
- Smart Home IoT
  - Smart Home environmental, occupancy, and security sensors
  - Home Gateways and Bridges
  - Smart Lighting
  - Smart Plugs
  - Access Control
  - HVACs and Thermostats
  - Window Shades
- Industrial/IoT
  - Positioning/Localization
  - Building Control and Monitoring
  - Building HVAC Control
  - Fire and Security
  - Smart Lighting
  - Access Control

Human Machine Interface modules

- General-purpose input/output (GPIO)
- Up to 29 GPIO available in 48-pin HVQFN package
- Up to 22 GPIO available in 40-pin HVQFN package

Safety

- Memory Protection Unit (MPU)
- Register write protection
- Illegal memory access
- Flash area protection
- SRAM Error Correction Code (ECC) and SRAM parity error check
- Clock Frequency Accuracy Measurement Circuit (CAC) using Signal Frequency Analyzer (SFA) module
- Cyclic Redundancy Check (CRC) calculator
- Two internal, independent, and one external watchdog timers
- Clock loss detection
- Main oscillator stop detection (Loss of lock detection)
- Low voltage / high voltage detection

System peripherals

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  - Modulation Types: 2 Level FSK, GFSK, MSK, GMSK
  - Integrated memories in radio containing Bluetooth LE Controller Stack and radio drivers
  - On-chip balun with single ended bidirectional RF port
  - Low external component counts for low cost, small form-factor designs
- For the latest information on Bluetooth® LE stack capabilities and supported features, refer to the MCUXpresso Software Development Kit (SDK) release notes

- DC/DC converter supporting buck and bypass operating modes
- Asynchronous DMA controller with per channel access permissions (secure/non-secure)
- Two internal and one external watchdog monitors
- Nested vectored interrupt controller
- Wakeup unit for power down modes

Operating characteristics

- Temperature range (ambient): –40 °C to 125 °C
- Temperature range (junction): –40 °C to 125 °C
- DC/DC voltage range: 1.8 V to 3.6 V
- Bypass voltage range: 1.8 V to 3.6 V

Table 1. Ordering information

Part number	Flash (KB)	SRAM (KB)	GPIOs	Pin count	Package	CAN	802.15.4	Bluetooth 6.3	Qualification	Temperature	Packaging type
MCXW716CMFTAT	1024	128	29	48	HVQFN	Yes	Yes	Yes	Industrial	-40°C to 125°C	Tray
MCXW716CMFTAR	1024	128	29	48	HVQFN	Yes	Yes	Yes	Industrial	-40°C to 125°C	Tape and Reel
MCXW716AMFTAT	1024	128	29	48	HVQFN	No	Yes	Yes	Industrial	-40°C to 125°C	Tray
MCXW716AMFTAR	1024	128	29	48	HVQFN	No	Yes	Yes	Industrial	-40°C to 125°C	Tape and Reel
MCXW716CMFPAT	1024	128	22	40	HVQFN	Yes	Yes	Yes	Industrial	-40°C to 125°C	Tray
MCXW716CMFPAR	1024	128	22	40	HVQFN	Yes	Yes	Yes	Industrial	-40°C to 125°C	Tape and Reel
MCXW716AMFPAT	1024	128	22	40	HVQFN	No	Yes	Yes	Industrial	-40°C to 125°C	Tray
MCXW716AMFPAR	1024	128	22	40	HVQFN	No	Yes	Yes	Industrial	-40°C to 125°C	Tape and Reel

Table 2. Device Revision Number

Device Mask Set Number	SIM_SDID[REVID]
2P43C	0b10

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Table 3. Related Resources

Type	Description	Resource
Reference Manual	The Reference Manual contains a comprehensive description of the structure and function (operation) of a device.	MCXW71RM
Data Sheet	The Data Sheet includes electrical characteristics and signal connections.	This document
Chip Errata	The chip mask set Errata provides additional or corrective information for a particular device mask set.	MCXW71_2P43C
Package drawing	Package dimensions are provided in package drawings.	• 48 HVQFN:SOT619-17(D) • 40 HVQFN:SOT618-13(DD)

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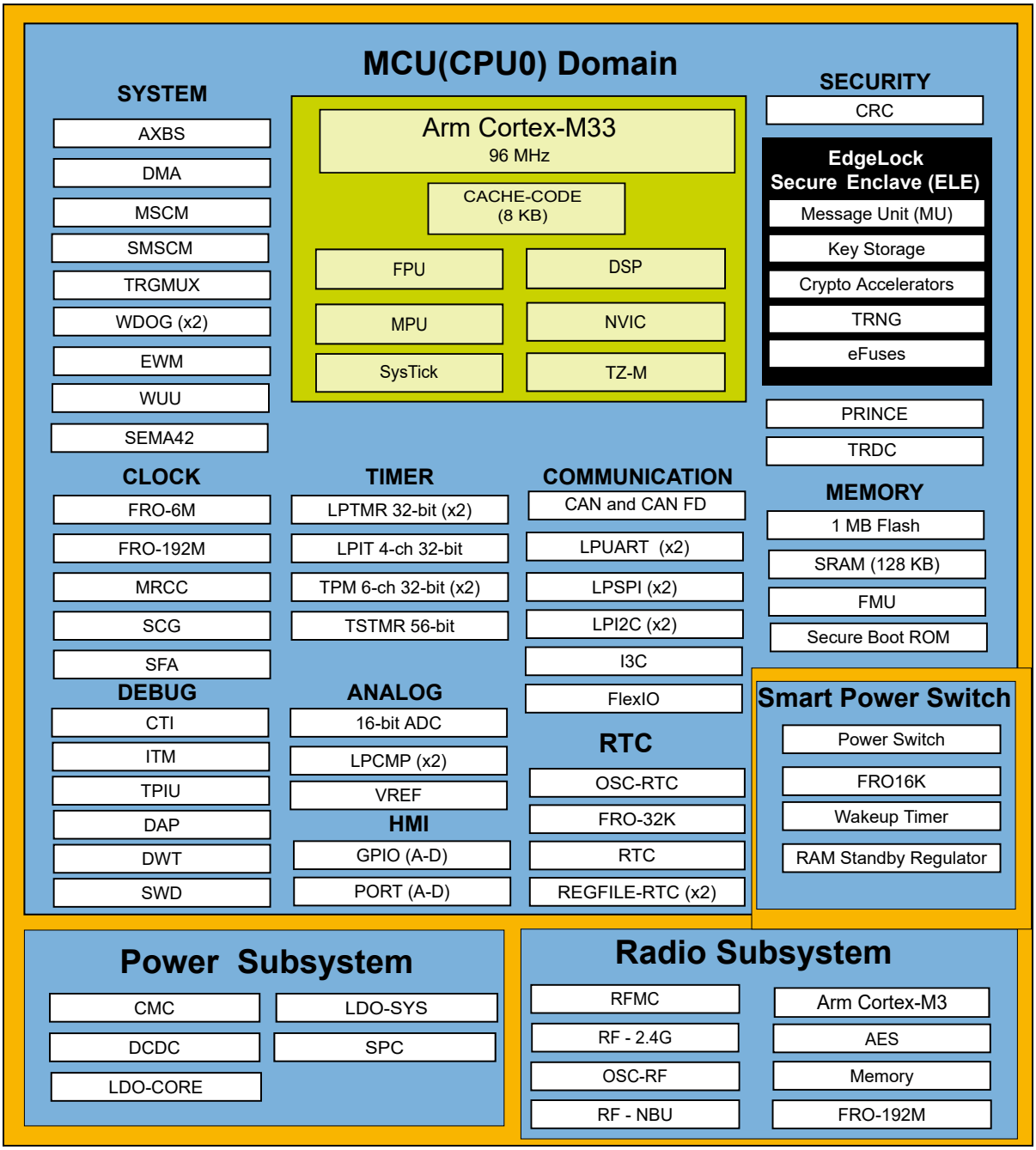
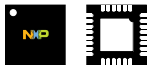
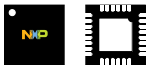


Figure 1. MCXW71 block diagram

1.1 Device isometric diagram



40HVQFN



48HVQFN

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6 x 6 x 0.85 mm	7 x 7 x 0.85 mm
Pitch 0.5 mm	Pitch 0.5 mm
Wettable Flanks	Wettable Flanks

2 Ratings

2.1 Thermal handling ratings

Table 4. Thermal handling ratings

Symbol	Description	Min.	Max.	Unit	Notes
T_{STG}	Storage temperature	–55	150	°C	[1]
T_{SDR}	Solder temperature, lead-free	—	260	°C	[2]

[1] Determined according to JEDEC Standard JESD22-A103, *High Temperature Storage Life*.
[2] Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

2.2 Moisture handling ratings

Table 5. Moisture handling ratings

Symbol	Description	Min.	Max.	Unit	Notes
MSL	Moisture sensitivity level	—	3	—	[1]

[1] Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

2.3 ESD and Latch-Up Ratings

Table 6. ESD and Latch-Up Ratings

Description	Rating	Notes
Electrostatic discharge voltage, human body model	±2000 V	[1]
Electrostatic discharge voltage, charged-device model (corner pins and antenna pin excluded)	±500 V	[2]
Electrostatic discharge voltage, charged-device model (corner pins)	±750 V	
Electrostatic discharge voltage, charged-device model (antenna pin)	±250 V	
Latch-up immunity level (Class II at 125 °C junction temperature)	Immunity Level A	[3]

[1] Determined according to JEDEC Standard JS-001-2017, *For Electrostatic Discharge (ESD) Sensitivity Testing, Human Body Model (HBM) - Component Level*.
[2] Determined according to JEDEC Standard JS-002-2018, *For Electrostatic Discharge (ESD) Sensitivity Testing, Charged-Device Model (CDM) - Device Level* .
[3] Determined according to JEDEC Standard JESD78F, *IC Latch-Up Test*.

2.4 Voltage and current maximum ratings

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Table 7. Voltage and current maximum ratings

Symbol	Description	Min.	Max.	Unit
VDD_CORE	Supply voltage for most digital domains	–0.3	1.26	V
VDD_SYS	Supply voltage for PMC, EFUSE, SRTC, and FROs	–0.3	1.98 [1]	V
VDD_DCDC	Supply voltage for DCDC regulator	–0.3	3.63	V
VDD_IO_D	Supply voltage for LDO_SYS regulator, and PortD	–0.3	3.63	V
VDD_LDO_CORE	Supply voltage for LDO_CORE regulator	–0.3	3.63	V
VDD_RF	Supply voltage for OSC and radio analog	–0.3	3.6	V
VPA_2P4GHZ	Supply voltage for 2.4 GHz radio power amplifier	–0.3	2.8	V
VDD_IO_ABC	Supply voltage for Port A, Port B, Port C, Flash and CMP0/1	–0.3	3.63	V
VDD_ANA	Supply voltage for ADC, DAC, and VREF	–0.3	3.63	V
V_{IN}	Port input voltage	–0.3	3.63 [2]	V
I_D	Maximum current single pin limit (digital output pins)	–25	25	mA

[1] The part supports 2.75 V for up to 20 s over lifetime to allow fuse programming
[2] The Max. of the V_{IN} cannot be greater than the voltage applied to the VDD_IO_*x*.

2.5 Required Power-On-Reset (POR) sequencing

When VDD_CORE is supplied by one of the internal regulators, VDD supply inputs can be powered up in any order. VDD supply inputs on power-up must not exceed VDD voltage maximums.

When powering VDD_CORE with an external supply, VDD_CORE must not be enabled until VDD_IO_ABC ≥ 1.65 V, as shown below.

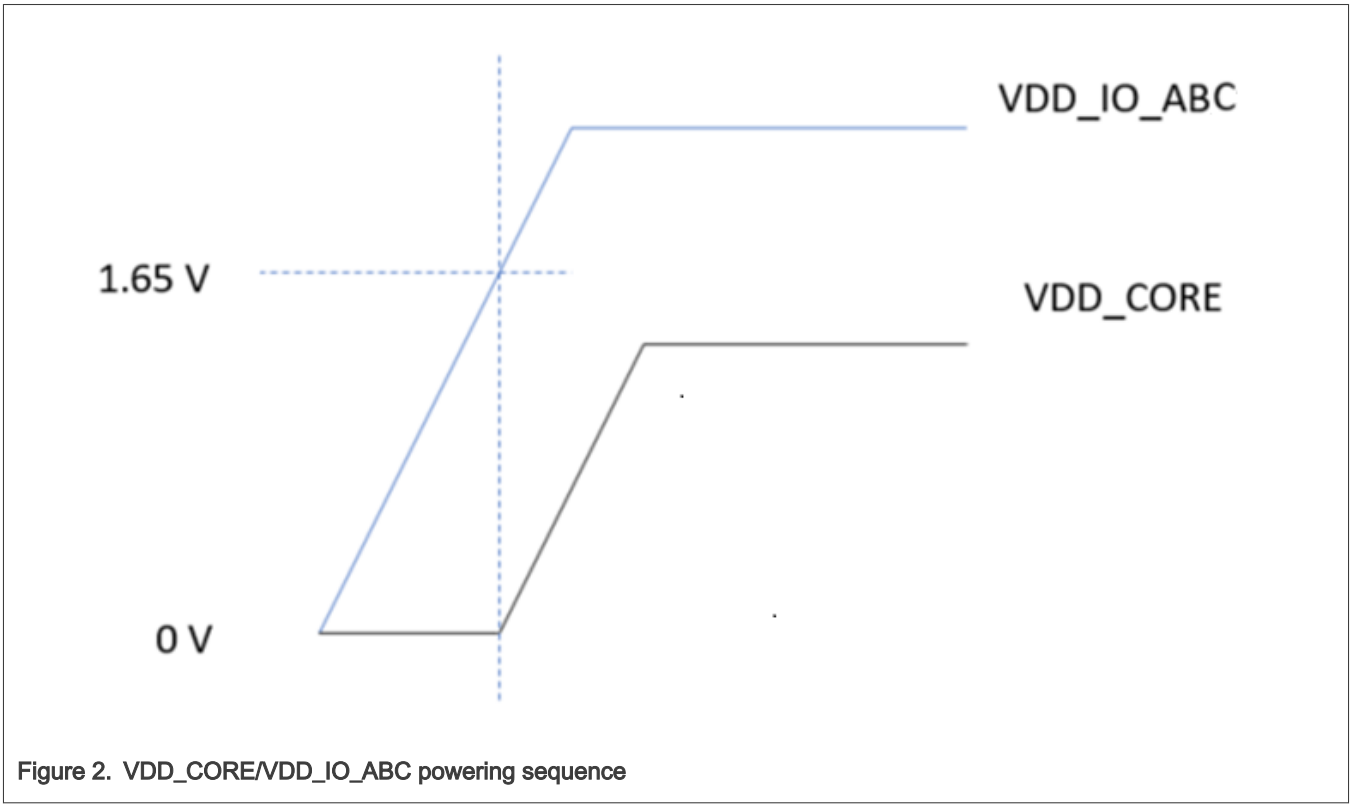


Figure 2. VDD_CORE/VDD_IO_ABC powering sequence

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2.6 Power sequence

Table 8. Power sequence

Symbol	Description	Order in sequence	Notes
VDD_SWITCH	Smart Power Switch input	1	[1]
VDD_DCDC/ VDD_IO_D	DCDC / PORT D / LDO_SYS regulator input	2	[1]
VDD_IO_ABC	Ports A, B, and C power rail input	2	[1]
VDD_ANA	Analog source input	2	[1]
VDD_LDO_CORE	Core power rail input	2	[1]
VDD_RF	RF power rail input	3	[1]
VPA_2P4GHz	RF PA voltage input	4	[1]

[1] All domains can be powered at the same time. If external sources are used, make sure they start at the same time or they follow the order in the sequence.

3 General

3.1 AC electrical characteristics

Unless specified, propagation delays are measured from the 50 % to the 50 % point, and rise and fall times are measured at the 20 % and 80 % points, as shown in the following figure.

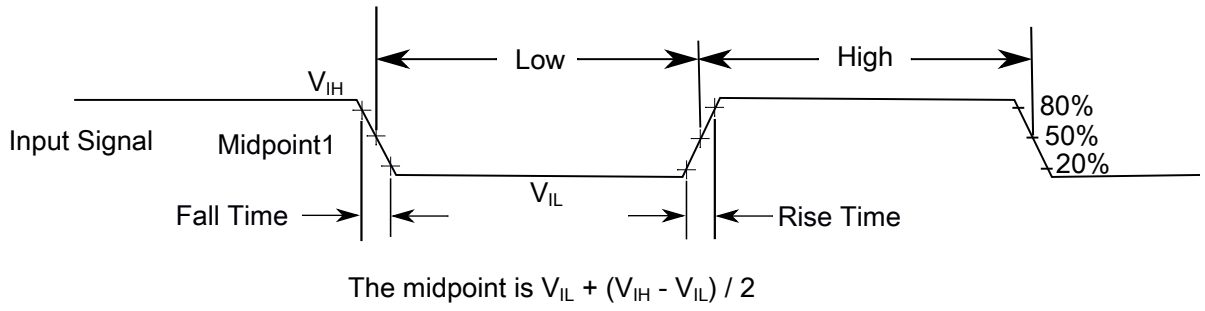


Figure 3. Input signal measurement reference

3.2 Nonswitching electrical specifications

3.2.1 Voltage and current operating requirements

Table 9. Voltage and current operating requirements

Symbol	Description	Min.	Max.	Unit	Notes
VDD_CORE	VDD_CORE input supply voltage			V	—
	Mid Drive (1.05 V) Operation	1.0	1.1		
	Normal Drive (1.1 V) Operation	1.045	1.15		

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Table 9. Voltage and current operating requirements...*continued*

Symbol	Description	Min.	Max.	Unit	Notes
	Safe-Mode Voltage (1.15 V) Operation	1.09	1.21		
VDD_SYS	Supply voltage for System Voltage Domain			V	—
	Normal mode	1.8	1.98		
	Fuse Programming	2.25	2.75		
VDD_DCDC	Supply voltage DCDC regulator	1.8	3.6	V	—
VDD_IO_D	Supply voltage for LDO_SYS regulator, PortD	1.86	3.6	V	[1]
VDD_LDO_CORE	Supply voltage for LDO_CORE regulator	1.25	3.6	V	—
VDD_RF	Supply voltage for OSC and radio analog	1.175	3.6	V	—
VPA_2P4GHz	Supply voltage for 2.4 GHz radio power amplifier	0.9	2.4	V	—
VDD_IO_ABC	Supply voltage for PortA, PortB, Port C, and CMPs	1.71	3.6	V	[2]
VDD_ANA	Supply voltage for ADC, DAC, and VREF	1.71	3.6	V	—
VSS - VSS_ANA	VSS-to-VSS_ANA differential voltage	–0.1	0.1	V	—
V_{IH}	Input high voltage			V	[3]
	1.71 V ≤ VDD_IO_ABC ≤ 3.6 V	0.7 × VDD_IO_ABC	—		
	1.86 V ≤ VDD_IO_D ≤ 3.6 V	0.7 × VDD_IO_D	—		
V_{IL}	Input low voltage			V	[3]
	1.71 V ≤ VDD_IO_ABC ≤ 3.6 V	—	0.3 × VDD_IO_ABC		
	1.86 V ≤ VDD_IO_D ≤ 3.6 V	—	0.3 × VDD_IO_D		
V_{HYS}	Input hysteresis	0.1 × VDD_IO_*X*	—	V	—
I_{ICIO}	IO pin DC injection current — single pin			mA	[4], [5]
	V_{IN} < VSS – 0.3 V (negative current injection)	0	—		
	V_{IN} > VDD + 0.3 V (positive current injection)	—	0		
V_{ODPU}	Open drain pullup voltage level	VDD_IO_*X*	VDD_IO_*X*	V	[6]

[1] When LDO_SYS is not used, the VDD_SYS input supply voltage is 1.8V to 1.98V and VDD_IO_D must be externally connected to VDD_SYS.
[2] If none of the PortA, PortB, and PortC pins are being used, then the VDD_IO_ABC can be left floating.
[3] VIH and VIL for PTD0 are based of VDD_SYS instead of VDD_IO_D
[4] All I/O pins are internally clamped to VSS and VDD_IO_*x* through an ESD protection diode. If V_{IN} is greater than VDD_IO_x_MIN(= VSS – 0.3 V) or is less than VDD_IO_x_MAX(= VDD + 0.3 V), then there is no need to provide current limiting resistors at the pads. If this limit cannot be observed, then a current limiting resistor is required.
[5] This device does not allow pin injection current. User must ensure that VIN is kept within the Voltage Maximum Ratings.
[6] Open drain outputs must be pulled to whichever supply voltage corresponds to that IO, VDD_IO_*X* as appropriate.

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3.2.2 HVD, LVD, and POR operating requirements

The device includes low-voltage detection (LVD) and high-voltage detection (HVD) power supervisor circuits for following power supplies:

- VDD_IO_ABC
- VDD_CORE
- VDD_SYS

For VDD_SYS, it has Power-on-reset (POR) power supervisor circuits.

Table 10. VDD_IO_ABC supply HVD, LVD, and POR operating ratings

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$V_{HVDH_IO_ABC}$	VDD_IO_ABC Rising high-voltage detect threshold	3.730	3.810	3.890	V	—
$V_{HVDH_HYS_IO_ABC}$	VDD_IO_ABC High-voltage inhibit reset/ recover hysteresis	—	38	—	mV	—
$V_{LVDH_IO_ABC}$	VDD_IO_ABC Falling low-voltage detect threshold - high range	2.567	2.619	2.673	V	—
$V_{LVDH_HYS_IO_ABC}$	VDD_IO_ABC Low-voltage inhibit reset/ recover hysteresis - high range	—	27	—	mV	—
$V_{LVDL_IO_ABC}$	VDD_IO_ABC Falling low-voltage detect threshold - low range	1.618	1.651	1.684	V	—
$V_{LVDV_HYS_IO_ABC}$	VDD_IO_ABC Low-voltage inhibit reset/ recover hysteresis - low range	—	20	—	mV	—

Table 11. VDD_CORE supply HVD and LVD operating ratings

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{HVD_CORE}	VDD_CORE Rising high-voltage detect threshold (HVD assertion)					
	Target VDD_CORE = 1.05 V	—	—	—	V	[1]
	Target VDD_CORE = 1.1 V	—	—	—		
	Target VDD_CORE = 1.15 V (safe mode LVD)	1.230	1.257	1.285		
$V_{HVD_HYS_CORE}$	VDD_CORE High-voltage inhibit reset/recover hysteresis					
	Target VDD_CORE = 1.05 V	—	—	—	mV	[1]
	Target VDD_CORE = 1.1 V	—	—	—		
	Target VDD_CORE = 1.15 V (safe mode LVD)	—	14	—		
V_{LVD_CORE}	VDD_CORE Falling low-voltage detect threshold (LVD assertion)					
	Target VDD_CORE = 1.05 V	0.944	0.963	0.983	V	—
	Target VDD_CORE = 1.1 V	0.989	1.009	1.029		
	Target VDD_CORE = 1.15 V (safe mode LVD)	1.043	1.064	1.086		
$V_{LVD_HYS_CORE}$	VDD_CORE Low-voltage inhibit reset/recover hysteresis					
	Target VDD_CORE = 1.05 V	—	14	—	mV	—

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Table 11. VDD_CORE supply HVD and LVD operating ratings...*continued*

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	Target VDD_CORE = 1.1 V	—	14	—		
	Target VDD_CORE = 1.15 V (safe mode LVD)	—	17	—		

[1] Same value applies to all conditions.

Table 12. VDD_SYS supply HVD and LVD operating ratings

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{HVD_SYS}	VDD_SYS Rising high-voltage detect threshold (HVD assertion)					
	Target VDD_SYS = 1.8 V	2.035	2.077	2.120	V	[1]
	Target VDD_SYS = 1.9 V (safe mode LVD)	2.035	2.077	2.120		
$V_{HVD_HYS_SYS}$	VDD_SYS High-voltage inhibit reset/recover hysteresis	—	22	—	mV	—
V_{POR_SYS}	Falling VDD_SYS POR detect voltage (POR assertion)	0.8	1.0	1.5	V	—
V_{LVD_SYS}	VDD_SYS Falling low-voltage detect threshold (LVD assertion)					
	Target VDD_SYS = 1.8 V	1.616	1.649	1.683	V	—
	Target VDD_SYS = 1.9 V (safe mode LVD)	1.700	1.735	1.770		
$V_{LVD_HYS_SYS}$	VDD_SYS Low-voltage inhibit reset/recover hysteresis	—	19	—	mV	—
V_{BG}	Bandgap voltage reference voltage	—	1.0	—	V	—

[1] When fuses are being programmed VDD_SYS is raised to 2.5 V nominal. This is outside the HVD bounds, so HVD detection for VDD_SYS must be disabled when programming fuses

3.2.3 Voltage and current operating behaviors

Table 13. Voltage and current operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{OH}	Output high voltage — Normal drive strength				V	[1]
	2.7 V ≤ VDD_IO_*X* ≤ 3.6 V, I_{OH} = 4 mA	VDD_IO_*X* – 0.5	—	—		
	1.71 V ≤ VDD_IO_ABC < 2.7 V, I_{OH} = 2.5 mA	VDD_IO_*X* – 0.5	—	—		
	1.86 V ≤ VDD_IO_D < 2.7 V, I_{OH} = 2.5 mA	VDD_IO_*X* – 0.5	—	—		
V_{OH}	Output high voltage — High drive strength				V	[1],[2]
	2.7 V ≤ VDD_IO_*X* ≤ 3.6 V, I_{OH} = 6 mA	VDD_IO_*X* – 0.5	—	—		
	1.71 V ≤ VDD_IO_ABC < 2.7 V, I_{OH} = 3.75 mA	VDD_IO_*X* – 0.5	—	—		

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Table 13. Voltage and current operating behaviors...*continued*

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	1.86 V ≤ VDD_IO_D < 2.7 V, I_{OH} = 3.75 mA	VDD_IO_*X* – 0.5	—	—		
I_{OHT}	Output high current total for all ports	—	—	100	mA	—
V_{OL}	Output low voltage — Normal drive strength				V	[1],[3]
	2.7 V ≤ VDD_IO_*X* ≤ 3.6 V, I_{OL} = 4 mA	—	—	0.5		
	1.71 V ≤ VDD_IO_ABC < 2.7 V, I_{OL} = 2.5 mA	—	—	0.5		
	1.86 V ≤ VDD_IO_D < 2.7 V, I_{OH} = 2.5 mA	—	—	0.5		
V_{OL}	Output low voltage — High drive strength				V	[1],[3], [2]
	2.7 V ≤ VDD_IO_*X* ≤ 3.6 V, I_{OL} = 6 mA	—	—	0.5		
	1.71 V ≤ VDD_IO_ABC < 2.7 V, I_{OL} = 3.75 mA	—	—	0.5		
	1.86 V ≤ VDD_IO_D < 2.7 V, I_{OL} = 3.75 mA	—	—	0.5		
I_{OLT}	Output low current total for all ports	—	—	100	mA	—
I_{IN}	Input leakage current (per pin) for full temperature range	—	—	1	µA	[4]
I_{IN}	Input leakage current (per pin) at 25 °C	—	—	0.025	µA	[4]
I_{IN}	Input leakage current (total all pins) for full temperature range	—	—	41	µA	[4]
I_{OZ}	Hi-Z (off-state) leakage current (per pin)	—	—	1	µA	—
R_{PU}	Internal pullup resistors	33	50	75	kΩ	—
R_{PU} (I3C)	Internal pullup resistors	1.1	2	2.833	kΩ	[5]
R_{PD}	Internal pulldown resistors	33	50	75	kΩ	—
R_{HPU}	High-resistance pullup option (PORTx_PCRy[PV] = 1)	0.67	—	1.5	MΩ	[6]
R_{HPD}	High-resistance pulldown option (PORTx_PCRy[PV] = 1)	0.67	—	1.5	MΩ	[6]

[1] When setting DSE1=1, the same VOH / VOL is met with IOH / IOL doubled.
[2] RTC signals are always configured in high drive mode
[3] Open drain outputs must be pulled to VDD_IO_*X*.
[4] Measured at VDD_IO_*X* = 3.6 V.
[5] Only I3C pins support this option
[6] Only Port D pins support this option.

3.2.4 On-chip regulator electrical specifications

3.2.4.1 DCDC converter specifications

Table 14. DCDC converter specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{DD_DCDC}	DCDC input voltage	1.71	—	3.6	V	—

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Table 14. DCDC converter specifications*...continued*

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{OUT_DCDC}	DCDC output voltage	1.25	—	2.5	V	[1], [2]
I_{LOAD}	DCDC load current					
	Normal drive strength	—	—	105	mA	[1], [3]
	Low drive strength	—	—	15		
	SPC_DCD_CFG[FREQ_CNTRL_ON]=1	—	—	45		
LX	DCDC inductor value	0.47	1	2.2	µH	[4]
ESR	External inductor equivalent series resistance	—	110	—	mΩ	[5]
C_{OUT}	DCDC capacitance value	6	22	30	µF	[6][7]
V_{RIPPLE}	DCDC voltage ripple					
	In normal drive strength	—	1	—	%	—
	In low drive strength	—	25	—	mV	
f_{burst}	DCDC burst frequency	3	5	8	MHz	[8]
f_{burst_acc}	DCDC burst frequency accuracy	—	10	—	%	[8]

[1] The system DCDC converter generates 1.8 V at DCDC_LX by default. The DCDC can be used to power VDD_RF, VDD_LDO_CORE, and external components as long as the max I_{LOAD} is not exceeded.
[2] The VDD_DCDC input supply to DCDC must be at least 500 mV higher than the desired output at DCDC_LX.
[3] The maximum load current during boot up shall not exceed 60 mA.
[4] Recommended inductor value is 1 µH to 1.5 µH. If the inductor is < 1 µH, the DCDC efficiency is not guaranteed
[5] The maximum recommended ESR is 250 mΩ (not a hard limit).
[6] The variation in capacitance of the capacitor at DCDC_LX due to aging, temperature, and voltage degradation must not exceed the Min./Max. values.
[7] Cout DCDC capacitance value parameter represents the total capacitance reflected on the DCDC low pass filter. In some configurations, the DCDC output supplies other power rails like VDD_RF, VDD_LDO_CORE and external components. The sum of all parallel capacitances of power rails, external components, and the DCDC low pass filter capacitor itself are included as part of Cout specification.
[8] FREQ_CNTRL_ON = 1.

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DCDC Efficiency plots

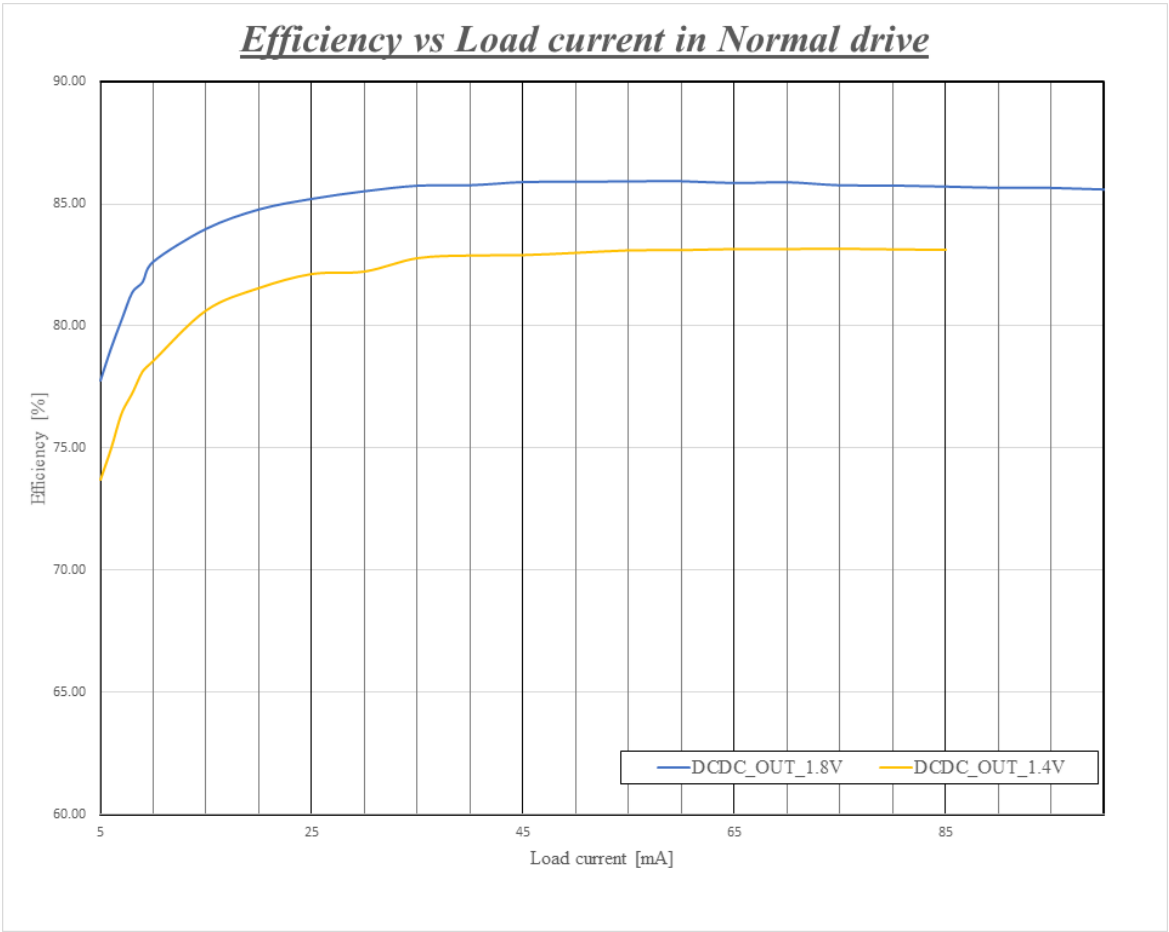


Figure 4. Efficiency vs Load current in Normal drive

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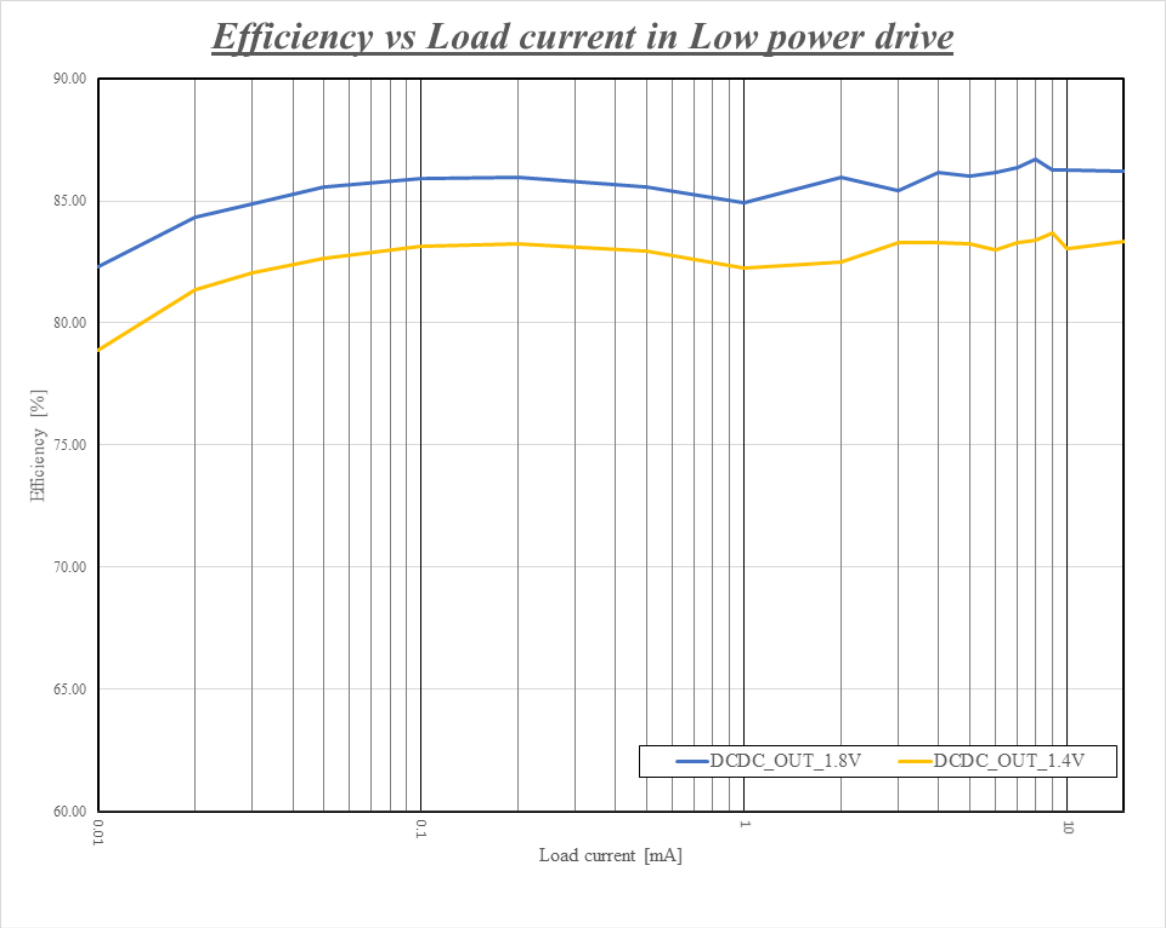


Figure 5. Efficiency vs Load current in Low-power drive

3.2.4.2 LDO_SYS electrical specifications

Table 15. LDO_SYS electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
VDD_IO_D	LDO_SYS input supply voltage					
	LDO_SYS input supply voltage (Regulation mode)	1.86	—	3.6	V	[1]
	LDO_SYS input supply voltage (Bypass mode)	1.8	—	1.98		
	Fuse programming mode	2.75	—	3.6		
VOUT_SYS	LDO_SYS regulator output voltage					
	Normal drive mode	1.71	1.8	1.98	V	[2],[3],[4],[5]
	Fuse Programming mode	2.25	2.5	2.75		
I_{LOAD}	LDO_SYS maximum load current					
	Normal drive mode	—	—	50	mA	—

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Table 15. LDO_SYS electrical specifications*...continued*

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	Low drive mode	—	—	2		
	Fuse programming mode	—	—	40		
I_{DD}	LDO_SYS power consumption					
	Normal drive mode	—	100	—	µA	[6]
	Low drive mode	—	70	—	nA	
C_{OUT}	External output capacitor	1.5	2.2	10	µF	—
C_{DEC}	External output decoupling capacitor	—	0.1	—	µF	—
ESR	External output capacitor equivalent series resistance	—	30	—	mΩ	—
I_{INRUSH}	LDO_SYS inrush current	—	—	120	mA	[7]

[1] Regulator will automatically switch to passthrough (means the regulator driver is fully ON) with the supply is below 1.95 V.
[2] The LDO_SYS converter generates 1.8 V by default at VOUT_SYS. VOUT_SYS can be used to power VDD_SYS, VDD_RF, VDD_IO_*X*, VDD_ANA, and external components as long as the max I_{LOAD} is not exceeded.
[3] VOUT_SYS and VDD_SYS are connected together.
[4] VDD_IO_D must be at least 150 mV higher than the desired VOUT_SYS.
[5] LDO_SYS can be used to program efuse and in this configuration the output voltage can range between 2.25 V and 2.75 V
[6] In normal drive strength, LDO_SYS draws ~100 µA for every 20 mA of load current.
[7] This is for 1.5 µF external output capacitor. If the capacitor has 10 µF value, this value should be 300 mA instead.

3.2.4.3 LDO_CORE electrical specifications

Table 16. LDO_CORE electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
VDD_LDO_CORE	LDO_CORE input supply voltage	1.25	—	3.6	V	[1], [2]
VOUT_CORE	LDO_CORE regulator output voltage					
	Normal drive strength	1.0	—	1.15	V	—
	Low drive strength	1.0	—	1.15		
I_{LOAD}	LDO_CORE max load current					
	Normal mode - VDD_LDO_CORE ≥ 1.5 V	—	—	60	mA	—
	Normal mode - VDD_LDO_CORE < 1.5 V	—	—	30		
	Low-power mode - VDD_LDO_CORE ≥ 1.5 V	—	—	5		
	Low-power mode - VDD_LDO_CORE < 1.5 V	—	—	5		
I_{DD}	LDO_CORE current consumption					
	Normal drive strength - VDD_LDO_CORE ≥ 1.5 V	—	—	150	µA	[3]
	Normal drive strength - VDD_LDO_CORE < 1.5 V	—	—	75		

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Table 16. LDO_CORE electrical specifications*...continued*

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	Low drive strength - VDD_LDO_CORE ≥ 1.5 V	—	—	0.05		
	Low drive strength - VDD_LDO_CORE < 1.5 V	—	—	0.05		
I_{INRUSH}	LDO_CORE inrush current	—	—	5 x I_{LOAD}	mA	—

[1] To bypass LDO_CORE, tie VDD_LDO_CORE to VDD_CORE
[2] The VDD_LDO_CORE input supply must also be at least 250 mV higher than the desired output at VOUT_CORE.
[3] In normal drive strength, LDO_CORE draws ~40 µA for every 20 mA of load current. In low drive strength, LDO_CORE draws ~50 nA for every 100 µA of load current.

Table 17. LDO_CORE external device electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
C_{OUT}	External output capacitor	3.7	4.7	10	µF	—
C_{DEC}	External output decoupling capacitor	—	0.1	—	µF	—
ESR	External output capacitor equivalent series resistance	—	10	—	mΩ	—

3.2.5 Smart power switch

Note: *SWITCH_WAKEUP_B pad is internally pulled up to the switch input through a resistor, it can be pulled down to wake up the smart power switch. To generate a valid internal wake-up signal successfully, maximum value of SWITCH_WAKEUP_B pulldown voltage is 0.7 V, duration time should be larger than 1 µs.*

Table 18. Smart power switch

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{supply}	Input voltage (VDD_SWITCH)	1.9	—	3.6	V	—
R_{ON}	Switch resistor at 'on' state	—	—	3	Ω	—
I_{load}	Load current	—	—	40	mA	—
$I_{leakage1}$	Typical leakage current when Vsupply = 2.7 V, 25 °C	—	4	—	nA	—
$I_{leakage2}$	Maximum leakage current when Vsupply = 3.3 V	—	—	1	µA	—

3.2.6 Power mode transition operating behaviors

All specifications in the following table assume that the default clock configuration will be 96 MHz CPU_CLK/BUS_CLK and 24 MHz slow clock.

Table 19. Power mode transition operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
t_{SLEEP}	SLEEP → ACTIVE	—	8.95	9.4	µs	—
t_{DSLEEP}	DEEP SLEEP → ACTIVE	—	9.6	10.1	µs	—

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Table 19. Power mode transition operating behaviors...*continued*

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
t_{PWDN}	POWER DOWN → ACTIVE	233.86	234.33	234.59	µs	—
t_{DPWDN}	Deep Power DOWN → ACTIVE	747.59	816.12	835.00	µs	—

3.2.7 Power consumption operating behaviors

The MCXW71 device has multiple power supplies that can be connected in different configurations, where the total current consumption of the device is the accumulative result of each individual power supply's current consumption. All current consumption specifications are measured with a bench power supply that provides externally the different voltage levels required by each power domain in the corresponding MCXW71 power mode configuration.

When calculating the total MCU current consumption, the following considerations should be made:

- Specifications below only include power for the MCU itself
- On top of the devices IDD current consumption, external loads applied to pins of the device need to be considered
- Efficiency of regulators (on-chip or off-chip) used to generate supply voltages should be considered

The maximum values stated in the following sections represent characterized results equivalent to the mean plus three times the standard deviation (mean + 6 sigma).

3.2.7.1 Power consumption operating behaviors

Table 20. Power consumption operating behaviors

—	DCDC power configuration						
Mode	Symbol	Description	Temp	Typ	Max	Unit	Notes
IDD_ACT8	IDD_ACT1	Active 1 mode current - DCDC in low strength, Core voltage = 1.0 V, all peripherals disabled, executing while(1) from FLASH in both CM33 at 48 MHz and NBU at 32 MHz	-40°C	4.9	—	mA	[1],[2]
			25°C	5.1	—		
			85°C	5.4	—		
			105°C	5.8	—		
IDD_ACT15	IDD_ACT2	Active 2 mode current - DCDC in normal strength, Core voltage = 1.1 V, all peripherals enabled, executing while(1) from FLASH in both CM33 at 48 MHz and NBU at 32 MHz	25°C	5.5	—	mA	[2],[3]
IDD_ACT16	IDD_ACT3	Active 3 mode current - DCDC in normal strength,	25°C	8.8	—	mA	[2],[3]

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Table 20. Power consumption operating behaviors...*continued*

		Core voltage = 1.1 V, all peripherals enabled, executing while(1) from FLASH in both CM33 at 96 MHz and NBU at 32 MHz					
IDD_ACT17	IDD_ACT4	Active 4 mode current - DCDC in normal strength, Core voltage = 1.1 V, all peripherals disabled, executing while(1) from FLASH in both CM33 at 96 MHz and NBU at 32 MHz	25°C	5.4	—	mA	[2],[3]
IDD_CM1	IDD_CM1	CoreMark 1 mode current - DCDC in normal strength, Core voltage = 1.1 V, all peripherals disabled, executing CoreMark® code from FLASH in CM33 at 96MHz, NBU in sleep mode.	-40°C	6.0	—	mA	[2],[3]
			25°C	6.2	—		
			85°C	6.4	—		
			105°C	7.7	—		
IDD_CM22	IDD_CM2	CoreMark 2 mode current - DCDC in low strength, Core voltage = 1.0 V, all peripherals disabled, executing CoreMark® code from FLASH in CM33 at 48MHz, NBU in sleep mode.	25°C	4.6	—	mA	[1],[2]
IDD_DS1	IDD_DS1	Deep Sleep 1 mode current - All regulators in low-power mode, all RAM retained, all peripherals, NBU, and EdgeLock disabled, OSC32K enabled	-40°C	3.0	—	µA	[4]
			25°C	2.8	—		
			85°C	12.5	—		
			105°C	26.2	—		
IDD_DS2	IDD_DS2	Deep Sleep 2 mode current - All regulators in low	-40°C	2.9	—	µA	[4]
			25°C	2.5	—		

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Table 20. Power consumption operating behaviors...*continued*

		power, 16 KB of RAM retained, all radio RAM retained, all peripherals, NBU, and Edge Lock disabled, OSC32K enabled	85°C	9.2	—		
			105°C	18.4	—		
IDD_PD2	IDD_PD1	Power Down 1 mode current - All regulators in low power, 16 KB of RAM retained, all radio RAM retained, all peripherals, NBU, and Edge Lock disabled, FRO32K enabled	-40°C	3.8	—	µA	[4]
			25°C	3.4	—		
			85°C	9.8	—		
			105°C	18.3	—		
IDD_DPD2	IDD_DPD1	Deep Power Down 1 mode current - LDO_CORE and DCDC off, LDO_SYS in low power, no RAM retained, no radio RAM retained, all peripherals, NBU, and EdgeLock disabled, FRO32K enabled	-40°C	1.70	—	µA	[4]
			25°C	1.2	—		
			85°C	3.7	—		
			105°C	7.2	—		
—	**Smart Power Switch**						
Mode	**Symbol**	**Description**	**Temp**	**Typ**	**Max**	**Unit**	**Notes**
IDD_SW_DPD2	IDD_SW_DPD1	Smart Power Switch Deep Power Down 2 mode current - All regulators off, 8 KB RAM retained, no radio RAM retained, all peripherals, NBU, and EdgeLock disabled, FRO16K enabled	-40°C	0.3	—	µA	[5],[6]
			25°C	0.4	—		
			85°C	2.2	—		
			105°C	3.3	—		

[1] All regulators enabled, 3.3 V supply upstream from the DCDC. DCDC output is 1.8 V, VDD_CORE =1.0. SYS_LDO input=3.3, output = 1.8 V.
[2] FRO-192M as clock source
[3] All regulators enabled, 3.3 V supply upstream from the DCDC. DCDC output is 1.35V, VDD_CORE =1.1. SYS_LDO input=3.3, output = 1.8 V.
[4] All regulators enabled, 3.3 V supply upstream from the DCDC. DCDC output is 1.25V, VDD_CORE =1.0. SYS_LDO input=3.3, output = 1.8V.
[5] 8 KB of retained RAM correspond to the last RAM block and is powered by the standby LDO in smart power switch domain
[6] External 3.3 V supply to Smart Power Switch. Power switch output connected to DCDC_IN, LDO_SYS, VDD_ANA, VDD_IO_D and VDD_IO_ABC; DCDC output connected to LDO_CORE, VDD_RF

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3.2.7.2 Typical power-down mode RAM current adders

The table below shows typical current consumption adders on the VDD_CORE domain for different SRAM configurations. All currents are measured in power-down mode, but RAM adder should be similar for other modes.

Table 21. Typical power-down mode RAM current adders

SRAM array	Non-Secure Start Address	Non-Secure End Address	Size	-40 °C	25 °C	85 °C	105 °C	Unit
CTCM0	0x40000000	0x40001FFF	8 KB	0.061	0.070	1.49	2.44	µA
CTCM1	0x40002000	0x40003FFF	8 KB	0.020	0.026	1.80	2.70	µA
STCM0	0x20000000	0x20003FFF	16 KB	0.142	0.151	2.95	4.68	µA
STCM1	0x20004000	0x20007FFF	16 KB	0.176	0.186	3.06	5.02	µA
STCM2	0x20008000	0x2000FFFF	32 KB	0.321	0.362	4.92	8.93	µA
STCM3	0x20010000	0x20017FFF	32 KB	0.207	0.215	3.76	6.17	µA
STCM4	0x20018000	0x20019FFF	8 KB	0.045	0.046	2.02	2.33	µA
STCM5	0x2001A000	0x2001BFFF	8 KB	1.12	1.16	1.33	1.38	µA

3.2.7.3 Low power mode peripheral power consumption adders

The following measurements were performed in DCDC mode with low drive strength configured at 1.25 V. Supply voltage is at 3.3 V

Table 22. Low power mode peripheral power consumption adders

Symbol	Description	Temperature	Unit
		• 25 °C	
LPTMR	LPTMR peripheral adder measured by placing the device in Deep Power-down mode using the FRO-32K configured for 1 second prescaler with 1 minute match. Include the FRO-32K power consumption.	252.9	nA
LPIT	LPIT peripheral adder measured by placing the device in Sleep mode with Wake Domain place in Sleep. Using FRO6M, configured for a 1 minute match. Does not include selected clock source power consumption.	3.2	µA
TSTMR	TSTMR peripheral adder measured by placing the device in Power-down mode with Wake Domain place in Sleep. Incrementing on the	4.0	µA

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Table 22. Low power mode peripheral power consumption adders...*continued*

	1MHz clock output from the FRO6M. Does not include the selected clock source power consumption.		
TPM0	TPM0 peripheral adder measured by placing the device in Power-down mode with Wake Domain place in Sleep. Using FRO32K configured for output compare generating a 10Hz clock signal. No load is placed on the I/O pin generating the clock signal. Includes the clock source power consumption	4.1	µA
RTC	RTC peripheral adder measured with external 32 kHz OSC enabled with an alarm of 1 minute, by placing the device in Deep Power-down mode. Includes OSC-RTC (32 kHz external crystal) power consumption.	210.7	nA
LPUART1	LPUART1 peripheral adder measured by placing the device in Sleep mode with Wake Domain Sleep. Selected clock source FRO6M as clock source waiting for Rx data at 115200 BR, configuring CC=10b for MRCC_LPUART1. Does not include selected clock source power consumption.	4.2	µA
LPI2C1	LPI2C1 peripheral adder measured by placing the device in Sleep mode configured as target with digital glitch filter disabled. Does not include selected clock source power consumption.	3.2	µA
I3C	LPI3C peripheral adder measured by placing the device in Sleep mode with Wake Domain place in Sleep, while configured as target.	3.3	µA

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Table 22. Low power mode peripheral power consumption adders...*continued*

	Does not include the clock source power		
LPSPI0	LPSPI0 peripheral adder measured by placing the device in Sleep mode with Wake Domain place in Sleep, while configured as target in SPI. Does not include the clock source power consumption.	4.0	µA
FlexIO	FlexIO peripheral adder measured by placing the device in Sleep mode with Wake Domain Sleep, while Using FRO6M, emulating UART waiting for RX data at 115200 baudrate. Does not include selected clock source power consumption.	3.3	µA
ADC	ADC peripheral adder by placing the device in Sleep mode with Wake Domain place in Sleep. ADC in low power single ended mode using the FRO6M and 10Ksps continuous conversion. Does not include selected clock source power consumption.	4.1	µA
CMP	CMP peripheral adder measured with CMP enabled 8-bit DAC and single input for compare. The device is placed in Sleep mode with Wake Domain place in Sleep. Does not include 6-bit DAC power consumption	3.3	µA
VREF	VREF peripheral adder measured by placing the device in Sleep mode with Wake Domain place in Sleep. Generating a 1.2V reference output voltage	3.9	µA
WDOG	WDOG peripheral adder measured by placing the device in Sleep mode with Wake Domain place in Sleep. The peripheral is configured	2.8	µA

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Table 22. Low power mode peripheral power consumption adders...*continued*

	Using OSC-RTC (External 32kHz) using the longest timeout period possible. Includes the OSC_RTC current consumption		

3.2.8 EMC radiated emissions operating behaviors

EMC measurements to IC-level IEC standards are available from NXP on request.

3.2.9 Designing with radiated emissions in mind

To find application notes that provide guidance on designing your system to minimize interference from radiated emissions:

1. Go to https://www.nxp.com/.
2. Perform a keyword search for “EMC design”.

3.2.10 Capacitance attributes

Table 23. Capacitance attributes

Symbol	Description	Min.	Max.	Unit
C_{IN_A}	Input capacitance: analog pins	—	7	pF
C_{IN_D}	Input capacitance: digital pins	—	7	pF

3.3 Switching specifications

3.3.1 Device clock specifications

Table 24. Device clock specifications

Symbol	Description	Min.	Max.	Unit	Notes
VDD_CORE = 1.1 V					
f_{CPU}	CPU clock (CPU_CLK)	—	96	MHz	—
f_{BUS}	Bus clock (BUS_CLK)	—	96	MHz	—
f_{SLOW}	Slow clock (SLOW_CLK)	—	24	MHz	—
VDD_CORE = 1.0 V					
f_{CPU}	CPU clock (CPU_CLK)	—	48	MHz	—
f_{BUS}	Bus clock (BUS_CLK)	—	48	MHz	—
f_{SLOW}	Slow clock (SLOW_CLK)	—	24	MHz	—

Note: *By default, VDD_CORE = 1.0 V, f_{CPU_CLK}/f_{BUS_CLK} = 32 MHz, f_{SLOW_CLK} = 16 MHz.*

3.3.2 General switching specifications

These general-purpose specifications apply to all signals configured for GPIO, LPUART, LPTMR, TPM, LPI2C, LPI3C, LPSPI, or FlexIO functions.

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Table 25. General switching specifications

Description		Min.	Max.	Unit	Notes
GPIO pin interrupt pulse width (digital glitch filter disabled) — Synchronous path		1.5	—	Bus clock cycles	[1]
GPIO pin interrupt pulse width (digital glitch filter disabled, analog filter enabled) — Asynchronous path		150	—	ns	—
GPIO pin interrupt pulse width (digital glitch filter disabled, analog filter disabled) — Asynchronous path		50	—	ns	—
External RESET and NMI pin interrupt pulse width — Asynchronous path		330	—	ns	[2]
GPIO pin interrupt pulse width — Asynchronous path		16	—	ns	[2]
Port rise/fall time					
Normal I/O pins					[3]
2.7 ≤ VDD_IO_*x* ≤ 3.6 V	Fast slew rate (SRE = 0; DSE = 0)	2.9	7	ns	
	Slow slew rate (SRE = 1; DSE = 0)	6	15	ns	
1.71 ≤ VDD_IO_*x* < 2.7 V	Fast slew rate (SRE = 0; DSE = 1)	2.4	7	ns	
	Slow slew rate (SRE = 1; DSE = 1)	6.1	20	ns	
I2C/I3C I/O pins					[4]
2.7 ≤ VDD_IO_*x* ≤ 3.6 V	Normal drive, fast slew rate (SRE = 0; DSE =)	3	7	ns	
	Normal drive, slow slew rate (SRE = 1; DSE = 0)	6.1	15	ns	
	High drive, fast slew rate (SRE = 0; DSE = 1)	2.8	7	ns	
	High drive, slow slew rate (SRE = 1; DSE = 1)	5.6	15	ns	
1.71 ≤ VDD_IO_*x* < 2.7 V	Normal drive, fast slew rate (SRE = 0; DSE = 0)	2.8	7	ns	
	Normal drive, slow slew rate (SRE = 1; DSE = 0)	6.4	20	ns	
	High drive, fast slew rate (SRE = 0; DSE = 1)	2.3	7	ns	
	High drive, slow slew rate (SRE = 1; DSE = 1)	5.7	20	ns	
Reset and NMI pins					[5]
2.7 ≤ VDD_IO_*x* ≤ 3.6 V		3.3	6.7	ns	
1.71 ≤ VDD_IO_*x* < 2.7 V		4.3	20	ns	

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[1] The synchronous and asynchronous timing must be met.
[2] This is the shortest pulse that is guaranteed to be recognized.
[3] Load is 25 pF. Drive strength and slew rate are configured using PORTx_PCRn[DSE] and PORTx_PCRn[SRE].
[4] Load is 25 pF for DSE=0 or DSE=1. Load is 50 pF for DSE=2 or DSE=3. Drive strength and slew rate are configured using PORTx_PCRn[DSE1], PORTx_PCRn[DSE], and PORTx_PCRn[SRE].
[5] Load is 25 pF.

3.4 Thermal specifications

3.4.1 Thermal operating requirements

Table 26. Thermal operating requirements

Symbol	Description	Min.	Typical	Max.	Unit	Notes
T_A	Ambient temperature	–40	25	125	°C	[1]
T_J	Die junction temperature maximum	–	–	125	°C	[2],[3], [4],[5]

[1] The device may operate at maximum T_A rating as long as T_J maximum of 125 °C is not exceeded. The simplest method to determine T_J is: $T_J = T_A + R_{\theta JA} \times$ chip power dissipation.
[2] The device operating specification is not guaranteed beyond 125 °C T_J.
[3] The maximum operating requirement applies to all chapters unless otherwise specifically stated.
[4] Operating at maximum conditions for extended periods may affect device reliability.
[5] The radio performances are guaranteed up to 105°C. Above this temperature, parameters will gradually change.

3.4.2 Thermal attributes

Table 27. Thermal attributes

Board type	Symbol	Description	48 HVQFN	40 HVQFN	Unit	Notes
Four-layer (2s2p)	$R_{\theta JA}$	Thermal resistance, junction to ambient (natural convection)	26	28	°C/W	[1], [2]
—	Ψ_{JT}	Thermal characterization parameter, junction to package top outside center (natural convection)	0.2	0.2	°C/W	[1], [2]

[1] Thermal test board meets JEDEC specification for this package (JESD51-7).
[2] Determined according to JEDEC Standard JESD51-2, *Integrated Circuits Thermal Test Method Environmental Conditions—Natural Convection (Still Air).*

4 Peripheral operating requirements and behaviors

4.1 Core modules

4.1.1 SWD electricals

Table 28. SWD timing

Symbol	Description	Min.	Max.	Unit
—	Operating voltage	1.71	3.6	V
S1	SWD_CLK frequency of operation	—	25	MHz
S2	SWD_CLK cycle period	1/S1	—	ns
S3	SWD_CLK clock pulse width	20	—	ns

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Table 28. SWD timing...*continued*

Symbol	Description	Min.	Max.	Unit
S4	SWD_CLK rise and fall times	—	3	ns
S5	SWD_DIO input data setup time to SWD_CLK rise	10	—	ns
S6	SWD_DIO input data hold time after SWD_CLK rise	0	—	ns
S7	SWD_CLK high to SWD_DIO data valid	—	25	ns
S8	SWD_CLK high to SWD_DIO high-Z	5	—	ns

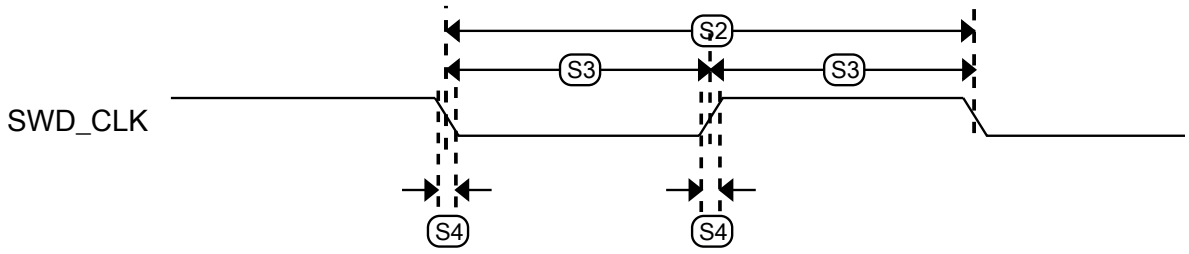


Figure 6. Serial wire clock input timing

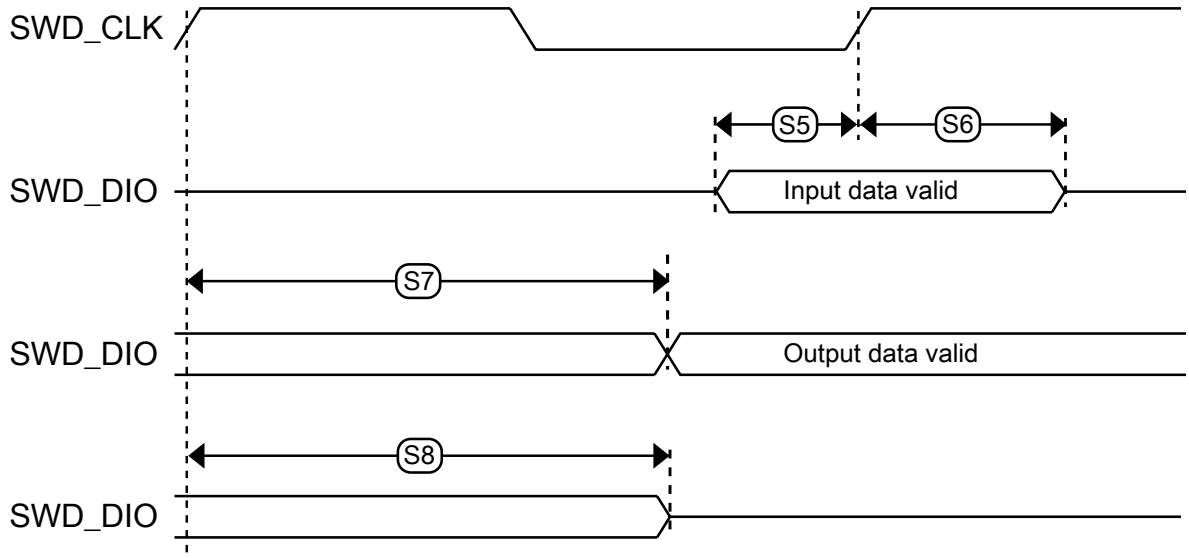


Figure 7. Serial wire data timing

4.2 Clock modules

4.2.1 Reference oscillator specification

This chip is designed to meet targeted specifications with a ±40 ppm frequency error over the life of the part, which includes the temperature, mechanical, and aging excursions.

The table below shows typical specifications for the crystal oscillator.

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Table 29. Reference crystal specification

Symbol	Description	f0 = 32.0 MHz			Unit	Notes
		Min	Typ	Max		
T_A	Operating Temperature	–40	—	105	°C	[1]
ftolat	Crystal frequency tolerance over Aging and Temperature	–33	—	30	ppm	[2],[3]
OSCvar	Oscillator variation	–17	—	20	ppm	[4]
ROscTtol	Total reference oscillator tolerance for Bluetooth LE applications	–50	—	50	ppm	[5]
ROscTtol15.4	Total reference oscillator tolerance for IEEE 802.15.4 applications	–40	—	40	ppm	[5]
C_L	Load capacitance	6	8	10	pF	[2],[6]
C_0	Shunt capacitance	0.469	0.67	0.871	pF	[2],[6]
Cm1	Motional capacitance	1.435	2.05	2.665	fF	[2], [6]
Lm1	Motional inductance	8.47	12.1	15.73	mH	[2],[6]
Rm1	Motional resistance	—	25	50	Ω	[2]
ESR	Equivalent series resistance	—	50	60	Ω	[2], [7]
P_d	Maximum crystal drive	—	—	200	µW	[2]
T_S	Trim sensitivity	6.30	9.00	11.70	ppm/pF	[2],[6]
t_{OSC}	Oscillator Startup Time	—	500	—	µs	[8]

[1] Full temperature range of this device. A reduced range can be chosen to meet application needs.
[2] Recommended crystal specification.
[3] Combination of frequency stability variation over desired temperature range and frequency variation due to aging over desired lifetime of system.
[4] Variation due to temperature, process, and aging of MCU.
[5] Sum of crystal initial frequency tolerance, crystal frequency stability and aging, oscillator variation, and PCB manufacturing variation must not exceed this value.
[6] Typical is target. 30 % tolerances shown.
[7] ESR = Rm1 * (1 + [C_0/C_L])^2.
[8] Time from oscillator enables to clock ready. Dependent on the complete hardware configuration of the oscillator.

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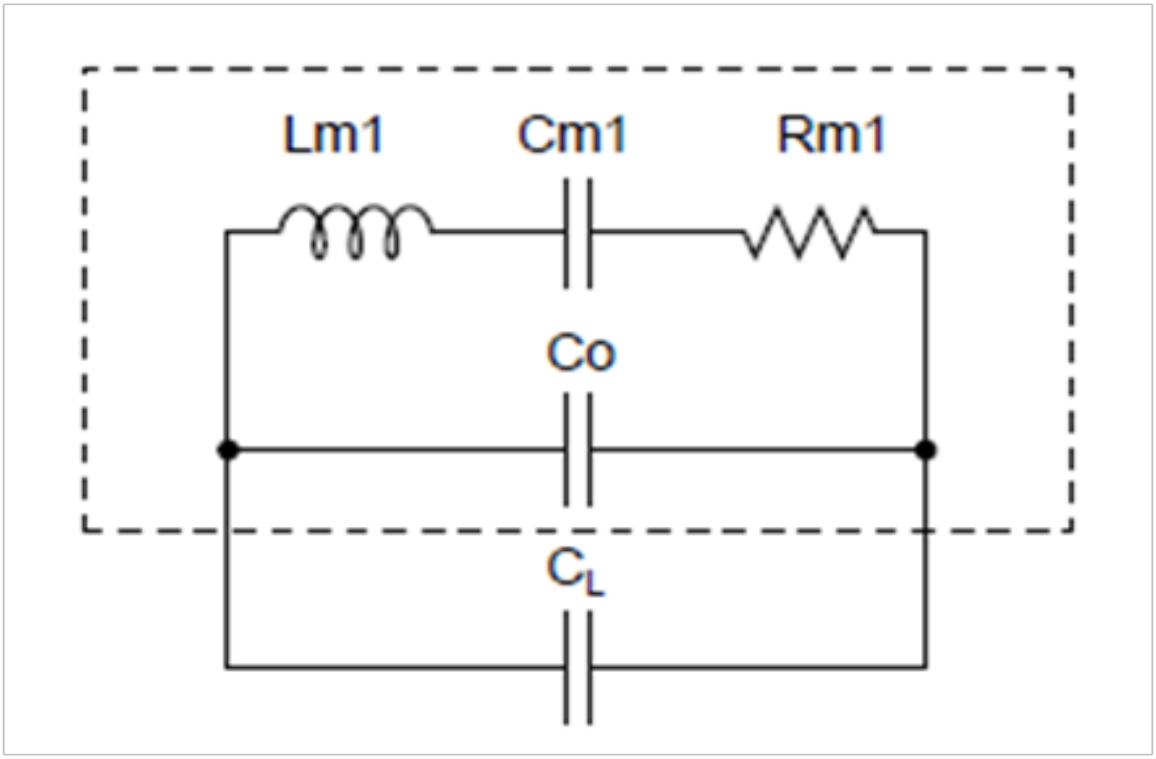


Figure 8. Crystal electrical block diagram

4.2.2 32 kHz oscillator electrical specifications

Table 30. 32 kHz oscillator electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
f_{osc_32k}	Crystal frequency	—	32.768	—	kHz	—
Tol	Frequency tolerance	—	±100	—	ppm	—
Jit_{osc}	Jitter					
	Period jitter (RMS)	—	10	—	ns	—
	Accumulated jitter over 1 ms (RMS)	—	50	—		
ESR	Crystal equivalent series resistance	—	—	80	kΩ	[1]
C_{para}	Parasitic capacitance of EXTAL32 and XTAL32	—	1	2.5	pF	—
t_{start}	Crystal start-up time	—	1000	2000	ms	[2][3]
I_{OSC_32k}	Current consumption					
	OFF mode	—	0.5	—	nA	[4]
	ON mode	—	110	—		
V_{pp}	Peak-to-peak amplitude of oscillation	—	0.2	—	V	[5]

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Table 30. 32 kHz oscillator electrical specifications...*continued*

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$f_{ec_extal32}$	Externally provided input clock frequency	—	32.768	—	kHz	[6]
$v_{ec_extal32}$	Externally provided input clock amplitude	—	VDD_SYS	—	mV	[6], [7]
$C_{extal/xtal}$	EXTAL, XTAL Load Capacitance	0	—	30	pF	[8]

[1] Maximum value is 80 kΩ for parasitic capacitances higher than 1 pF, and 150 kΩ for parasitic capacitances around 1 pF.
[2] Proper PC board layout procedures must be followed to achieve specifications.
[3] For some crystals at cold it can take up to 8000ms.
[4] Crystal ESR=30K, Cload=6 pF Vdd_sys=1.8V
[5] When a crystal is being used with the 32 kHz oscillator, the EXTAL32 and XTAL32 pins should only be connected to required oscillator components and must not be connected to any other devices.
[6] This specification is for an externally supplied clock driven to EXTAL32 and does not apply to any other clock input. The oscillator remains enabled and XTAL32 must be left unconnected.
[7] The parameter specified is a peak-to-peak value and V_{IH} and V_{IL} specifications do not apply. The voltage of the applied clock must be within the range of V_{SS} to $V_{DD_IO_D}$.
[8] With 2 pF steps.

Table 31. 32 kHz oscillation gain setting

Coarse_Amp_Gain (ESR Range)	Max ESR (kΩ)	Max Cx (pF) [1]	Notes
00 (default)	50	14	—
01	70	22	—
10	80	22	—
11	80	22	For higher negative resistance margin

[1] Cx is the sum of cap connected to EXTAL or XTAL, including internal load capacitors, pad capacitance and PCB. Cload will be approx Cx/2.

Note: *It is recommended that the oscillator margin be measured on the actual application PCB with the target crystal.*

4.2.3 Free-running oscillator FRO-192M specifications

Table 32. FRO-192M specifications

Symbol	Characteristic	Min.	Typ.	Max.	Unit	Notes
$f_{fro192m}$	FRO-192M frequency (nominal)	96/192			MHz	—
$\Delta f_{fro192m}$	Frequency deviation (–40 °C – 125 °C)					
	Open loop	—	—	±3	%	—
	Closed loop (using accurate clock source as reference)	—	—	±0.25		
$t_{startup}$	Start-up time					
	Oscillation time with initial accuracy of ±20 % to ±2 % of enable signal assertion	—	2	—	µs	—
	Oscillation time within ±2 % from enable signal assertion	—	10	—		

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Table 32. FRO-192M specifications...*continued*

Symbol	Characteristic	Min.	Typ.	Max.	Unit	Notes
f_{os}	Frequency overshoot during startup	—	—	2	%	—
jit_{per}						
	Period jitter RMS [1]	—	50	—	ps	—
	Accumulated jitter over 1 µs	—	375	—		
jit_{cyc}	Cycle to Cycle jitter RMS	—	60	—	ps	—
$I_{fro192m}$	Current consumption	—	40	100	µA	—

[1] Reference clock = 192 MHz.

4.2.4 Free-running oscillator FRO-6M specifications

Table 33. FRO-6M specifications

Symbol	Characteristic	Min.	Typ.	Max.	Unit	Notes
f_{fro6m}	FRO-6M frequency (nominal)	—	6	—	MHz	—
Δf_{fro6m}	Frequency deviation					
	open loop	—	—	±3	%	—
	closed loop (using accurate clock source as reference)	—	—	±0.6		
$t_{startup}$	Start-up time					
	Oscillation time with initial accuracy of -20 % to +2 % of enable signal assertion	—	5	—	µs	—
	Oscillation time within ± 2 % from enable signal assertion	—	10	—		
f_{os}	Frequency overshoot during startup	—	10	—	%	—
I_{fro6m}	Current consumption	—	—	4	µA	—

4.2.5 Free-running oscillator FRO-32K specifications

Table 34. FRO-32K specifications

Symbol	Characteristic	Min.	Typ.	Max.	Unit	Notes
f_{fro32k}	FRO-32K frequency (nominal)	—	32.768	—	kHz	—
Δf_{fro32k}	Frequency deviation • open loop	—	—	±2	%	—
$TRIM_{step}$	Trimming step	—	0.03	—	%	—
$t_{startup}$	Start-up time	—	—	120	µs	—
f_{os}	Frequency overshoot during startup • Trimmed	—	10	—	%	—
I_{fro32k}	Current consumption	—	350	—	nA	—

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4.2.6 Free-running oscillator FRO-16K specifications

Table 35. FRO-16K specifications

Symbol	Characteristic	Min.	Typ.	Max.	Unit	Notes
V_{BAT}	Supply voltage operating range	1.9	2.7	3.6	V	[1]
Temp	Temperature range	–40	25	125	°C	—
f_{fro16K}	FRO-16K frequency (nominal)	—	16.384	—	kHz	—
Δf_{fro16K}	Frequency deviation • Over –40 °C~125 °C temperature range	—	—	±6	%	—
TRIMstep	Frequency trimming step	—	1.5	—	%	—
I_{fro16k}	Current consumption	—	50	—	nA	[2]
I_{por}	Current consumption	—	26	—	nA	—

[1] FRO-16K is in Power Switch block, which is powered by min 1.9 V VDD_SWITCH
[2] The Typical value (70 nA) of current consumption includes 20 nA POR current consumption in stable running period.

4.3 Memories and memory interfaces

4.3.1 Flash electrical specifications

This section describes the electrical characteristics of the flash memory module.

4.3.1.1 Flash read wait state control specifications

FCTRL[RWSC] defines the number of read wait-states in the flash module for FMC read access to the flash array during full power and low-power modes. The following requirements must be met.

Table 36. Recommend RWSC settings on MCXW71 (for MCU flash and Radio Flash)

Mode	Typical Frequency (MHz)	FCTRL[RWSC]
SD – 1.1 V	96	0010b
SD – 1.1 V	64	0001b
SD – 1.1 V	48	0001b
MD – 1.0 V	48	0001b
MD – 1.0 V	32	0000b

4.3.1.2 Flash timing specifications

The following command times assume a flash bus clock frequency of 24 MHz.This clock come from SLOW_CLK. Command times will be increased by up to 10 µs at 24 MHz if the module is exiting sleep mode when the command is launched. The time to abort a command is not included in the following table.

Table 37. Flash command time specifications

Symbol	Description	Typ.	Max.	Unit	Notes
$t_{rd1all1024k}$	Read 1s All execution time (1024 KB)	—	6200	µs	—
$t_{rd1blk1024k}$	Read 1s Block execution time (1024 KB)	—	6000	µs	—

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Table 37. Flash command time specifications...*continued*

Symbol	Description	Typ.	Max.	Unit	Notes
t_{rd1scr}	Read 1s Sector execution time	—	50	µs	[1]
t_{rd1pg}	Read 1s Page execution time	—	4.4	µs	[1]
$t_{rd1pglv}$	Read 1s Page at low voltage execution time	—	5.8	µs	[1]
$t_{rd1phrlv}$	Read 1s Phrase at low voltage execution time	—	4.8	µs	[1]
$t_{rd1ipglv}$	Read 1s IFR Page at low voltage execution time	—	5.8	µs	[1]
$t_{rd1iphrlv}$	Read 1s IFR Phrase at low voltage execution time	—	4.8	µs	[1]
t_{rd1phr}	Read 1s Phrase execution time	—	3.8	µs	[1]
$t_{rdmisr8k}$	Read into MISR (8 KB)	—	50	µs	[1]
$t_{rdmisr1024k}$	Read into MISR (1024 KB)	—	6000	µs	[1]
$t_{rd1iscr}$	Read 1s IFR Sector execution time	—	50	µs	[1]
t_{rd1ipg}	Read 1s IFR Page execution time	—	4.4	µs	[1]
$t_{rd1iphr}$	Read 1s IFR Phrase execution time	—	3.8	µs	[1]
$t_{rdimisr8k}$	Read IFR into MISR (8 KB)	—	50	µs	[1]
$t_{rdimisr32k}$	Read IFR into MISR (32 KB)	—	190	µs	[1]
t_{pgmpg}	Program Page execution time	450	1000	µs	[2]
t_{pgmphr}	Program Phrase execution time	135	375	µs	[2]
$t_{ersall1024k}$	Erase All execution time (1024 KB)	—	2800	ms	—
$t_{masers1024k}$	Mass Erase execution time (1024 KB)	—	2800	ms	—
t_{ersscr}	Erase Sector execution time	2	22	ms	[2]

[1] Time to abort the command may significantly impact the time to execute the command.
[2] Measured from the time PERDY is cleared.

4.3.1.3 Flash high voltage current behavior

Table 38. Flash high voltage current behavior

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$I_{DD_IO_PGM}$	Average current adder to VDD_IO_x during flash programming operation	—	—	6	mA	[1]
$I_{DD_IO_ERS}$	Average current adder to VDD_IO_x during flash erase operation	—	—	4	mA	[1]

[1] See the Power Management chapter in the reference manual for the specific VDD_IO_x voltage supply powering the flash array.

4.3.1.4 Flash reliability specifications

Table 39. Flash reliability specifications

Symbol	Description	Min.	Typ.[1]	Max.	Unit	Notes
Program Flash						

Table continues on the next page...

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Table 39. Flash reliability specifications...*continued*

Symbol	Description	Min.	Typ.[1]	Max.	Unit	Notes
$t_{nvmretp10k}$	Data retention after up to 10 K cycles	10	50	—	years	—
$N_{nvmcycscr}$	Sector cycling endurance	10 K	500 K	—	cycles	[2]
$t_{nvmretp1k}$	Data retention after up to 1 K cycles	20	100	—	years	—
$t_{nvmretp100k}$	Data retention after up to 100 K cycles	5	50	—	years	—
$N_{nvmcyc256k}$	Sector cycling endurance for 256 KB per array block	100 K	500 K	—	cycles	[3]

[1] Typical data retention values are based on measured response accelerated at high temperature and derated to a constant 25 °C use profile.
[2] Sector cycling endurance represents the number of Program/Erase cycles on a single sector at -40 °C ≤ T_j ≤ 125 °C.
[3] For devices with a single flash block, sectors must be located within the last 256 KB of the flash main memory. For devices with two flash blocks, sectors must be located within the last 256 KB of each flash main memory.

4.4 Radio modules

4.4.1 2.4 GHz radio transceiver electrical specification

Table 40. 2.4 GHz radio transceiver specifications

Symbol	Characteristic	Min.	Typ.	Max.	Unit	Notes
VDD_RF	RF supply voltage	1.175	1.2	3.6	V	—
VPA_2P4GHZ	Supply voltage for 2.4 GHz radio power amplifier	0.9	—	2.4	V	[1], [2]
f_{in}	Input RF frequency	2.360	—	2.4835	GHz	—
f_c	Output RF frequency	2.360	—	2.4835	GHz	—
P_{max}	RF input power	—	—	10	dBm	—
f_{ref}	Crystal reference oscillator frequency	—	32	—	MHz	—
f_{tol}	Frequency tolerance	—	±50	—	ppm	—
t_{rx_tx}	Rx - Tx turnaround time	—	150	—	µs	[3]

[1] Voltage required at this rail depends on the desired output power. See Transmit and PLL feature summary for the required voltages.
[2] VPA_2P4GHZ is internally connected to the VDD_RF pin. When not powered externally, VPA_2P4GHZ = VDD_RF - 0.275 V. An internal regulator prevents VPA_2P4GHZ from going above 2.4 V when powered through the VDD_RF pin.
[3] Bluetooth LE. Other modes have different requirements

4.4.2 Receiver feature summary

Table 41. Top-level receiver specifications (T_A = 25 °C, nominal process unless otherwise noted)

Characteristic[1]	Symbol	Min.	Typ.	Max.	Unit
Receiver active power consumption					
Supply current Rx On with DC-DC converter enable (Buck; VDD_DCDC =3.3 V, VDD_RF=VDD_LDO_CORE = 1.25 V) [2]	I_{Rxon}	—	4.68	—	mA

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Table 41. Top-level receiver specifications (T_A = 25 °C, nominal process unless otherwise noted)*...continued*

Characteristic[1]	Symbol	Min.	Typ.	Max.	Unit
Supply current Rx On with DC-DC converter disabled (Bypass, VDD_RF = VDD_LDO_CORE = 3.3. V) [2]	I_{Rxon}	—	10.01	—	mA
Supply current Rx On with DC-DC converter disabled (Buck, VDD_DCDC = 3.3 V, VDD_RF = VDD_LDO_CORE = 1.25 V) for IEEE802.15.4[2]	$I_{Rxon15.4}$	—	3.69	—	mA
Supply current Rx On with DC-DC converter disabled (Bypass, VDD_RF = VDD_LDO_CORE = 3.3. V) [2]	$I_{Rxon15.4}$	—	7.9	—	mA
Receiver general specifications					
Input RF Frequency	f_{in}	2.360	—	2.4835	GHz
GFSK Rx Sensitivity(250 kbps GFSK-BT = 0.5, h = 0.5)[3][4]	$SENS_{GFSK}$	—	–103	—	dBm
Max RX RF Input Signal Level	RF_{inMax}	—	—	10	dBm
Noise Figure for maximum gain mode @ typical sensitivity[5]	NF_{HG}	—	6.5	—	dB
Receiver Signal Strength Indicator Range[6]	$RSSI_{Range}$	-100	—	0[7]	dBm
Receiver Signal Strength Indicator Resolution	$RSSI_{Res}$	—	1	—	dB
Typical RSSI variation over frequency	RSSIVarTypFreq	–2	—	2	dB
Typical RSSI variation over temperature	RSSIVarTypTemp	–2	—	2	dB
Narrowband RSSI accuracy[8]	$RSSI_{Acc}$	–3	—	3	dB
Spurious Emission < 1.6 MHz offset (Measured with 100 kHz resolution and average detector. Device transmit on RF channel with center frequency fc and spurious power measured in 1 MHz at RF frequency f), where |f-fc| < 1.6 MHz	SE,1.6MHz	—	–54	—	dBc
Spurious Emission > 2.5 MHz offset (Measured with 100 kHz resolution and average detector. Device transmit on RF channel with center frequency fc and spurious power measured in 1 MHz at RF frequency f), where |f-fc| > 2.5 MHz[9]	SE,2.5MHz	—	–70	—	dBc
Bluetooth LE coded 125 kbps (Long Range, 8x Spreading)					
Bluetooth LE LR 125 kbps Sensitivity[10],[3][4]	$SENS_{BLELR125}$	—	–106	—	dBm
Bluetooth LE LR 125 kbps Co-channel Interference (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz).	$COSEL_{BLELR125}$	—	–2	—	dB
Adjacent/Alternate Channel Performance[11]					

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Table 41. Top-level receiver specifications (T_A = 25 °C, nominal process unless otherwise noted)*...continued*

Characteristic[1]	Symbol	Min.	Typ.	Max.	Unit
Bluetooth LE LR 125 kbps Adjacent ±1 MHz Interference offset (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz.)	$SEL_{BLELR125,\ 1\ MHz}$	—	8	—	dB
Bluetooth LE LR 125 kbps Adjacent ± 2 MHz Interference offset (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz.)	$SEL_{BLELR125,\ 2\ MHz}$	—	50/35	—	dB
Bluetooth LE LR 125 kbps Alternate ±3 MHz Interference offset (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz.)	$SEL_{BLELR125,\ 3\ MHz}$	—	55/45	—	dB
Bluetooth LE LR 125 kbps Alternate ≥ ±4 MHz Interference offset (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz.)[4]	$SEL_{BLELR125,\ 4+\ MHz}$	—	55	—	dB
Bluetooth LE coded 500 kbps (Long Range, 2x Spreading)					
Bluetooth LE LR 500 kbps Sensitivity[10],[3][4]	$SENS_{BLELR500}$	—	–102	—	dBm
Bluetooth LE LR 500 kbps Co-channel Interference (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz).	$COSEL_{BLELR500}$	—	–3	—	dB
Adjacent/Alternate Channel Performance[11]					
Bluetooth LE LR 500 kbps Adjacent ±1 MHz Interference offset (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz.)	$SEL_{BLELR500,\ 1\ MHz}$	—	8	—	dB
Bluetooth LE LR 500 kbps Adjacent ±2 MHz Interference offset (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz.)	$SEL_{BLELR500,\ 2\ MHz}$	—	50/35	—	dB
Bluetooth LE LR 500 kbps Alternate ±3 MHz Interference offset (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz.)	$SEL_{BLELR500,\ 3\ MHz}$	—	55/45	—	dB
Bluetooth LE LR 500 kbps Alternate ≥ ±4 MHz Interference offset (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz.)[4]	$SEL_{BLELR500,\ 4+\ MHz}$	—	52	—	dB
Bluetooth LE un-coded 1 Mbps					
Bluetooth LE 1 Mbps Sensitivity[10],[3][4]	$SENS_{BLE1M}$	—	–97.5	—	dBm
Bluetooth LE 1 Mbps Co-channel Interference (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz).	$COSEL_{BLE1M}$	—	–6	—	dB
Adjacent/Alternate channel selectivity performance[11]					
Bluetooth LE 1 Mbps Selectivity ±1 MHz Interference offset (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz.)	$SEL_{BLE1M,\ 1\ MHz}$	—	0	—	dB

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Table 41. Top-level receiver specifications (T_A = 25 °C, nominal process unless otherwise noted)*...continued*

Characteristic[1]	Symbol	Min.	Typ.	Max.	Unit
Bluetooth LE 1 Mbps Adjacent ±2 MHz Interference offset (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz.)	$SEL_{BLE1M, 2 MHz}$	—	45/35	—	dB
Bluetooth LE 1 Mbps Selectivity ±3 MHz Interference offset (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz.)	$SEL_{BLE1M, 3 MHz}$	—	53/45	—	dB
Bluetooth LE 1 Mbps Alternate ≥ ±4 MHz Interference offset (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz.)[4]	$SEL_{BLE1M, 4+ MHz}$	—	52	—	dB
Intermodulation performance					
Bluetooth LE 1 Mbps Intermodulation with continuous wave interferer at ±3 MHz and modulated interferer is at ±6 MHz (or ±8 MHz) – Wanted signal at –67 dBm, BER < 0.1 %.	$IM3\text{-}6_{BLE1M}$ $IM4\text{-}8_{BLE1M}$	—	–27	—	dBm
Bluetooth LE 1 Mbps Intermodulation with continuous wave interferer at ±5 MHz and modulated interferer is at ±10 MHz – Wanted signal at –67 dBm, BER < 0.1 %.	$IM5\text{-}10_{BLE1M}$	—	–28	—	dBm
Blocking performance					
Bluetooth LE 1 Mbps Out of band blocking from 30 MHz to 1000 MHz and 4000 MHz to 5000 MHz (Wanted signal at –67 dBm, BER < 0.1 %. Interferer continuous wave signal.)[12]	OOB30-100M,4000-5000M, BLE1M	–2	—	—	dBm
Bluetooth LE 1 Mbps Out of band blocking from 1000 MHz to 2000 MHz and 3000 MHz to 4000 MHz (Wanted signal at –67 dBm, BER < 0.1 %. Interferer continuous wave signal.)	OOB1000-2000M,3000-4000M, BLE1M	–10	—	—	dBm
Bluetooth LE 1 Mbps Out of band blocking from 2001 MHz to 2339 MHz and 2484 MHz to 2999 MHz (Wanted signal at –67 dBm, BER < 0.1 %. Interferer continuous wave signal.)[13]	OOB2001-2339M,2484-2999M, BLE1M	–10	—	—	dBm
Bluetooth LE 1 Mbps Out of band blocking from 5000 MHz to 12750 MHz (Wanted signal at –67 dBm, BER < 0. 1 %. Interferer continuous wave signal.)[13]	OOB5000-12750M, BLE1M	2	10	—	dBm
Bluetooth LE un-coded 2 Mbps (High Speed)					
Bluetooth LE 2 Mbps Sensitivity[10],[3][4]	$SENS_{BLE2M}$	—	–95	—	dBm
Bluetooth LE 2 Mbps Co-channel Interference (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz).	$COSEL_{BLE2M}$	—	–7	—	dB
Adjacent/Alternate channel performance[11]					

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Table 41. Top-level receiver specifications (T_A = 25 °C, nominal process unless otherwise noted)*...continued*

Characteristic[1]	Symbol	Min.	Typ.	Max.	Unit
Bluetooth LE 2 Mbps Adjacent ±2 MHz Interference offset (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz.)	$SEL_{BLE2M, 2\ MHz}$	—	5	—	dB
Bluetooth LE 2 Mbps Alternate ±4 MHz Interference offset (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 2 MHz.)	$SEL_{BLE2M, 4\ MHz}$	—	42/30	—	dB
Bluetooth LE 2 Mbps Selectivity ±6 MHz Interference offset (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 4 MHz.)	$SEL_{BLE2M, 6\ MHz}$	—	50	—	dB
Bluetooth LE 2 Mbps Selectivity ≥±8 MHz Interference offset (Wanted signal at –67 dBm, BER < 0.1 %. Measurement resolution 1 MHz.)[4]	$SEL_{BLE2M, 8+\ MHz}$	—	52	—	dB
Intermodulation performance					
Bluetooth LE 2 Mbps Intermodulation with continuous wave interferer at ±6 MHz and modulated interferer is at ±12 MHz (or ±16 MHz) -- Wanted signal at –67 dBm, BER < 0.1 %.	$IM3\text{-}6_{BLE2M}$	—	–28	—	dBm
Bluetooth LE 2 Mbps Intermodulation with continuous wave interferer at ±8 MHz (±10 MHz) and modulated interferer is at ±16 MHz (or ±20 MHz) – Wanted signal at –67 dBm, BER < 0.1 %.)	$IM4\text{-}8_{BLE2M}$ $IM4\text{-}10_{BLE2M}$	—	–32	—	dBm
Blocking performance					
Bluetooth LE 2 Mbps Out of band blocking from 30 MHz to 1000 MHz and 4000 MHz to 5000 MHz (Wanted signal at –67 dBm, BER < 0.1 %. Interferer continuous wave signal.)[12]	OOB30-100M,4000-5000M, BLE2M	–4	—	—	dBm
Bluetooth LE 2 Mbps Out of band blocking from 1000 MHz to 2000 MHz and 3000 MHz to 4000 MHz (Wanted signal at –67 dBm, BER < 0.1 %. Interferer continuous wave signal.)	OOB1000-2000M,3000-4000M, BLE2M	–10	—	—	dBm
Bluetooth LE 2 Mbps Out of band blocking from 2001 MHz to 2339 MHz and 2484 MHz to 2999 MHz (Wanted signal at –67 dBm, BER < 0.1 %. Interferer continuous wave signal.)[13]	OOB2001-2339M,2484-2999M, BLE2M	–10	—	—	dBm
Bluetooth LE 2 Mbps Out of band blocking from 5000 MHz to 12750 MHz (Wanted signal at –67 dBm, BER < 0.1 %. Interferer continuous wave signal.)[13]	OOB5000-12750M, BLE2M	2	10	—	dBm
IEEE 802.15.4					
IEEE 802.15.4 1 % PER Sensitivity	SENS15.4	—	-103	—	dBm

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Table 41. Top-level receiver specifications (T_A = 25 °C, nominal process unless otherwise noted)*...continued*

Characteristic[1]	Symbol	Min.	Typ.	Max.	Unit
IEEE 802.15.4 Co-channel Interference (Wanted signal at 3 dBm above sensitivity, PER 1 %).	COSEL15.4	—	-4	—	dB
WIFI rejection. 1 % PER, with wanted signal IEEE802.15.4 –75 dBm 2470 MHz, WIFI signal IEEE 802.11n 2447 MHz (20 MHz mode). Frequency offset > 23 MHz	RejWIFI15.4	—	-46	—	dBc
Adjacent/Alternate channel performance[11]					
IEEE 802.15.4 Adjacent ±5 MHz interference offset (Wanted signal 3 dB over reference sensitivity level, PER <1 %)	SEL15.4, 5 MHz	—	35	—	dB
IEEE 802.15.4 Alternate ±10 MHz interference offset (Wanted signal 3 dB over reference sensitivity level, PER <1 %.)	SEL15.4, 10 MHz	—	45	—	dB
IEEE 802.15.4 Alternate ≥ ±15 MHz interference offset (Wanted signal 3 dB over reference sensitivity level, PER <1 %.)	SEL15.4, 15 MHz	—	52	—	dB
Blocking performance					
IEEE 802.15.4 out of band blocking for frequency offsets > 10 MHz and <= 80 MHz(Wanted signal 3 dB over reference sensitivity level, PER <1 %. Interferer continuous wave signal.)[14]	OOB10-80M, 15.4	—	–20	—	dBm
IEEE 802.15.4 out of band blocking from carrier frequencies in 1 GHz to 4 GHz range excluding frequency offsets < ±80 MHz (Wanted signal 3 dB over reference sensitivity level, PER <1 %. Interferer continuous wave signal.)	OOB1-4G, 15.4	—	–10	—	dBm
IEEE 802.15.4 out of band blocking frequency from fc < 1 GHz or 4 GHz < fc < 5 GHz or fc > 6 GHz (Wanted signal 3 dB over reference sensitivity level, PER <1 %. Interferer continuous wave signal..11	OOB1|4-5|6G, 15.4	—	-1	—	dBm
IEEE 802.15.4 out of band blocking frequency from 5 GHz < fc < 6 GHz (Wanted signal 3 dB over reference sensitivity level, PER <1%. Interferer continuous wave signal..11	OOB5-6G, 15.4	—	-17	—	dBm

[1] All the RX parameters are measured at the RF pins.
[2] Transceiver power consumption.
[3] Variation across temperature (-40 °C to 105 °C) is up to 3 dB.
[4] Exceptions allowed for multiple of XTAL frequency
[5] Receiver noise Figure is computed from RF pin to composite (I+jQ) ADC output
[6] Narrow-band RSSI mode.
[7] With RSSI_CTRL_0.RSSI_ADJ field calibrated to account for antenna to RF input losses.
[8] With one point calibration over frequency and temperature.
[9] Exceptions allowed for twice the reference clock frequency(fref) multiples.
[10] Measured at 0.1 % BER using 37 byte long packets in maximum gain mode and nominal conditions.
[11] Bluetooth LE adjacent and alternate selectivity performance is measured with modulated interference signals.
[12] Exceptions allowed for carrier frequency sub harmonics.
[13] Exceptions allowed for carrier frequency harmonics.
[14] Exception to the 10 MHz > freq offset ≤ 80 MHz out-of-band blocking limit allowed for frequency offsets of twice the reference frequency(fref)

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Table 42. Receiver specifications with generic FSK modulations

—				Adjacent/Alternate channel selectivity (dB)[1]					
Modulation type	Data rate (kb/s)	Channel BW (kHz)	Typical sensitivity (dBm)[2]	Desired signal level (dBm)	Interferer at ±1* channel BW offset	Interferer at ±2* channel BW offset	Interferer at ±3* channel BW offset	Interferer at ±4* channel BW offset	Co-channel
GFSK BT = 0.5, h = 0.5	2000	4000	-95	-67	5	45/35	52	55	7
	1000	2000	-98	-67	0	42/32	52/42	55	7
	500	1000	-101	-85	40	50/35	55	55	6
	250	500	-103	-85	38	48	52	55/35	6

[1] Selectivity measured with an unmodulated blocker.
[2] Variation across temperature (-40 °C to 105 °C) is up to 3 dB.

4.4.3 Transmit and PLL feature summary

- Supports constant envelope modulation of 2.4 GHz ISM frequency band.
- Fast PLL Lock time: < 25 µs
- Reference Frequency:
  - 32 MHz crystals supported for Bluetooth LE and Generic FSK modes

Table 43. Top-level transmitter specifications (T_A = 25 °C, nominal process unless otherwise noted)

Characteristic[1]	Symbol	Min.	Typ.	Max.	Unit
Transmitter active power specifications					
Supply current Tx On with P_{RF} = 0 dBm and DC-DC converter enabled (Buck; VDD_DCDC = 3.3 V, VDD_RF = VDD_LDO_CORE = 1.25 V) [2]	I_{TX0dBm}	—	4.60	—	mA
Supply current Tx On with P_{RF} = 0 dBm and DC-DC converter disabled (Bypass, VDD_RF = VDD_LDO_CORE = 3.3 V) [2]	$I_{TX0dBmb}$	—	9.83	—	mA
Supply current Tx On with P_{RF} = +4 dBm and DC-DC converter enabled (Buck; VDD_DCDC = 3.3 V, VDD_RF = VDD_LDO_CORE = 1.25 V) [2]	I_{TX4dBm}	—	7.63	—	mA
Supply current Tx On with P_{RF} = +4 dBm and DC-DC converter disabled (Bypass, VDD_RF = VDD_LDO_CORE = 3.3 V) [2]	I_{TX4dBm}	—	11.89	—	mA
Supply current Tx On with P_{RF} = +7 dBm and DC-DC converter enabled (Buck; VDD_DCDC = 3.3 V, VDD_RF = VDD_LDO_CORE = 1.8 V) [2]	I_{TX7dBm}	—	10.79	—	mA
Supply current Tx On with P_{RF} = +7 dBm and DC-DC converter disabled (Bypass, VDD_RF = VDD_LDO_CORE = 3.3 V, LDO_ANT ≥ 1.61 V)[2]	$I_{TX7dBmb}$	—	16.81	—	mA
Supply current Tx On with P_{RF} = +10 dBm and DC-DC converter enabled (Buck; VDD_DCDC = 3.3 V, VDD_RF = VDD_LDO_CORE = LDO_ANT = 2.4 V)[2]	$I_{TX10dBm}$	—	18.71	—	mA

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Table 43. Top-level transmitter specifications (T_A = 25 °C, nominal process unless otherwise noted)*...continued*

Characteristic[1]	Symbol	Min.	Typ.	Max.	Unit
Supply current Tx On with P_{RF} = +10 dBm and DC-DC converter disabled (Bypass, VDD_RF = VDD_LDO_CORE = 3.3 V, LDO_ANT ≥ 2.21 V)[2]	$I_{TX10dBmb}$	—	20.99	—	mA
Supply current Tx On in IEEE 802.15.4 with P_{RF} = 0 dBm and DC-DC converter enabled (Buck; VDD_DCDC = 3.3 V, VDD_RF = VDD_LDO_CORE = 1.25 V)[2],[3]	$I_{TX0dBm15.4}$	—	3.75	—	mA
Supply current Tx On in IEEE 802.15.4 with P_{RF} = 0 dBm and DC-DC converter disabled (Bypass, VDD_RF = VDD_LDO_CORE = 3.3 V)[2],[3]	$I_{TX0dBm15.4}$	—	8.02	—	mA
Supply current Tx On in IEEE 802.15.4 with P_{RF} = +10 dBm and DC-DC converter enabled (Buck; VDD_DCDC = 3.3 V, VDD_RF = VDD_LDO_CORE = 1.25 V)[2],[3]	$I_{TX0dBm15.4}$	—	17.10	—	mA
Supply current Tx On in IEEE 802.15.4 with P_{RF} = +10 dBm and DC-DC converter disabled (Bypass, VDD_RF = VDD_LDO_CORE = 3.3 V)[2],[3]	$I_{TX0dBm15.4}$	—	19.19	—	mA
Transmitter general specifications					
Output RF Frequency	f_{RFout}	2.360	—	2.4835	GHz
Maximum RF Output Power; 10 dBm configuration [4],[5]	$P_{RF,maxV}$	—	10	—	dBm
Minimum RF Output power [6],[5]	$P_{RF,minn}$	—	-30	—	dBm
RF Output power control range (nominal power supply)	P_{RFCR}	—	32	—	dB
Bluetooth LE Maximum Deviation of the Carrier Frequency[7]	$f_{cdev,BLE}$	—	±3	—	kHz
Bluetooth LE Frequency Hopping Support	BLEFhop	—	YES	—	—
2nd Harmonic of Transmit Carrier Frequency (P_{out} = $P_{RF,max}$)[8],[9]	TXH2	—	–53	—	dBm/MHz
3rd Harmonic of Transmit Carrier Frequency (P_{out} = $P_{RF,max}$)[9]	TXH3	—	–50	—	dBm/MHz
Bluetooth LE un-coded 1 Mbps/coded 125 kbps/coded 500 kbps					
Bluetooth LE 1 Mbps TX Output Spectrum 20 dB BW	$TXBW_{BLE1M}$	1.0	—	—	MHz
Bluetooth LE 1 Mbps average frequency deviation using a 00001111 modulation sequence	$\Delta f1_{avg,BLE1M}$	—	250	—	kHz
Bluetooth LE 1 Mbps average frequency deviation using a 01010101 modulation sequence	$\Delta f2_{avg,BLE1M}$	—	220	—	kHz
Bluetooth LE 1 Mbps RMS FSK Error	$FSK_{err,BLE1M}$	—	3%	—	—
Bluetooth LE 1 Mbps Adjacent Channel Transmit Power at 2 MHz offset[9]	$P_{RF2MHz,BLE1M}$	—	—	-55	dBc
Bluetooth LE 1 Mbps Adjacent Channel Transmit Power at ≥ 3 MHz offset[9]	$P_{RF3MHz,BLE1M}$	—	—	-59	dBc

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Table 43. Top-level transmitter specifications (T_A = 25 °C, nominal process unless otherwise noted)*...continued*

Characteristic[1]	Symbol	Min.	Typ.	Max.	Unit
Bluetooth LE un-coded 2 Mbps					
Bluetooth LE 2 Mbps TX Output Spectrum 20 dB BW	$TXBW_{BLE2M}$	2.0	—	—	MHz
Bluetooth LE 2 Mbps average frequency deviation using a 00001111 modulation sequence	$\Delta f1_{avg,BLE2M}$	—	500	—	kHz
Bluetooth LE 2 Mbps average frequency deviation using a 01010101 modulation sequence	$\Delta f2_{avg,BLE2M}$	—	440	—	kHz
Bluetooth LE 2 Mbps RMS FSK Error	$FSK_{err,BLE2M}$	—	4%	—	—
Bluetooth LE 2 Mbps Adjacent Channel Transmit Power at 4 MHz offset[9]	$P_{RF4MHz,BLE2M}$	—	—	-55	dBc
Bluetooth LE 2 Mbps Adjacent Channel Transmit Power at ≥ 6 MHz offset[9]	$P_{RF6MHz,BLE2M}$	—	—	-60	dBc
IEEE 802.15.4					
IEEE 802.15.4 Peak Frequency Deviation	$fdev_{15.4}$	—	±500	—	kHz
IEEE 802.15.4 Error Vector Magnitude[10][11]	$EVM_{15.4}$	—	5	8	%
IEEE 802.15.4 Offset Error Vector Magnitude[12][13]	$OEVM_{15.4}$	—	0.5	—	%
IEEE 802.15.4 TX spectrum level at 3.5 MHz offset[10],[14]	$TXPSD_{15.4}$	—	—	–36	dBc
Transmitter spurious emissions					
30 MHz to 1 GHz, Peak detector, RBW=100 kHz	PD30M-1G, 100kHz	—	—	–60	dBm
1 GHz to 26 GHz, Peak detector, RBW = 1 MHz, based on FCC 15.247 at +10 dBm	PD1-26G, 1M	—	—	–42	dBm
1 GHz to 2.36 GHz and 2.483 to 12.75 GHz, Peak detector, RBW = 1 MHz, based on ETSI EN 300 328 at +10 dBm	PD1-2.36G,2.483 -12.75G, 1M	—	—	–37	dBm
2.36 GHz to 2.4 GHz and 2.4 GHz to 2.483 GHz, Peak detector RBW 1 MHz, ETSI EN 300 328 at +10dBm	PD2.36-2.4G,2.4 G-2.483G, 1M	—	—	–42	dBm

[1] All the TX parameters are measured at test hardware SMA connector.
[2] Transceiver power consumption. NBU running at 16 MHz.
[3] To obtain current consumption at higher output power use the formula $I_{TXndBm15.4}=I_{TXndBm15.4}+(I_{TXndBm}-I_{TX0dBm})$ where n is the desired output power (+4 or +7)
[4] Measured at RF pins, with V_{PA_2P4GHz} ≥ 2.4 V.
[5] Variation across temperature (-40 °C to 105 °C) is up to 3 dB.
[6] Measured at the RF pins single supply configuration VDD_RF = VDD_LDO_CORE = 1.25V
[7] Maximum drift of carrier frequency of the PLL during a Bluetooth LE packet with a nominal 32 MHz reference crystal.
[8] Harmonic levels based on recommended 2 component match for TX output power ≤ 5 dBm. Transmit harmonic levels depend on the quality of matching components. Additional harmonic margin using a 3rd matching component (1x shunt capacitor) is possible.
[9] Measured at P_{out} > 5 dBm and recommended high-power TX match.
[10] Measured as per IEEE Standard 802.15.4
[11] Except for Channel 26 which has a specific configuration to keep a good trade-off between a passing FCC band edge test and an acceptable EVM value (and still under the IEEE 802.15.4 limit).
[12] Offset EVM is computed at one point per symbol, by combining the I value from the beginning of each symbol and the Q value from the middle of each symbol into a single complex value for EVM computations
[13] Except for Channel 26 which has a specific configuration to keep a good trade-off between a passing FCC band edge test and an acceptable EVM offset value.
[14] Measured at PRF, Max and recommended TX match.

Transmit PA driver output as a function of the TX-PA_POWER[5:0] field when measured at the IC pins is as follows:

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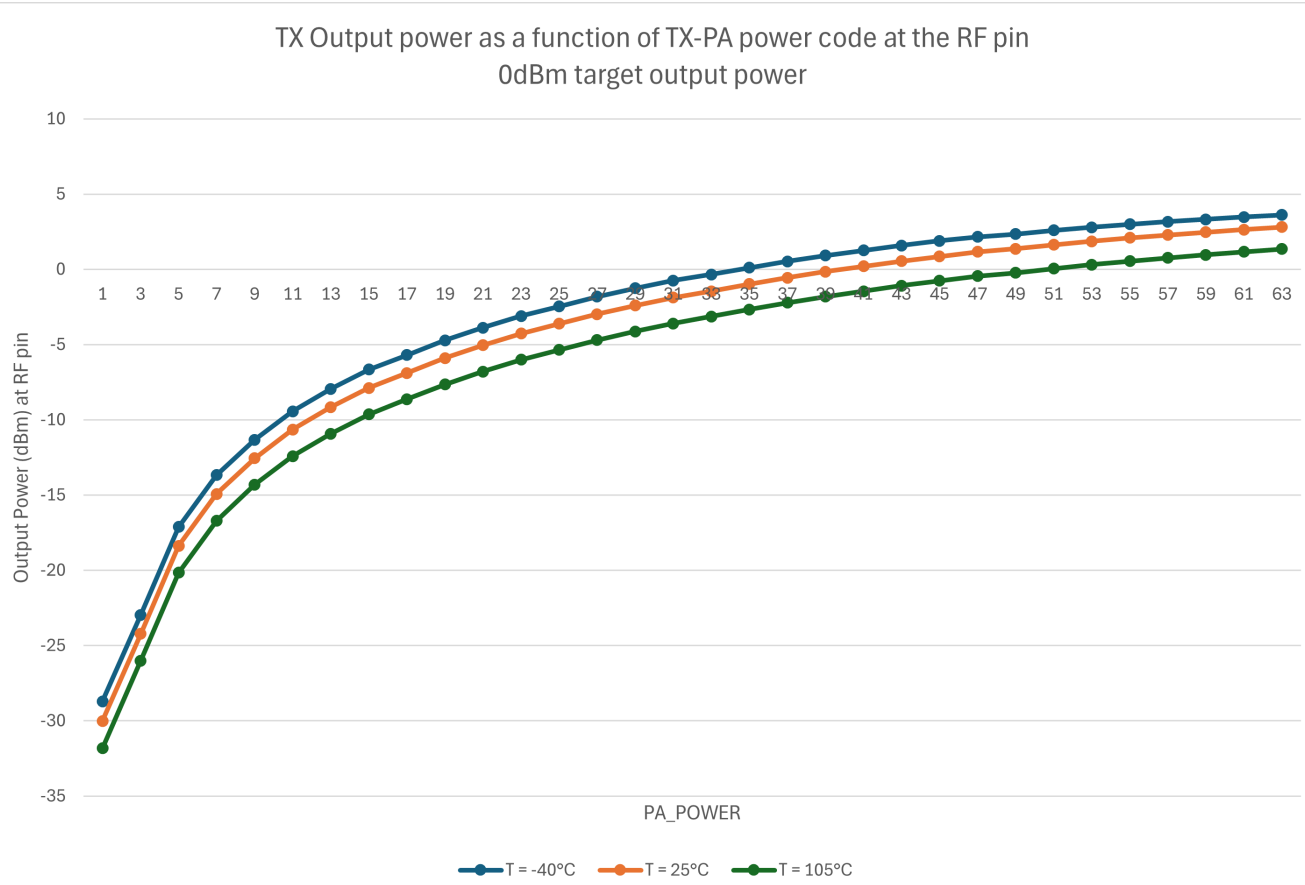


Figure 9. TX Pout (dBm) as function TX-PA power code at RF pins

Table 44. Transmit output power as a function of PA_POWER VPA_2P4GHZ = 1 V / 0 dBm output power target

TX Pout (dBm)				
PA_POWER	LDO ANT	T = –40 °C	T = 25 °C	T = 105 °C
1	3	-28.71	-30	-31.83
3	3	-22.96	-24.22	-26
5	3	-17.11	-18.37	-20.15
7	3	-13.67	-14.92	-16.71
9	3	-11.32	-12.55	-14.31
11	3	-9.43	-10.65	-12.42
13	3	-7.94	-9.16	-10.92
15	3	-6.65	-7.88	-9.64
17	3	-5.7	-6.89	-8.63
19	3	-4.72	-5.9	-7.65
21	3	-3.87	-5.04	-6.79

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Table 44. Transmit output power as a function of PA_POWER VPA_2P4GHZ = 1 V / 0 dBm output power target...*continued*

TX Pout (dBm)				
PA_POWER	LDO ANT	T = –40 °C	T = 25 °C	T = 105 °C
23	3	-3.1	-4.27	-6
25	3	-2.46	-3.62	-5.35
27	3	-1.82	-2.98	-4.7
29	3	-1.26	-2.41	-4.13
31	3	-0.74	-1.88	-3.59
33	3	-0.34	-1.45	-3.14
35	3	0.11	-0.98	-2.66
37	3	0.53	-0.55	-2.22
39	3	0.92	-0.15	-1.81
41	3	1.26	0.2	-1.45
43	3	1.59	0.55	-1.09
45	3	1.89	0.86	-0.76
47	3	2.16	1.16	-0.45
49	3	2.35	1.37	-0.23
51	3	2.59	1.63	0.05
53	3	2.8	1.87	0.31
55	3	3	2.09	0.55
57	3	3.16	2.28	0.76
59	3	3.33	2.47	0.97
61	3	3.48	2.64	1.16
63	3	3.62	2.81	1.35

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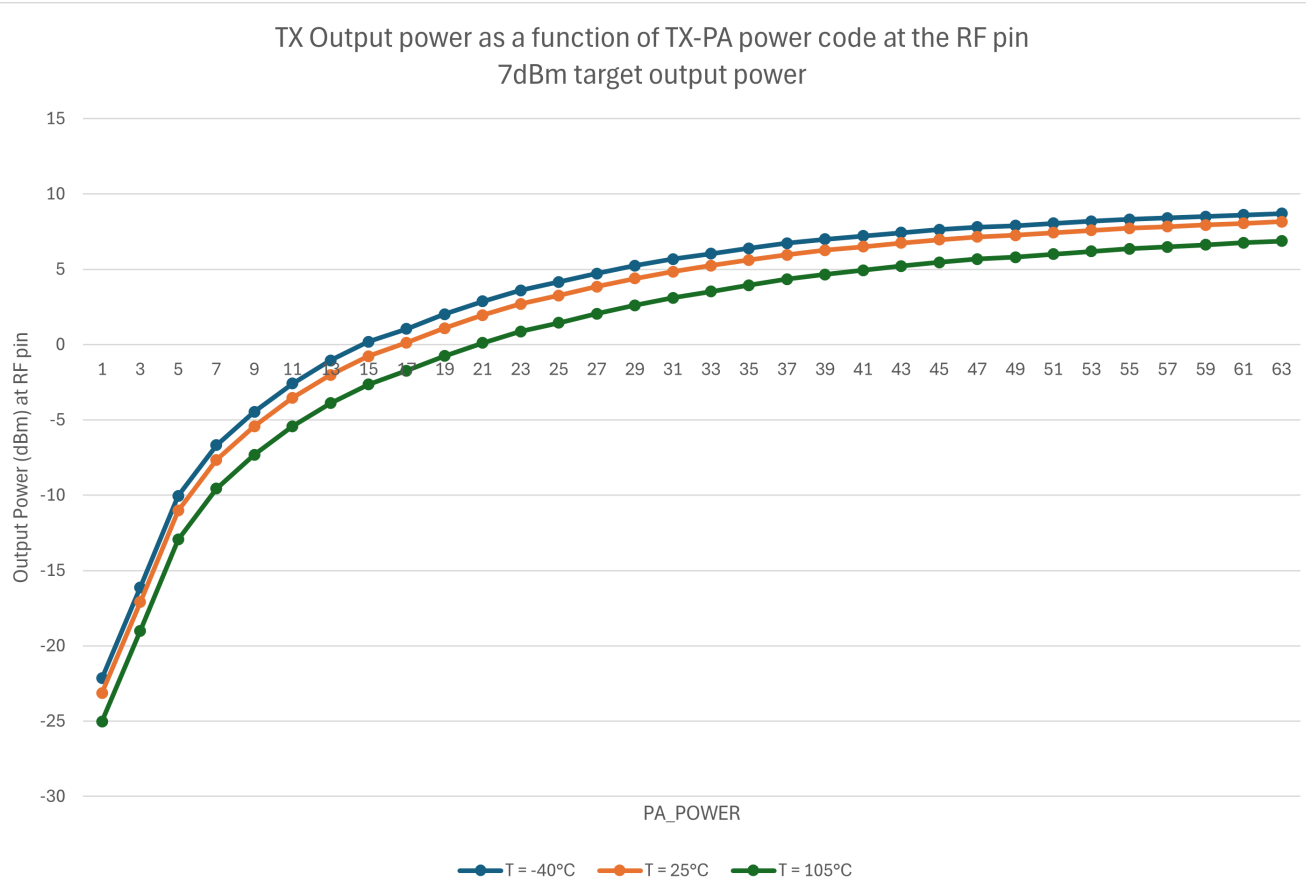


Figure 10. TX Pout (dBm) as function TX-PA Power Code at 7 dBm

Table 45. Transmit output power as a function of PA_POWER VPA_2P4GHZ = 1.6 V / 7 dBm output power target

TX Pout (dBm)				
PA_POWER	LDO_ANT	T = –40 °C	T = 25 °C	T =105 °C
1	9	-22.14	-23.12	-25.02
3	9	-16.11	-17.1	-19
5	9	-10.04	-11.02	-12.94
7	9	-6.67	-7.65	-9.56
9	9	-4.45	-5.42	-7.31
11	9	-2.58	-3.53	-5.42
13	9	-1.05	-2.01	-3.89
15	9	0.19	-0.76	-2.64
17	9	1.05	0.13	-1.73
19	9	2.02	1.1	-0.75
21	9	2.88	1.96	0.12

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Table 45. Transmit output power as a function of PA_POWER VPA_2P4GHZ = 1.6 V / 7 dBm output power target...*continued*

TX Pout (dBm)				
PA_POWER	LDO_ANT	T =–40 °C	T = 25 °C	T =105 °C
23	9	3.61	2.7	0.87
25	9	4.16	3.26	1.45
27	9	4.73	3.86	2.06
29	9	5.24	4.39	2.61
31	9	5.68	4.85	3.1
33	9	6.04	5.24	3.53
35	9	6.4	5.62	3.95
37	9	6.73	5.97	4.34
39	9	7	6.27	4.66
41	9	7.22	6.51	4.94
43	9	7.44	6.75	5.21
45	9	7.64	6.97	5.46
47	9	7.81	7.16	5.68
49	9	7.9	7.27	5.81
51	9	8.05	7.44	6.01
53	9	8.19	7.59	6.2
55	9	8.32	7.73	6.36
57	9	8.41	7.84	6.48
59	9	8.51	7.95	6.63
61	9	8.61	8.06	6.76
63	9	8.7	8.16	6.87

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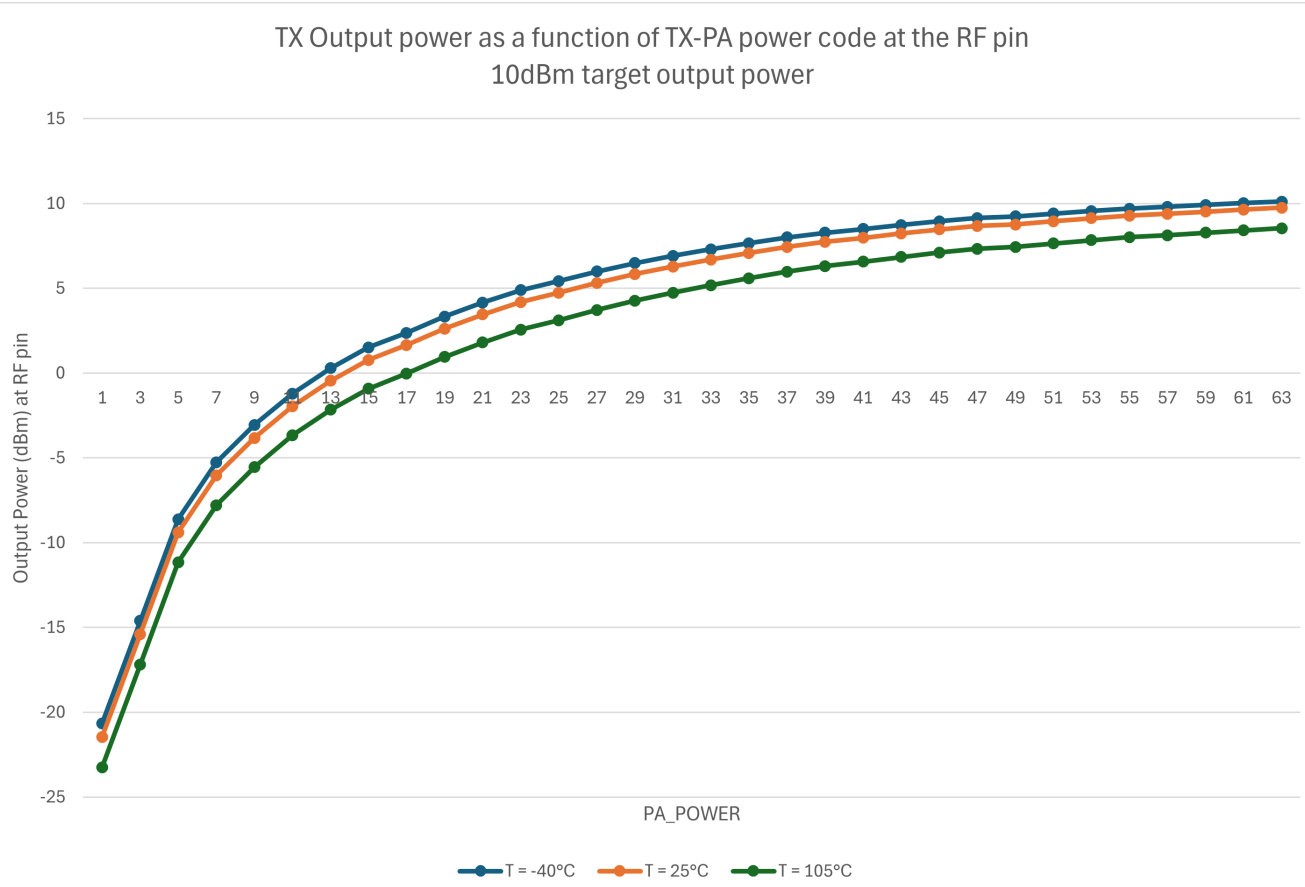


Figure 11. TX Pout (dBm) as function TX-PA Power Code at 10 dBm

Table 46. Transmit output power as a function of PA_POWER VPA_2P4GHZ = 2.2 V / 10 dBm output

TX Pout (dBm)				
PA_POWER	LDO_ANT	T = -40 °C	T = 25 °C	T = 105 °C
1	15	-20.67	-21.46	-23.26
3	15	-14.61	-15.39	-17.19
5	15	-8.61	-9.39	-11.16
7	15	-5.26	-6.03	-7.79
9	15	-3.06	-3.82	-5.55
11	15	-1.2	-1.95	-3.67
13	15	0.29	-0.45	-2.16
15	15	1.52	0.78	-0.92
17	15	2.37	1.65	-0.03
19	15	3.33	2.61	0.95
21	15	4.17	3.46	1.81

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Table 46. Transmit output power as a function of PA_POWER VPA_2P4GHZ = 2.2 V / 10 dBm output...*continued*

TX Pout (dBm)				
PA_POWER	LDO_ANT	T = -40 °C	T = 25 °C	T = 105 °C
23	15	4.89	4.19	2.56
25	15	5.42	4.74	3.12
27	15	5.99	5.32	3.73
29	15	6.49	5.84	4.27
31	15	6.92	6.29	4.74
33	15	7.3	6.7	5.18
35	15	7.66	7.08	5.6
37	15	8	7.43	5.98
39	15	8.28	7.74	6.31
41	15	8.5	7.98	6.57
43	15	8.74	8.23	6.85
45	15	8.96	8.47	7.1
47	15	9.15	8.67	7.33
49	15	9.24	8.77	7.44
51	15	9.41	8.96	7.65
53	15	9.56	9.13	7.84
55	15	9.7	9.28	8.01
57	15	9.8	9.39	8.13
59	15	9.92	9.52	8.28
61	15	10.03	9.64	8.42
63	15	10.12	9.75	8.55

4.5 Analog

4.5.1 ADC electrical specifications

4.5.1.1 16-bit ADC operating conditions

Table 47. 16-bit ADC operating conditions

Symbol	Description	Min.	Typ.[1]	Max.	Unit	Notes
V_{DD_ANA}	Supply voltage	1.71	—	3.6	V	—
ΔV_{DD_ANA}	Supply voltage delta to V_{DD} ($V_{DD} - V_{DD_ANA}$)	–0.1	0	+0.1	mV	[2]
ΔV_{SS_ANA}	Ground voltage delta to V_{SS} ($V_{SS} - V_{SS_ANA}$)	–0.1	0	+0.1	mV	[2]

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Table 47. 16-bit ADC operating conditions...*continued*

Symbol	Description		Min.	Typ.[1]	Max.	Unit	Notes
V_{REFH}	ADC reference voltage high		0.99	V_{DD_ANA}	V_{DD_ANA}	V	—
V_{REFL}	ADC reference voltage low		V_{SS_ANA}	V_{SS_ANA}	V_{SS_ANA}	V	[3]
V_{ADIN}	Input voltage		V_{REFL}	—	V_{REFH}	V	[3], [4],[5]
f_{ADCK}	ADC input clock frequency						
	Low-power mode (PWRSEL=00)		6	—	20	MHz	—
	High-speed 16b mode (PWRSEL = 10)		6	—	48		
	High-speed 12b mode (PWRSEL = 10)		6	—	60		
C_{ADIN}	Input capacitance		—	3.7	4.63	pF	—
C_p	Parasitic Cap of pad /package		—	2	3	pF	—
R_{AS}	Analog source resistance (external)		—	—	5	kΩ	[6]
R_{ADIN}	High-speed dedicated input channel (CH0:3)	$V_{DD_ANA} \geq 1.71$ V	—	0.95	1.7	kΩ	[7],[8]
		$V_{DD_ANA} \geq 2.1$ V	—	0.95	1.6		
		$V_{DD_ANA} \geq 2.5$ V	—	0.95	1.4		
	Standard external input channel (Ch4:7)	$V_{DD_ANA} \geq 1.71$ V	—	1.35	3.25		
		$V_{DD_ANA} \geq 2.1$ V	—	1.35	2.15		
		$V_{DD_ANA} \geq 2.5$ V	—	1.35	1.75		
	Standard muxed input channel (Ch4:11)	$V_{DD_ANA} \geq 1.71$ V	—	1.65	7.25		
		$V_{DD_ANA} \geq 2.1$ V	—	1.65	3.05		
		$V_{DD_ANA} \geq 2.5$ V	—	1.65	2.35		

[1] Typical values assume V_{DD_ANA}= 3.0 V, Temp = 25 °C, f_{ADCK} = 24 MHz, unless otherwise stated. Typical values are for reference only, and are not tested in production.
[2] DC potential difference.
[3] For devices that do not have a dedicated VREFL and VSS_ANA pins, VREFL and VSS_ANA are tied to VSS internally.
[4] If V_{REFH} is less than V_{DD_ANA}, then voltage inputs greater than V_{REFH} but less than V_{DD_ANA} are allowed but result in a full scale conversion result
[5] ADC selected inputs and unselected dedicated inputs must not exceed V_{DD_ANA} during an ADC conversion. Unselected muxed inputs may exceed V_{DD_ANA} but must not exceed the IO supply associated with the inputs (VDD_IO_X) when a conversion is in progress. If an ADC input may exceed these levels, then a minimum of 1 K series resistance must be used between the source and the ADC input pin.
[6] This resistance is external to MCU. To achieve the best results, the analog source resistance must be kept as low as possible.
[7] There are several types of ADC inputs. To see which channels correspond to which type of ADC inputs, see channel index map in reference manual
[8] If the input come through a mux in the IO pad, add the IO Mux Resistance Adder value to the resistance for the channel type

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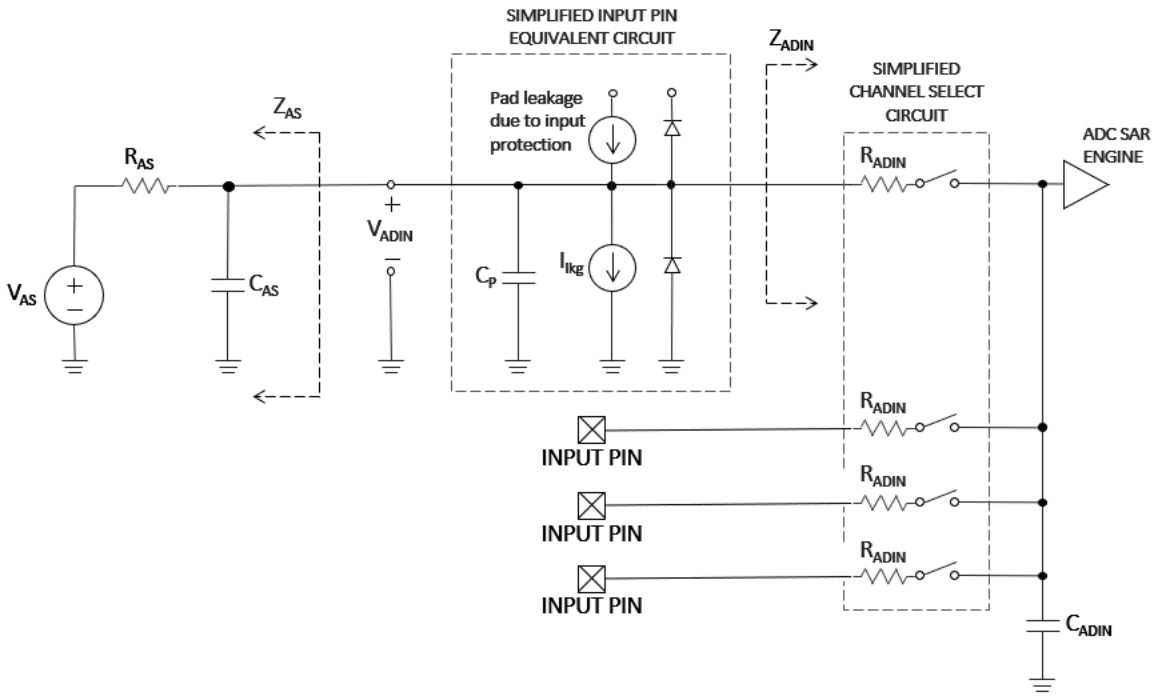


Figure 12. ADC input impedance equivalency diagram

4.5.1.2 16-bit ADC electrical characteristics

Table 48. 16-bit ADC characteristics (VREFH = VDD_ANA, VREFL = VSS_ANA)

Symbol	Description	Min.	Typ.[1]	Max.	Unit	Notes
I_{DDA}	Supply current					
	PWREN=0, Conversions triggered at 1 kS/s	—	2.2	—	µA	[2]
	PWREN=1, No Conversions	—	160	215		
	Low-power, single-ended mode, 6 MHz	—	340	440		
	Low-power, or dual-SE mode, 6 MHz	—	500	640		
	Low-power, single-ended mode, 24 MHz	—	415	530		
	Low-power, or dual-SE mode, 24 MHz	—	580	750		
	High-speed, single-ended mode, 48 MHz	—	940	1200		
	High-speed, or dual-SE mode, 48 MHz	—	1500	1950		
I_{TS}	Temp Sensor Current Adder	—	40	50	µA	—
C_{SMP}	ADC Sample cycles	3.5	—	131.5	cycles	[3]
C_{CONV}	ADC conversion cycles	24	—	152	cycles	—
C_{RATE}	ADC conversion rate					

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Table 48. 16-bit ADC characteristics (VREFH = VDD_ANA, VREFL = VSS_ANA)*...continued*

Symbol	Description	Min.	Typ.[1]	Max.	Unit	Notes
	Low-power mode	—	—	0.857	MS/s	[4]
	High-speed mode (16-bits)	—	—	2		
	High-speed mode (12-bits)	—	—	3.16		
t_{SMP_REQ}	Required Sample Time	See equation	—	—	ns	[5]
t_{AZ_REQ}	Required Auto-zero Time					
	Low-power mode	291.7	—	—	ns	[5]
	High-power mode (16-bits)	72.9	—	—		
	High-power mode (12-bits)	58.3	—	—		
t_{SMP}	Sample Time External inputs	See equation	—	—	ns	[5]
t_{SMP_INT}	Internal channel sample time	1.5	—	—	µs	[6]
DNL	Differential non-linearity	—	±0.7	+1.4/-0.95	LSB[7]	[8]
INL	Integral non-linearity	—	±2.0	+4.0/–2.0	LSB[7]	[8]
Z_{SE}	Zero-scale error (V_{ADIN} = V_{REFL})	—	±1.0	±2.0	LSB[7]	[8]
F_{SE}	Full-scale error (V_{ADIN}=V_{REFH})	—	±2.0	+2.0/–8.0	LSB[7]	[8]
TUE	Total unadjusted error	—	±4.0	±10.0	LSB[7]	[8]
ENOB	Effective number of bits					
	Differential mode, 0.5 MS/s	12.7	13.5	—	bits	[8],[9]
	Differential mode, 2 MS/s	12.0	12.7	—		
	Single-ended mode, 0.5 MS/s	12.4	13.1	—		
	Single-ended mode, 2 MS/s	11.5	12.2	—		
SINAD	Signal-to-noise plus distortion					
	Differential mode, 0.5 MS/s	80	86	—	dB	[8],[9]
	Differential mode, 2 MS/s	75	79	—		
	Single-ended mode, 0.5 MS/s	77	81	—		
	Single-ended mode, 2 MS/s	71	75	—		
THD	Total harmonic distortion	85	92	—	dB	[8],[10]
SFDR	Spurious free dynamic range	86	94	—	dB	[8],[10]
t_{SU}	ADC/VREF start-up time	5	—	—	µs	[11]
E_{IL}	Input leakage error	—	$I_{lkg} \times R_{AS}$	—	mV	[12]
E_{TS}	Temperature sensor error					
	T=–40 °C to 105 °C	—	±1	±3	°C	[13]

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Table 48. 16-bit ADC characteristics (VREFH = VDD_ANA, VREFL = VSS_ANA)*...continued*

Symbol	Description	Min.	Typ.[1]	Max.	Unit	Notes
	T=–40 °C to 125 °C	—	±1.5	±4		

[1] Typical values assume V_{DD_ANA} = 3.0 V, Temp = 25 °C, f_{ADCK} = 24 MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
[2] The ADC supply current depends on the ADC conversion clock speed, conversion rate and power mode. Typical value show is at 6 MHz, 24 MHz, and 48 MHz. For lowest power operation, PWRSEL should be set to 00.
[3] Must meet minimum TSMP requirement.
[4] Maximum conversion rate for high-speed mode is with f_{ADCK} = 48 MHz. Maximum conversion rate for low-power mode is f_{ADCK} = 24 MHz and 7.5 sample cycles (to meet the minimum auto-zero time requirement).
[5] Required sample time is dictated by external components R_{AS}, C_{AS}, internal components R_{ADIN}, C_{ADIN}, C_P, and desired sample accuracy in bits. Calculated it with formula: $T_{SMP_REQ} = B*IN(2)*[R_{AS}*(C_{AS}*C_P)+ (R_{AS} + R_{ADIN})* C_{ADIN(typ)}$. Required auto-zero time is for ADC comparator offset cancellation. The chosen sample time should be no less than maximum of the two: $T_{SMP} = max(T_{SMP_REQ},T_{AZ_REQ})$.
[6] Internal channel inputs are those that do not come from external source (temperature sensor, bandgap).
[7] 1 LSB = $(V_{REFH} - V_{REFL})/2^N$ (N=14 bits), for 16-bit specifications, multiply by 4.
[8] All accuracy numbers assume the ADC is calibrated with V_{REFH}=V_{DD_ANA} and using a high-speed dedicated input channel.
[9] Dynamic results assume F_{in} = 1 kHz sinewave, AVGS = 0 for 2 MS/s, AVGS = 4 for 0.5 MS/s.
[10] Dynamic results assume F_{in} = 1 kHz sinewave, no averaging.
[11] Set the power up delay (PUDLY) according to the ADC start-up time if PWREN=0.
[12] I_{lkg} = leakage current (Refer to pin leakage specification in the packaged device's voltage and current operating ratings).
[13] The temperature sensor can be calibrated to a ± 0.5% precision after board assembly by using a 3 temperature calibration flow with accurate ± 0.15 % temperature chamber.

4.5.2 CMP and 8-bit DAC electrical specifications

Table 49. Comparator and 8-bit DAC electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
VDD_IO_ABC	Supply voltage	1.71	—	3.6	V	—
VREFH	8-bit DAC reference voltage high	0.97	—	VDD_IO_ABC	V	—
I_{DD_CMP}	Supply current					
	High-speed mode (EN=1, HPMD=1)	—	200	—	µA	—
	Normal mode (EN=1, HPMD=0, NPMD=0)	—	10	—	µA	
	Nano mode (EN=1, HPMD=0, NPMD=1)	—	400	—	nA	
V_{AIN}	Analog input voltage	VSS_ANA	—	VDD_ANA	V	[1]
V_{AIO}	Analog input offset voltage					
	High-speed mode	—	—	20	mV	—
	Normal mode	—	—	20		
	Nano mode	—	—	40		
V_H	Analog comparator hysteresis					
	CR0[HYSTCTR] = 00	—	0	—	mV	[2]
	CR0[HYSTCTR] = 01	—	10	—		
	CR0[HYSTCTR] = 10	—	20	—		
	CR0[HYSTCTR] = 11	—	30	—		
t_D	Propagation delay					

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Table 49. Comparator and 8-bit DAC electrical specifications...*continued*

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	High-speed mode, 100 mV overdrive, power > 1.71 V	—	—	25	ns	[3]
	High-speed mode, 30 mV overdrive, power > 1.71 V	—	—	50	ns	
	Normal mode, 30 mV overdrive, power > 1.71 V	—	—	600	ns	
	Nano mode, 30 mV overdrive, power > 1.71 V	—	—	5	µs	
t_{init}	Analog comparator initialization delay	—	—	40	µs	[4]
I_{DAC8b}	8-bit DAC current adder (enabled)					
	High-power mode (EN=1, PMODE=1)	—	10	—	µA	—
	Low-power mode (EN=1, PMODE=0)	—	1	—		
INL	8-bit DAC integral non-linearity					
	Low/High power mode, supply power > 1.71 V	–1.0	—	+1.0	LSB	[5]
DNL	8-bit DAC differential non-linearity					
	Low/High power mode, power > 1.71 V	–1.0	—	+1.0	LSB	[5]

[1] For devices that do not have a dedicated VSS_ANA pin, VSS_ANA is tied to VSS internally.
[2] Typical hysteresis is measured with input voltage range limited to 0.6 to VDD_ANA–0.6 V.
[3] Overdrive does not include input offset voltage or hysteresis.
[4] Comparator initialization delay is defined as the time between software writes to change control inputs (Writes to CMP_DACCR[DACEN], CMP_DACCR[VRSEL], CMP_DACCR[VOSEL], CMP_MUXCR[PSEL], and CMP_MUXCR[MSEL]), and the comparator output settling to a stable level.
[5] 1 LSB = $V_{reference}$/256.

Typical hysteresis

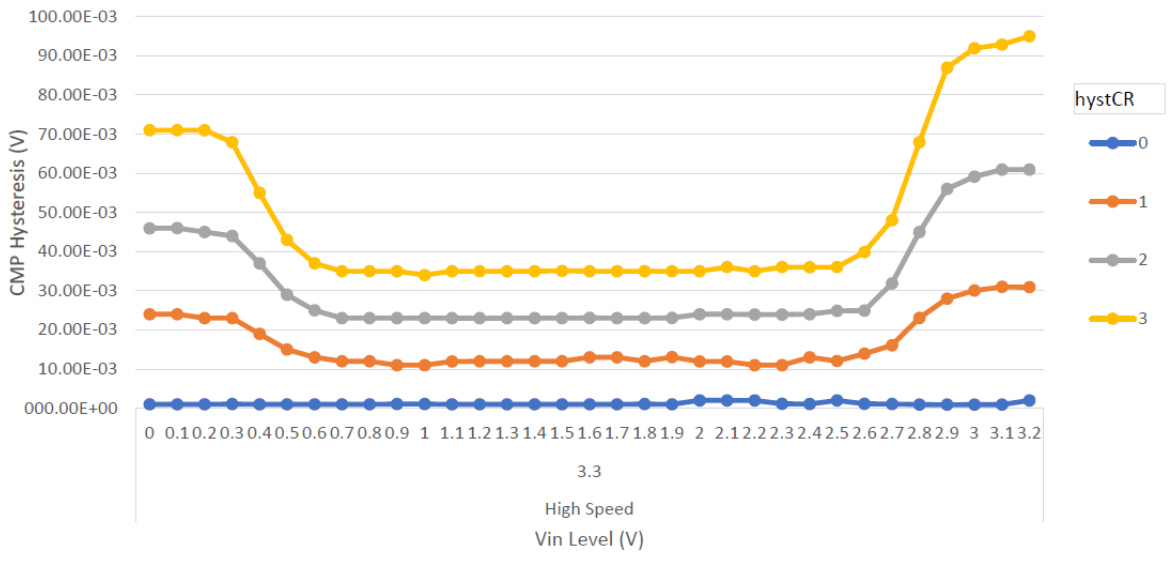


Figure 13. Typical hysteresis vs. Vin level (VDD = 3.3 V, HPMD = 1)

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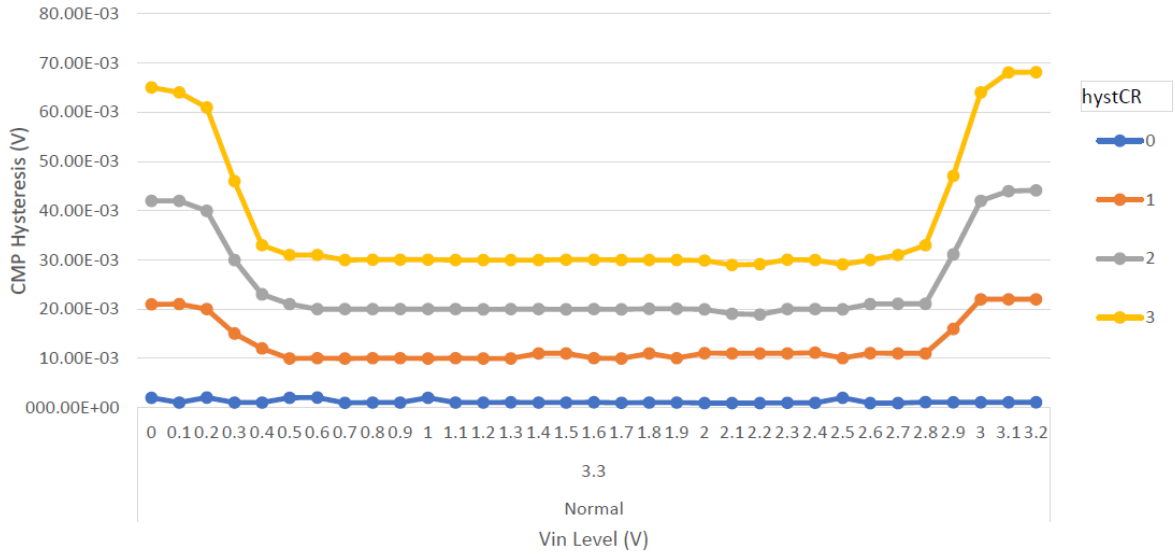


Figure 14. Typical hysteresis vs. Vin level (VDD = 3.3 V, HPMD = 0, NPMD = 0)

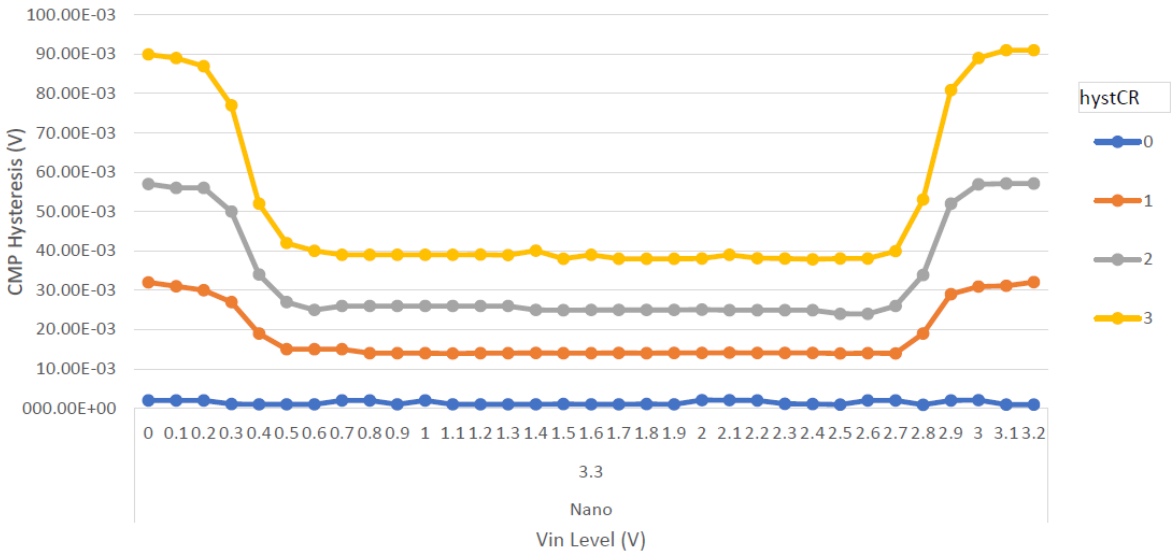


Figure 15. Typical hysteresis vs. Vin level (VDD = 3.3 V, HPMD = 0, NPMD = 1)

4.5.3 Voltage reference electrical specifications

Table 50. VREF operating requirements

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
VDD_ANA	Supply voltage	1.71	3.0	3.6	V	—
C_L	Output load capacitance	130	220	470	nF	[1]

[1] C_L must be connected to VREFO if the VREFO functionality is being used for either an internal or external reference.

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Table 51. VREF operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
1.0 V low-power reference voltage						
V_{vrefo_lpbg}	Voltage reference output 1.0 V - LP bandgap	—	1.0	—	V	[1]
I_{q_lpbg}	Quiescent current - LP bandgap	—	16	—	µA	—
I_{out_lpbg}	Output current - LP bandgap	—	10	—	µA	—
t_{st_lpbg}	Start-up time - LP bandgap	—	6	20	µs	—
$\Delta V/V_{refo_lpbg}$	Voltage variation - LP bandgap	—	±5	—	%	—
High precision reference voltage						
V_{vrefo}	Voltage reference output 2.0 V	1.0	—	2.1	V	[2][1]
V_{step}	Fine trim step	—	0.5 x V_{refo}	—	mV	—
I_q	Quiescent current	—	750	—	µA	—
I_{out}	Output current	±1	—	—	mA	—
t_{st_lpbg}	Start-up time	—	—	400	µs	—
ΔV_{LOAD}	Load regulation	—	100	200	µV/mA	[3]
V_{acc}	Absolute voltage accuracy (room temp)	—	±1.5	±6.5	mV	—
V_{dev}	Voltage deviation over temperature	—	15	—	ppm/°C	—

[1] See the chip's Reference Manual for the appropriate settings of the VREF Status and Control register.
[2] V_{vrefo} max is also ≤ VDD_ANA - 600 mV.
[3] Load regulation voltage is the difference between the VREFO voltage with no load vs. voltage with defined load.

4.6 Timers

See General switching specifications.

4.7 Communication interfaces

4.7.1 LPUART

See General switching specifications.

4.7.2 LPSPI switching specifications

The Low Power Serial Peripheral Interface (LPSPI) provides a synchronous serial bus with controller and target operations. Many of the transfer attributes are programmable. The following tables provide timing characteristics for classic SPI timing modes.

Table 52. LPSPI controller mode timing

Symbol	Description	Min.	Max.	Unit	Notes
LP1	Frequency of operation				
	LPSPI0	—	12	MHz	[1]
	LPSPI1	—	24	MHz	

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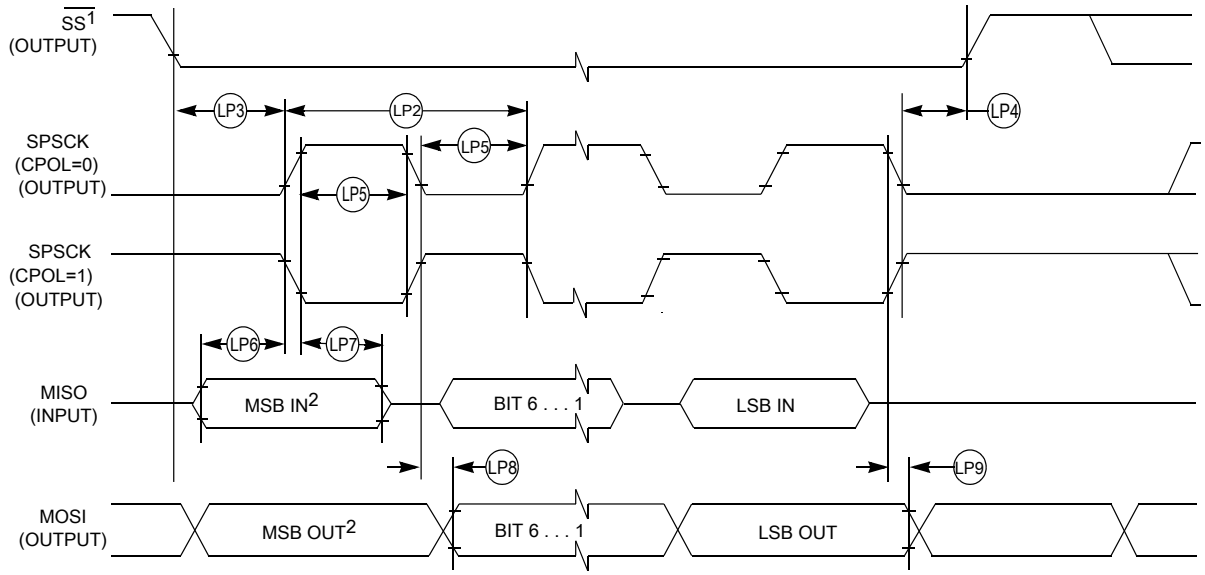
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Table 52. LPSPI controller mode timing...*continued*

Symbol	Description	Min.	Max.	Unit	Notes
LP2	SPSCK period	2 x t_{periph}	2048 x t_{periph}	ns	[2]
LP3	Enable lead time	1/2	—	t_{periph}	[2]
LP4	Enable lag time	1/2	—	t_{periph}	[2]
LP5	Clock (SPSCK) high or low time	t_{SPSCK}/2 - 3	t_{SPSCK}/2	ns	—
LP6	Data setup time (inputs)	8	—	ns	—
LP7	Data hold time (inputs)	0	—	ns	—
LP8	Data valid (after SPSCK edge)	—	6	ns	—
LP9	Data hold time (outputs)	2	—	ns	—

[1] The frequency of operation is also limited to a minimum of f_{periph}/2048 and a max of f_{periph}/2, where f_{periph} is the LPSPI peripheral functional clock.
[2] $t_{periph} = 1/f_{periph}$.

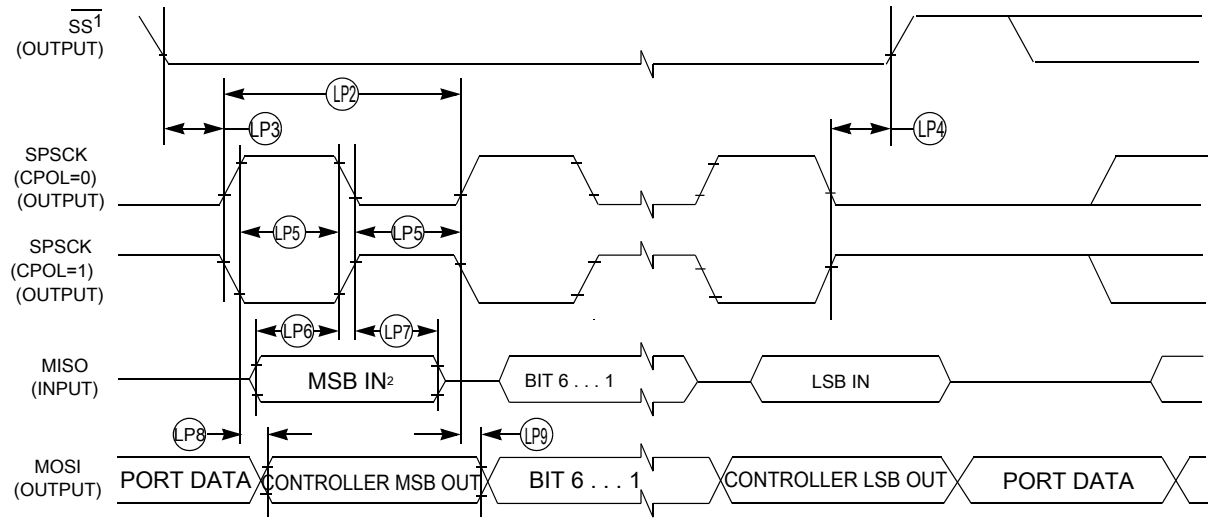


1. If configured as an output.
2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure 16. LPSPI controller mode timing (CPHA = 0)

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1.If configured as output
2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure 17. LPSPI controller mode timing (CPHA = 1)

Table 53. LPSPI target mode timing

Symbol	Description	Min.	Max.	Unit	Notes
LP1	Frequency of operation				
	LPSPI0-LPSPI1	—	12	MHz	[1]
LP2	SPSCK period	4 x t_{periph}	2048 x t_{periph}	ns	[2]
LP3	Enable lead time	1	—	t_{periph}	[2]
LP4	Enable lag time	1	—	t_{periph}	[2]
LP5	Clock (SPSCK) high or low time	t_{SPSCK}/2 - 5	t_{SPSCK}/2	ns	—
LP6	Data setup time (inputs)	8	—	ns	—
LP7	Data hold time (inputs)	1	—	ns	—
LP8	Target access time	—	t_{periph}	ns	[2][3]
LP9	Target MISO disable time	—	t_{periph}	ns	[2][4]
LP10	Data valid (after SPSCK edge)	—	28	ns	—
LP11	Data hold time (outputs)	1	—	ns	—

[1] The frequency of operation is also limited to a minimum of f_{periph}/2048 and a max of f_{periph}/4, where f_{periph} is the LPSPI peripheral functional clock.
[2] $t_{periph} = 1/f_{periph}$.
[3] Time to data active from high-impedance stat.
[4] Hold time to high-impedance state.

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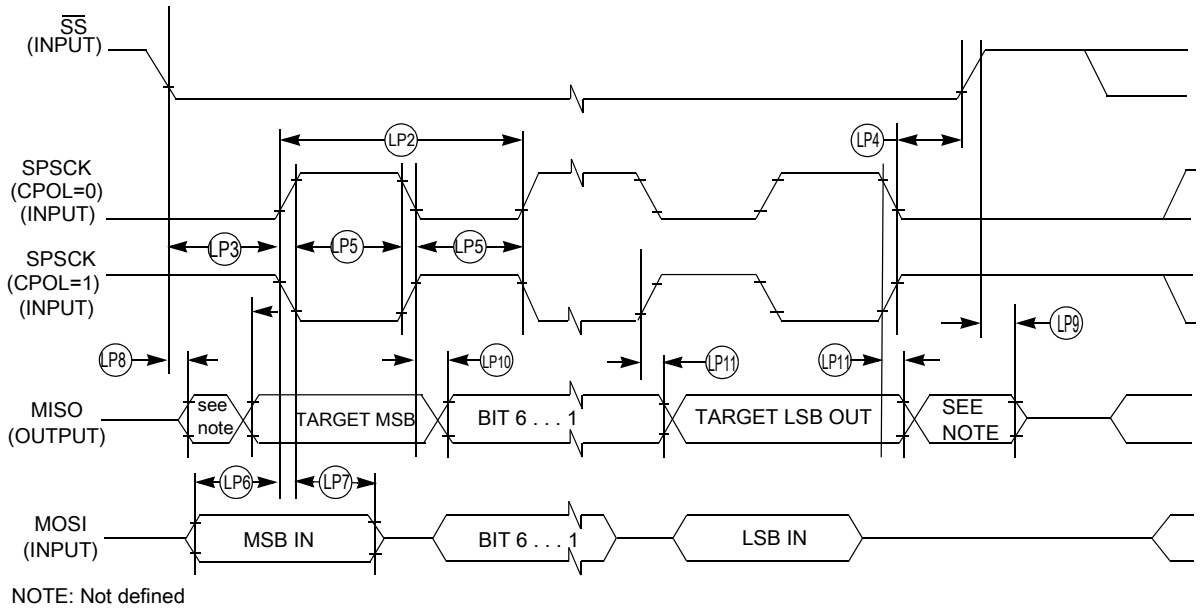


Figure 18. LPSPI target mode timing (CPHA = 0)

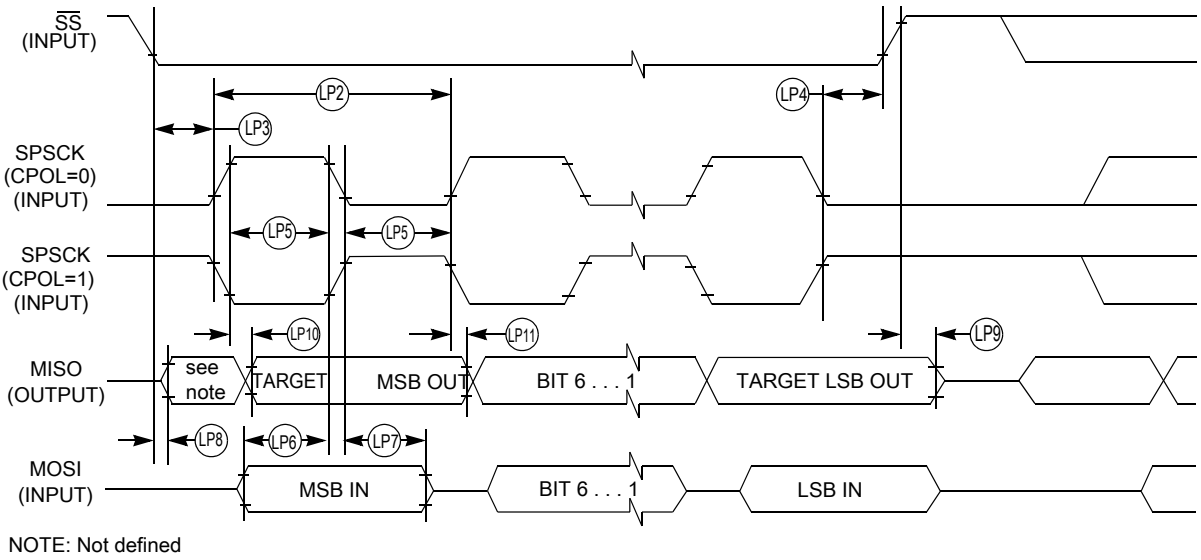


Figure 19. LPSPI target mode timing (CPHA = 1)

4.7.3 Inter-Integrated Circuit Interface (I2C) specifications

Table 54. I2C timing

Characteristic	Symbol	Standard Mode		Fast Mode		Unit
		Min.	Max.	Min.	Max.	
SCL Clock Frequency	f_{SCL}	0	100	0	400	kHz

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Table 54. I2C timing...*continued*

Characteristic	Symbol	Standard Mode		Fast Mode		Unit
		Min.	Max.	Min.	Max.	
Hold time (repeated) START condition. After this period, the first clock pulse is generated.	t_{HD}; STA	4	—	0.6	—	µs
LOW period of the SCL clock	t_{LOW}	4.7	—	1.25	—	µs
HIGH period of the SCL clock	t_{HIGH}	4	—	0.6	—	µs
Set-up time for a repeated START condition	t_{SU}; STA	4.7	—	0.6	—	µs
Data hold time for I2C bus devices	t_{HD}; DAT	0[1],[2]	3.45[3]	0[4],[2]	0.9[1]	µs
Data set-up time	t_{SU}; DAT	250[5]	—	100[3][6]	—	ns
Rise time of SDA and SCL signals	t_r	—	1000	20 +0.1C_b[7]	300	ns
Fall time of SDA and SCL signals	t_f	—	300	20 +0.1C_b[6]	300	ns
Set-up time for STOP condition	t_{SU}; STO	4	—	0.6	—	µs
Bus free time between STOP and START condition	t_{BUF}	4.7	—	1.3	—	µs
Pulse width of spikes that must be suppressed by the input filter	t_{SP}	N/A	N/A	0	50	ns

[1] The controller mode I2C deasserts ACK of an address byte simultaneously with the falling edge of SCL. If no targets acknowledge this address byte, then a negative hold time can result, depending on the edge rates of the SDA and SCL lines.
[2] A device must internally provide a hold time of at least 300 ns for the SDA signal (with respect to the VIH(min) of the SCL signal) to bridge the undefined region of the falling edge of SCL.
[3] The maximum tHD; DAT must be met only if the device does not stretch the LOW period (tLOW) of the SCL signal.
[4] Input signal Slew = 10 ns and Output Load = 50 pF
[5] Set-up time in target-transmitter mode is 1 IPBus clock period, if the TX FIFO is empty.
[6] A Fast mode I2C bus device can be used in a Standard mode I2C bus system, but the requirement $t_{SU;\,DAT} \geq 250$ ns must then be met. This is automatically the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, then it must output the next data bit to the SDA line $t_{rmax} + t_{SU;\,DAT} = 1000 + 250 = 1250$ ns (according to the Standard mode I2C bus specification) before the SCL line is released.
[7] C_b = total capacitance of the one bus line in pF.

Table 55. I2C 1 Mbps timing

Characteristic	Symbol	Min.	Max.	Unit
SCL Clock frequency	f_{SCL}	0	1	MHz
Hold time (repeated) START condition. After this period, the first clock pulse is generated.	t_{HD}; STA	0.26	—	µs
LOW period of the SCL clock	t_{LOW}	0.5	—	µs
HIGH period of the SCL clock	t_{HIGH}	0.26	—	µs
Set-up time for a repeated START condition	t_{SU}; STA	0.26	—	µs
Data hold time for I2C bus devices	t_{HD}; DAT	0	—	µs
Data set-up time	t_{SU}; DAT	50	—	ns
Rise time of SDA and SCL signals	t_r	20 +0.1C_b [1]	120	ns

Table continues on the next page...

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Table 55. I2C 1 Mbps timing*...continued*

Characteristic	Symbol	Min.	Max.	Unit
Fall time of SDA and SCL signals	t_f	20 +0.1C_b[1]	120	ns
Set-up time for STOP condition	t_{SU}; STO	0.26	—	µs
Bus free time between STOP and START condition	t_{BUF}	0.5	—	µs
Pulse width of spikes that must be suppressed by the input filter	t_{SP}	0	50	ns

[1] C_b = total capacitance of the one bus line in pF. The max Cb value is 50 pF.

Table 56. I2C HS mode timing[1]

Parameter	Symbol	Min	Max	Units
SCL Clock frequency	f_{SCL}	0	3.4	MHz
Hold time (repeated) START condition. After this period, the first clock pulse is generated.	t_{HD}; STA	0.26	–	µs
LOW period of the SCL clock	t_{LOW}	0.5	–	µs
High period of the SCL clock	t_{HIGH}	0.26	–	µs
Set-up time for a repeated START condition	t_{SU}; STA	0.26	–	µs
Data hold time for I2C bus devices	t_{HD}; DAT	0[2]	–	µs
Data setup time	t_{SU}; DAT	34	_	ns
Rise time of SDA and SCL signals	t_r	20 +0.1Cb[3]	120	ns
Fall time of SDA and SCL signals	t_f	20 +0.1Cb[3]	120	ns
Setup time for STOP condition	t_{SU}; STO	0.26	_	µs
Bus free time between STOP and START condition	t_{BUF}	0.5	_	µs
Pulse width of spikes that must be suppressed by the input filter	t_{SP}	0	50	ns

[1] Only PTB4/5, PTA18/19, PTC0/1, PTC4/5 pin can support Fast+ (3 MHz) mode.
[2] A device must internally provide a data hold time to bridge the undefined part between VIH and VIL of the falling edge of the SCLH signal. An input circuit with a threshold as low as possible for the falling edge of the SCLH signal minimizes this hold time.
[3] Cb = total capacitance of the one bus line in pF. The max Cb value is 50 pF.

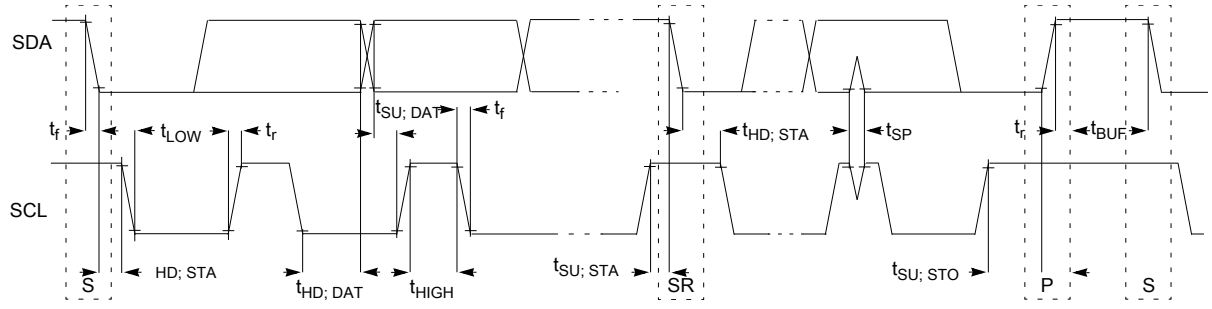


Figure 20. Timing definition for devices on the I2C bus

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4.7.4 Improved Inter-Integrated Circuit Interface (MIPI-I3C) specifications

Unless otherwise specified, MIPI-I3C specifications are timed to/from the V_{IH} and/or V_{IL} signal points.

Table 57. MIPI-I3C specifications when communicating with legacy I2C devices

Symbol	Characteristic	400 kHz/Fast mode		1 MHz/ Fast+ mode		Unit
		Min.	Max.	Min.	Max.	
f_{SCL}	SCL Clock frequency	0	0.4	0	1.0	MHz
t_{SU_STA}	Set-up time for a repeated START condition	600	—	260	—	ns
t_{HD_STA}	Hold time (repeated START condition)	600	—	260	—	ns
t_{LOW}	LOW period of the SCL clock	1300	—	500	—	ns
t_{HIGH}	HIGH period of the SCL clock	600	—	260	—	ns
t_{SU_DAT}	Data set-up time	100	—	50	—	ns
t_{HD_DAT}	Data hold time for I2C bus devices	0	—	0	—	ns
t_f	Fall time of SDA and SCL signals	20 + $0.1C_b$[1]	300	20 + $0.1C_b$[1]	120	ns
t_r	Rise time of SDA and SCL signals	20 + $0.1C_b$[1]	300	20 + $0.1C_b$[1]	120	ns
t_{SU_STO}	Set-up time for STOP condition	600	—	260	—	ns
t_{BUF}	Bus free time between STOP and START condition	1.3	—	0.5	—	µs
t_{SP}	Pulse width of spikes that must be suppressed by the input filter	0	50	0	50	ns

[1] C_b = total capacitance of the one bus line in pF.

Table 58. MIPI-I3C open drain mode specifications

Symbol	Characteristic	Min.	Max.	Unit	Notes
t_{LOW_OD}	LOW period of the SCL clock	200	—	ns	—
$t_{DIG_OD_L}$		t_{LOW_OD} + t_{fDA_OD} (min)	—	ns	—
t_{HIGH}	HIGH period of the SCL clock	t_{CF}	12	ns	—
t_{fDA_OD}	Fall time of SDA signal	20 +$0.1C_b$	120	ns	[1]
t_{SU_OD}	Data set-up time during open drain mode	3	—	ns	—
t_{CAS}	Clock after START (S) Condition				—
	ENTAS0	38.4	1000	ns	
	ENTAS1	38.4	100000	ns	
	ENTAS2	38.4	2000000	ns	
	ENTAS3	38.4	50000000	ns	

Table continues on the next page...

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Table 58. MIPI-I3C open drain mode specifications...*continued*

Symbol	Characteristic	Min.	Max.	Unit	Notes
t_{CBP}	Clock before STOP (P) condition	t_{CAS}(min)/2	—	ns	—
$t_{MMOverlap}$	Current controller to secondary controller overlap time during handoff	$t_{DIG_OD_L}$	—	ns	—
t_{AVAL}	Bus available condition	1	—	µs	—
t_{IDLE}	Bus idle condition	1	—	ms	—
t_{MMLock}	Time internal where new controller not driving SDA low	t_{AVAL}	—	µs	—

[1] C_b = total capacitance of the one bus line in pF.

Table 59. MIPI-I3C push-pull specifications for SDR and HDR-DDR modes

Symbol	Characteristic	Min.	Typ.	Max.	Unit	Notes
f_{SCL}	SCL Clock Frequency	0.01	—	12.5	MHz	—
t_{LOW}	LOW period of the SCL clock	24	—	—	ns	—
t_{DIG_L}		32	—	—	ns	—
t_{HIGH_MIXED}	HIGH period of the SCL clock for a mixed bus	24	—	—	ns	—
$t_{DIG_H_MIXED}$		32	—	45	ns	[1]
t_{HIGH}	HIGH period of the SCL clock	24	—	—	ns	—
t_{DIG_H}		32	—	—	ns	—
tSCO	Clock in to data out for target					
	Load capacitance = 50 pF	—	—	38	ns	—
	Load capacitance = 25 pF	—	—	36	ns	—
	Load capacitance = 15 pF	—	—	35	ns	—
	Load capacitance = 1 pF	—	—	33	ns	—
t_{CR}	SCL clock rise time	—	—	150 x 1/ f_{SCL} (capped at 60)	ns	—
t_{CF}	SCL clock fall time	—	—	150 x 1/ f_{SCL} (capped at 60)	ns	—
t_{HD_PP}	SDA signal data hold					
	Controller mode	t_{CR} + 3 and	—	—	ns	—
	Target mode	t_{CF} + 3	—	—		

Table continues on the next page...

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Table 59. MIPI-I3C push-pull specifications for SDR and HDR-DDR modes...*continued*

Symbol	Characteristic	Min.	Typ.	Max.	Unit	Notes
		0				
t_{SU_PP}	SDA signal setup	3	—	—	ns	—
t_{CASr}	Clock after repeated START (Sr)	t_{CAS} (min)	—	—	ns	—
t_{CBSr}	Clock before repeated START (Sr)	t_{CAS} (min)/2	—	—	ns	—
C_b	Capacitive load per bus line	—	—	50	pF	—

[1] When communicating with an I3C Device on a mixed Bus, the $t_{DIG_H_MIXED}$ period must be constrained in order to make sure that I2C devices do not interpret I3C signaling as valid I2C signaling.

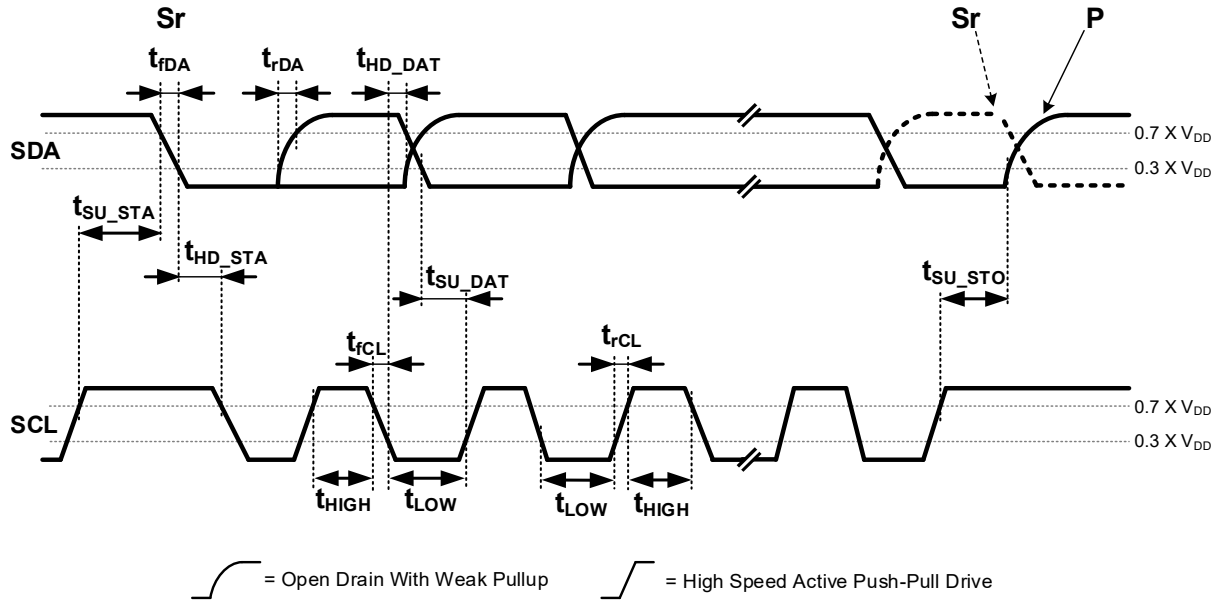


Figure 21. I3C legacy mode timing

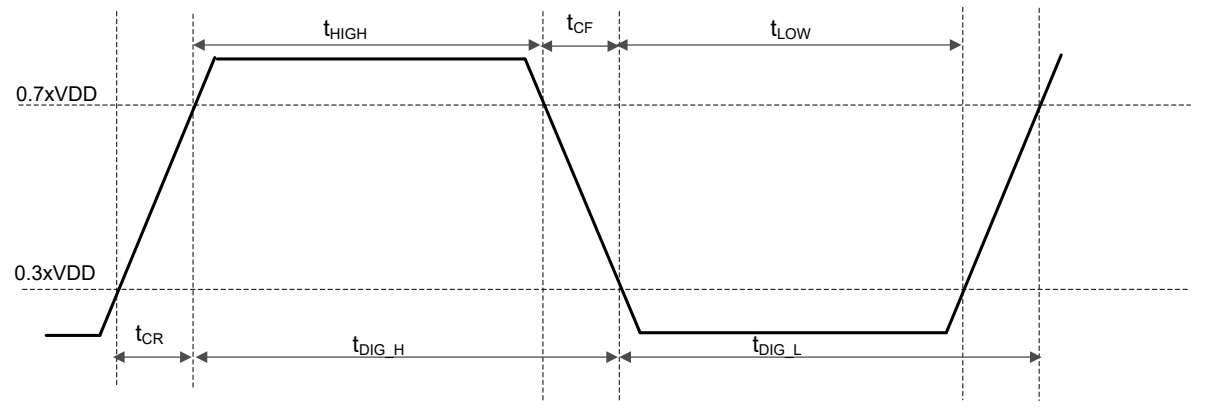


Figure 22. t_{DIG_H} and t_{DIG_L}

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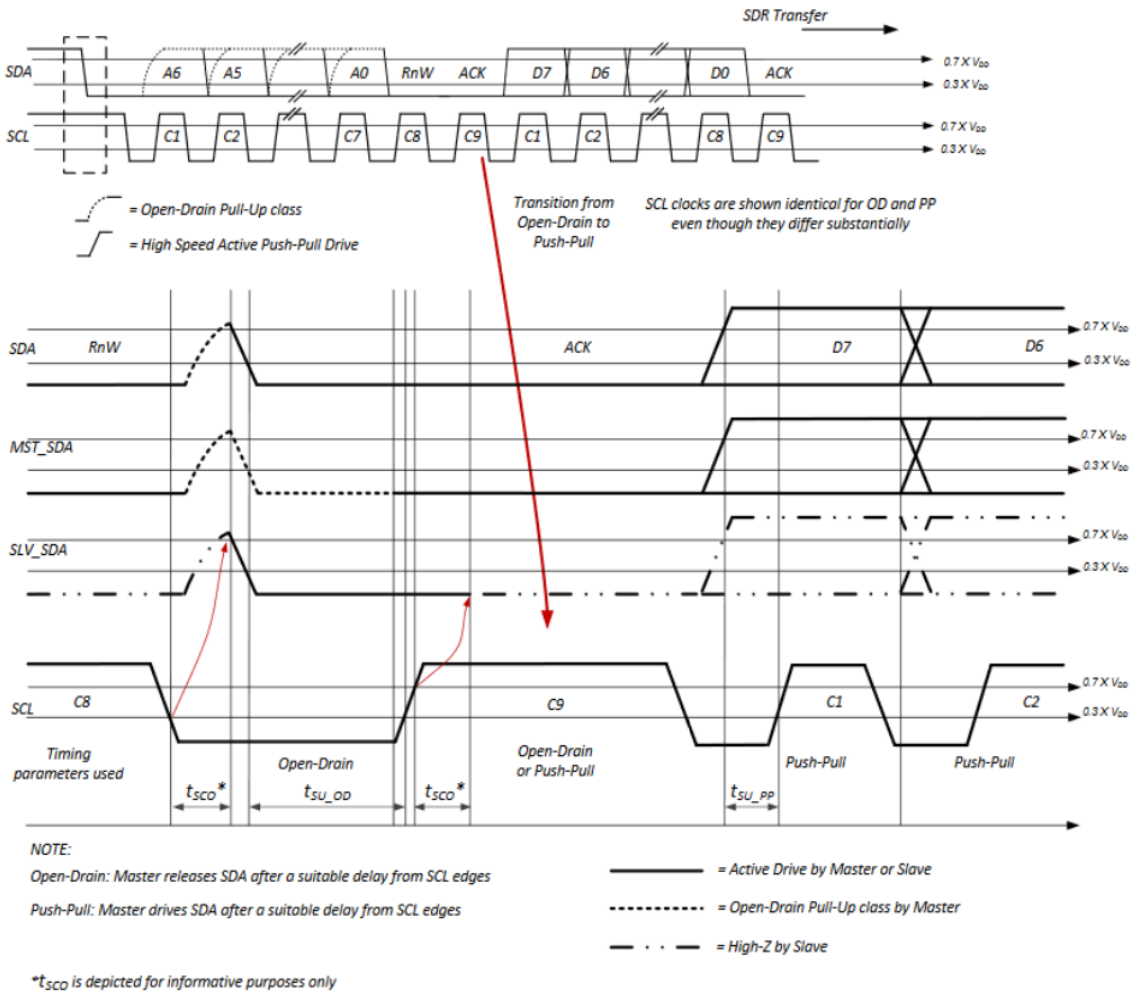


Figure 23. Timing definition for devices on the I3C bus

4.8 Human Machine Interface (HMI) modules

4.8.1 General Purpose Input/Output (GPIO)

See General switching specifications.

4.8.2 Flexible IO controller (FlexIO)

Table 60. FlexIO Timing Specifications

Symbol	Description	Min	Typ	Max	Unit	Notes
t_{ODS}	Output delay skew between any two FlexIO_Dx pins configured as outputs that toggle on same internal clock cycle	0	—	10	ns	[1]
t_{IDS}	Input delay skew between any two FlexIO_Dx pins configured as inputs that are sampled on the same internal clock cycle	0	—	10	ns	[1]

[1] Assumes pins muxed on same VDD_IO domain with same load

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5 Package dimensions

5.1 Obtaining package dimensions

Package dimensions are provided in package drawings.

To find a package drawing, go to nxp.com and perform a keyword search for the drawing's document number:

If you want the drawing for this package	Then use this document number
40-pin HVQFN	SOT618-13(DD)
48-pin HVQFN	SOT619-17(D)

6 Pinout

6.1 Pinout table

Table 61. Pinout table

48HVQFN	40HVQFN	Pin Name	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	ALT8	ALT9	ALT10	ALT11	Wake up
2	1	PTB4	—	PTB4	LPSPI1_PCS3	LPUART1_CTS_b	LPI2C1_SDA	I3C0_SDA	TRGMUX0_IN0	—	—	FLEXIO0_D30	—	—	WUU0_P15
3	2	PTB5	—	PTB5	LPSPI1_PCS2	LPUART1_RTS_b	LPI2C1_SCL	I3C0_SCL	TRGMUX0_OUT0	—	—	FLEXIO0_D31	—	—	—
4	3	VDD_IO_ABC	VDD_IO_ABC	—	—	—	—	—	—	—	—	—	—	—	—
5	4	SWITCH_WAKEUP_B	SWITCH_WAKEUP_B	—	—	—	—	—	—	—	—	—	—	—	—
6	5	VDD_SWITCH	VDD_SWITCH	—	—	—	—	—	—	—	—	—	—	—	—
7	6	VOUT_SWITCH	VOUT_SWITCH	—	—	—	—	—	—	—	—	—	—	—	—
8	7	PTA0	—	PTA0	CMP0_OUT	LPUART0_CTS_b	RF_GPO_11[1]	TPM0_CH4	FLEXIO0_D0	SWD_DIO	—	—	—	—	WUU0_P0

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Table 61. Pinout table*...continued*

48HVQFN	40HVQFN	Pin Name	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	ALT8	ALT9	ALT10	ALT11	Wake up
9	8	PTA1	—	PTA1	CMP1_OUT	LPUART0_RTS_b	RF_GPO_10[1]	TPM0_CH5	FLEXIO0_D1	SWD_CLK	—	—	—	—	—
10	9	PTA4	ADC0_A10/CMP0_IN0	PTA4	—	RF_GPO_9[1]	TPM0_CLKIN	TRACE_SWO	FLEXIO0_D4	BOOT_CONFIG	—	—	—	—	WUU0_P2/RF_XTAL_OUT_ENABLE[1]
11	—	PTA16	ADC0_A12	PTA16	LPSPI0_PCS0	EWM0_OUT_b	LPI2C0_SCLS	TPM0_CH4	LPUART0_RX	RF_GPO_8[1]	—	FLEXIO0_D5	—	—	RF_NOT_ALLOWED[1]
12	10	PTA17	ADC0_A13	PTA17	LPSPI0_SIN	EWM0_IN	LPI2C0_SDAS	TPM0_CH5	LPUART0_TX	RF_GPO_7[1]	RF_GPO_8[1]	FLEXIO0_D6	—	RF_EXT_XTAL_REQUEST/RF_GPO_7[1]	WUU0_P3/RF_NOT_ALLOWED[1]
13	11	PTA18	CMP1_IN1	PTA18	LPSPI0_SOUT	LPUART0_CTS_b	LPI2C0_SDA	TPM0_CH3	RF_GPO_0[1]	—	—	—	LPUART0_RX	SPC0_LPREQ	—
14	12	PTA19	CMP1_IN0/	PTA19	LPSPI0_SCK	LPUART0_RTS_b	LPI2C0_SCL	TPM0_CH2	RF_GPO_1[1]	—	—	—	—	—	WUU0_P4
15	13	VDD_LDO_CORE	VDD_LDO_CORE	—	—	—	—	—	—	—	—	—	—	—	—
16	14	VOUT_CORE/VDD_CORE	VOUT_CORE/VDD_CORE	—	—	—	—	—	—	—	—	—	—	—	—
17	15	PTA20	ADC0_A14/CMP0_IN3	PTA20	LPSPI0_PCS2	LPUART0_TX	EWM0_IN	TPM0_CH1	RF_GPO_2[1]	—	FLEXIO0_D7	—	—	—	—

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Table 61. Pinout table*...continued*

48HVQFN	40HVQFN	Pin Name	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	ALT8	ALT9	ALT10	ALT11	Wake up
18	16	PTA21	ADC0_A15/CMP0_IN2	PTA21	LPSPI0_PCS3	LPUART0_RX	EWM0_OUT_b	TPM0_CH0	RF_GPO_3[1]	RF_GPO_7[1]	FLEXIO0_D8	RF_GPO_10[1]	—	—	WUU0_P5
19	17	VSS_DCDC	VSS_DCDC	—	—	—	—	—	—	—	—	—	—	—	—
20	18	DCDC_LX	DCDC_LX	—	—	—	—	—	—	—	—	—	—	—	—
21	19	VDD_IO_D/VDD_DCDC	VDD_IO_D/VDD_DCDC	—	—	—	—	—	—	—	—	—	—	—	—
22	20	VOUT_SYS/VDD_SYS	VOUT_SYS/VDD_SYS	—	—	—	—	—	—	—	—	—	—	—	—
23	21	PTD0	ADC0_A5	PTD0	—	RESET_b	—	—	—	—	—	—	—	—	—
24	—	PTD1	ADC0_B5	PTD1	SPC0_LPREQ	NMI_b	RF_GPO_4[1]	—	—	—	—	—	—	—	—
25	—	PTD2	ADC0_A6	PTD2	LPTMR0_ALT3	TAMPER0	RF_GPO_5[1]	—	—	—	—	—	—	—	—
26	—	PTD3	ADC0_B6	PTD3	LPTMR1_ALT3	TAMPER1	RF_GPO_6[1]	—	TRGMUX0_IN2	—	—	—	—	—	—
27	22	PTD4	XTAL32K	PTD4	LPTMR0_ALT2	TAMPER2	—	—	—	—	—	—	—	—	—
28	23	PTD5	EXTAL32K	PTD5	LPTMR1_ALT2	—	—	—	—	—	—	—	—	—	—
29	24	VDD_ANA	VDD_ANA	—	—	—	—	—	—	—	—	—	—	—	—
30	25	VREFO	VREFO	—	—	—	—	—	—	—	—	—	—	—	—
49	41	VREFL[2]	VREFL	—	—	—	—	—	—	—	—	—	—	—	—

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Table 61. Pinout table*...continued*

48HVQFN	40HVQFN	Pin Name	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	ALT8	ALT9	ALT10	ALT11	Wake up
31	—	XTAL_OUT	XTAL_OUT	—	—	—	—	—	—	—	—	—	—	—	—
32	26	XTAL	XTAL	—	—	—	—	—	—	—	—	—	—	—	—
33	27	EXTAL	EXTAL	—	—	—	—	—	—	—	—	—	—	—	—
34	28	VDD_RF	VDD_RF	—	—	—	—	—	—	—	—	—	—	—	—
35	29	ANT_2P4GHZ[1],[3]	ANT_2P4GHZ[1]	—	—	—	—	—	—	—	—	—	—	—	—
36	30	VPA_2P4GHZ[1],[3]	VPA_2P4GHZ[1]	—	—	—	—	—	—	—	—	—	—	—	—
37	—	PTC0	—	PTC0	LPSPI1_PCS2	CAN0_TX[4]	I3C0_SDA	TPM1_CH0	—	LPI2C1_SCL	—	FLEXIO0_D16	—	—	WUU0_P7
38	—	PTC1	—	PTC1	LPSPI1_PCS3	CAN0_RX[4]	I3C0_SCL	TPM1_CH1	—	LPI2C1_SDA	—	FLEXIO0_D17	—	—	WUU0_P8
39	31	PTC2	—	PTC2	LPSPI1_SOUT	LPUART1_RX	LPI2C1_SCLS	TPM1_CH2	—	I3C0_PUR	—	FLEXIO0_D18	—	—	WUU0_P9
40	32	PTC3	—	PTC3	LPSPI1_SCK	LPUART1_TX	LPI2C1_SDAS	TPM1_CH3	—	—	—	FLEXIO0_D19	—	—	—
41	33	VDD_CORE	VDD_CORE	—	—	—	—	—	—	—	—	—	—	—	—
42	34	PTC4	—	PTC4	LPSPI1_SIN	CAN0_TX[4]	LPI2C1_SCL	—	TPM2_CH0[1]	—	—	FLEXIO0_D20	—	—	WUU0_P10
43	35	PTC5	—	PTC5	LPSPI1_PCS0	CAN0_RX[4]	LPI2C1_SDA	TPM1_CH4	TPM2_CH1[1]	—	—	FLEXIO0_D21	—	—	—
44	[5]	PTC6	ADC0_A8	PTC6	LPSPI1_PCS1	—	—	TPM1_CH5	—	—	—	FLEXIO0_D22	—	—	WUU0_P11

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Table 61. Pinout table*...continued*

48HVQFN	40HVQFN	Pin Name	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	ALT8	ALT9	ALT10	ALT11	Wake up
45	36	PTC7	—	PTC7	TRGMUX0_IN3	TRGMUX0_OUT3	SFA0_CLK	TPM1_CLKIN	TPM2_CLKIN[1]	CLKOUT	—	FLEXIO0_D23	—	—	WUU0_P12 / NMI_b / RF_NOT_ALLOWED [1]
46	37	PTB0	ADC0_B10	PTB0	LPSPI1_PCS0	—	—	TPM1_CH0	—	—	—	FLEXIO0_D26	—	—	WUU0_P13
47	38	PTB1	ADC0_B11	PTB1	LPSPI1_SIN	—	—	TPM1_CH1	—	—	—	FLEXIO0_D27	—	—	—
48	39	PTB2	ADC0_B12	PTB2	LPSPI1_SCK	LPUART1_TX	—	TPM1_CH2	—	—	—	FLEXIO0_D28	—	—	—
1	40	PTB3	ADC0_B13	PTB3	LPSPI1_SOUT	LPUART1_RX	—	TPM1_CH3	—	—	—	FLEXIO0_D29	—	—	WUU0_P14
49	41	VSS	VSS	—	—	—	—	—	—	—	—	—	—	—	—

[1] This signal is not available for the parts without Radio modules.
[2] VREF shorts to VSS.
[3] For the parts that have no radio modules, this pin is not connected.
[4] This signal is not available for the parts without CAN module.
[5] PTC6_WUU0_P11 pin signal available only as a wake up source for FlexCAN module on signal CAN0_RX from pin PTC5. Other configuration on PTC6 shall not be used.

6.2 Recommended connection for unused analog and digital pins

Table 62 shows the recommended connections for pins if those pins are not used in the customer's application

Table 62. Recommended connection for unused interfaces

Pin Type	Pin Function	Recommendation	Comments
Power	VDD_LDO_CORE	Connect to VOUT_CORE	When LDO-CORE is not used, the VDD_LDO_CORE and VDD_CORE need to be shorted together and supplied at the VDD_CORE voltage level. The LDO-CORE can be disabled in software.
Power	VOUT_CORE	Connect to VDD_LDO_CORE add VSS	When the LDO is not used, the input and output should be connected together and tied to ground through a 10 kΩ resistor. The regulator should also be disabled in software.

Table continues on the next page...

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Table 62. Recommended connection for unused interfaces...*continued*

Pin Type	Pin Function	Recommendation	Comments
Power	VOUT_SYS	1.5 µF - 10 µF Capacitor	Connect a capacitor between range 1.5 µF and 10 µF as specified in the LDO_SYS electrical specifications table. External capacitors are needed for output stability
Power	VDD_DCDC	Ground	When the DCDC is not used, the input should be tied to VSS through a 10 kΩ resistor.
Power	DCDC_LX	Float	—
Power	VDD_IO_D	Must be powered	VDD_IO_D is used to power parts of the system power controller (SPC) and must be powered to use the chip. If LDO_SYS is not being used, then tie VDD_IO_D to VOUT_SYS and supply power from an external source. The regulator should also be disabled in software.
Power	VDD_SWITCH	Must be powered	Powers FRO16 and a portion of RAM.
Power	VOUT_SWITCH	Float	—
Power	VDD_IO_ABC	Must be powered	VDD_IO_ABC powers the mux logic for PORTA, PORTB and PORTC. It must be powered during POR. The recommendation is to keep it powered, but it can be connected to the output of the Smart Power Switch and be left floating in shelf storage mode.
Power	VPA_2P4GHz	Float/Connect to ANT_2P4GHZ	Float-The pin must be left floating when the radio is not used in the application. Connect to ANT_2P4GHz-The pin shall be connected to the ANT pin in applications that use the radio.
Power	VDD_ANA	Float	—
Power	VREFH	Always connect to VDD_ANA potential	Always connect to VDD_ANA potential
Power	VREFL	Always connect to VSS potential	Always connect to VSS potential
Power	VSS_ANA	Always connect to VSS potential	Always connect to VSS potential
Power	VSS_DCDC	Always connect to VSS potential	Always connect to VSS potential
Power	VSS_RF	Always connect to VSS potential	Always connect to VSS potential
Analog/non-GPIO	ADC*n_x*	Float	—
Analog/non-GPIO	VREFO	Float	Analog output - Float
Analog/non-GPIO	TAMPERx	Float	—
Analog/non-GPIO	RTC_WAKEUP_B	Float	—

Table continues on the next page...

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Table 62. Recommended connection for unused interfaces...*continued*

Pin Type	Pin Function	Recommendation	Comments
Analog/non-GPIO	RTC_RTCCLKOUT	Float	—
Analog/non-GPIO	EXTAL32K	Float	—
Analog/non-GPIO	XTAL32K	Float	Analog output - Float
Analog/non-GPIO	EXTAL_32M	Float	—
Analog/non-GPIO	XTAL_32M	Float	Analog output - Float
GPIO/Analog	PTx/CMP*n*_IN*x*	Float	Float (default is analog input)
GPIO/Digital	PTD1/NMI_b	10kΩ pullup or disable and float	Pull high or disable in PCR & FOPT and float
GPIO/Digital	PTx	Float	Float (default is disabled)

6.3 Pinouts diagram

The below figure shows the pinout diagram for the devices supported by this document. Many signals may be multiplexed onto a single pin. To determine what signals can be used on which pin, see the previous section.

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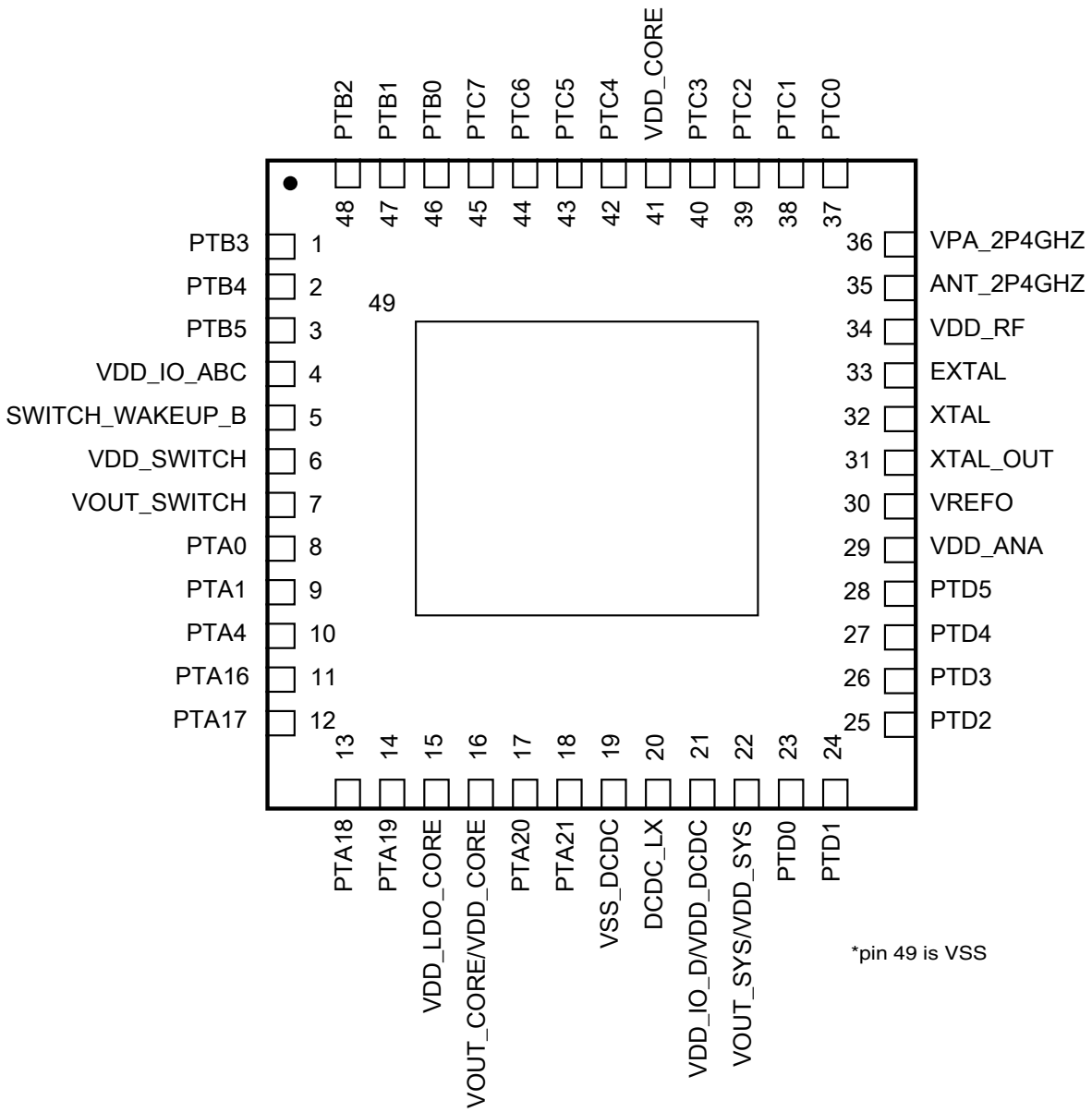


Figure 24. 48-pin HVQFN package pinout diagram

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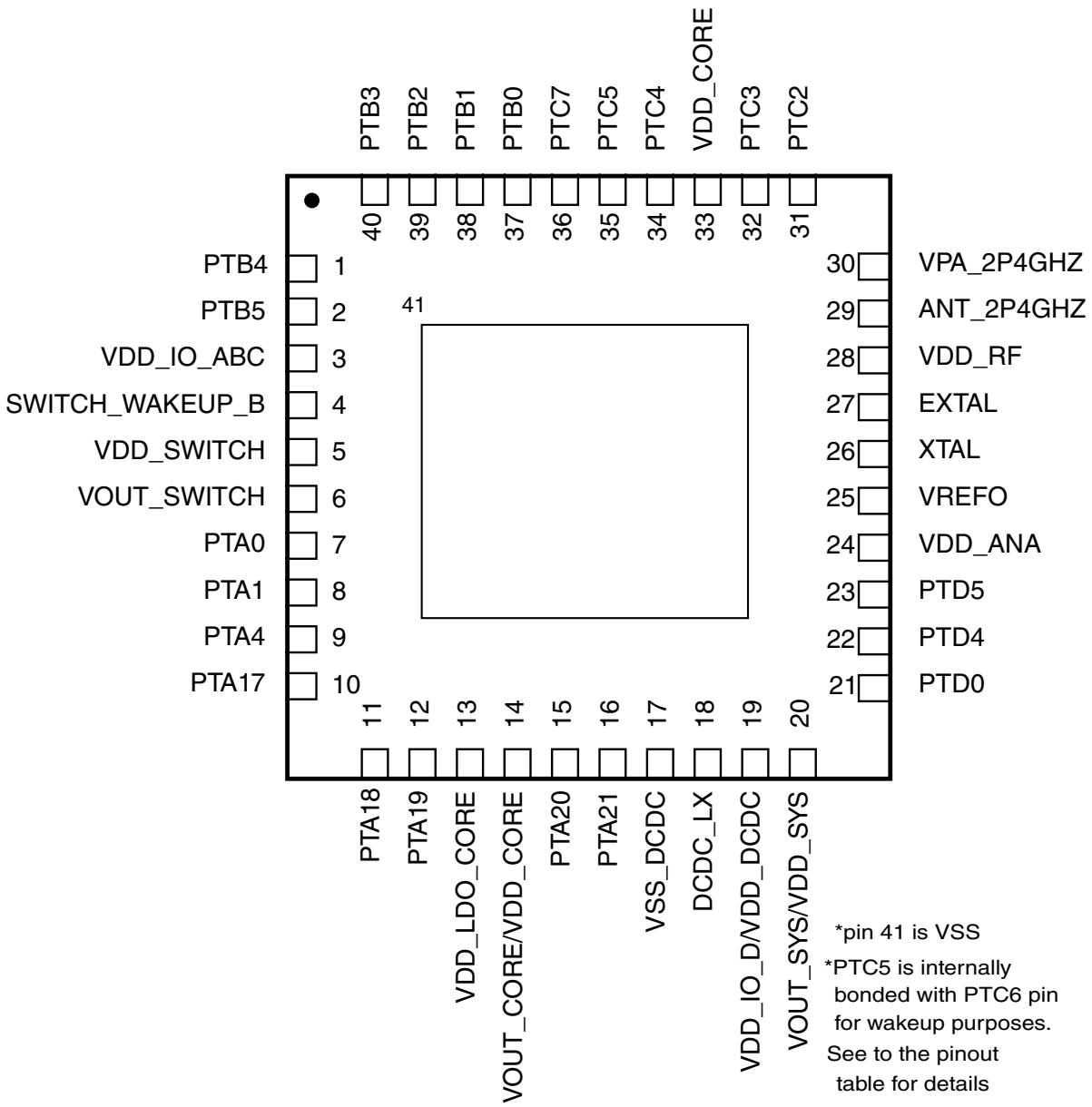


Figure 25. 40-pin HVQFN package pinout diagram

7 Ordering parts

7.1 Determining valid orderable parts

Valid orderable part numbers are provided on the web. To determine the orderable part numbers for this device, go to nxp.com and perform a part number search for the following device numbers:MCXW716

8 Part identification

Part numbers for the device have fields that identify the specific part. Use the values of these fields to determine the specific part.

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8.1 Part number format

Part numbers for this device have the following format:

B PS SF R F SF T PG SR PT

Table 63. Part number fields descriptions

Field	Description	Values
B	Brand	• MCX
PS	Product series name	• W= Wireless
SF	Sub Family	• 7= Performance Class
R	Radio	• 1= Bluetooth LE + 802.15.4
F	Flash Size	• 6= 1 MB
SF	Sub Feature	• A= Baseline • C= CAN
T	Temperature	• M= Industrial, –40 °C to + 125 °C (Ta)
PG	Package	• FT= 48 HVQFN "Wettable", 7 mm x 7 mm, 0.5p • FP= 40 HVQFN "Wettable", 6 mm x 6 mm, 0.5p
SR	Silicon Revision	• A= Production Mask Set
PT	Package Type	• T= Tray • R= Tape and Reel

8.2 Example

This is an example part number:

MCXW716AMFTAT

8.3 Package marking

Part numbers for this device have the following format:

B PS SF R F SF T PG SR

Table 64. Package Marking

Field	Description	Values
B	Brand	MCX
PS	Product series name	W= Wireless
SF	Sub Family	7= Performance Class
R	Radio	1= Bluetooth LE + 802.15.4
F	Flash Size	6= 1 MB

Table continues on the next page...

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Table 64. Package Marking...*continued*

Field	Description	Values
SF	Sub Feature	A= Baseline
		C= CAN
T	Temperature	M=Industrial, –40 ºC to + 125 ºC (Ta)
PG	Package	FT= 48 HVQFN “Wettable”, 7 mm x 7 mm, 0.5p
		FP= 40 HVQFN “Wettable”, 6 mm x 6 mm, 0.5p
SR	Silicon Revision	A= Production Mask Set

8.3.1 Package marking information

The MCXW71 package has the following top-side marking:

- First line: aaaaaa
- Second line: aaaaaa
- Third line: mmmmm
- Fourth line: xxxywwxx

Table 65. Package marking

Identifier	Description
a	Reduced part number code, refer to Package marking table
m	Mask set
y	Year
w	Work week
x	NXP internal use

9 Terminology and guidelines

9.1 Definitions

Key terms are defined in the following table:

Term	Definition
Rating	A minimum or maximum value of a technical characteristic that, if exceeded, may cause permanent chip failure: • *Operating ratings* apply during operation of the chip. • *Handling ratings* apply when the chip is not powered. ***Note:*** *The likelihood of permanent chip failure increases rapidly as soon as a characteristic begins to exceed one of its operating ratings.*

Table continues on the next page...

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Table continued from the previous page...

Term	Definition
Operating requirement	A specified value or range of values for a technical characteristic that you must guarantee during operation to avoid incorrect operation and possibly decreasing the useful life of the chip
Operating behavior	A specified value or range of values for a technical characteristic that are guaranteed during operation if you meet the operating requirements and any other specified conditions
Typical value	A specified value for a technical characteristic that: • Lies within the range of values specified by the operating behavior • Is representative of that characteristic during operation when you meet the typical-value conditions or other specified conditions ***Note:*** *Typical values are provided as design guidelines and are neither tested nor guaranteed.*

9.2 Examples

Operating rating:

Symbol	Description	Min.	Max.	Unit
V_{DD}	1.0 V core supply voltage	–0.3	1.2	V

EXAMPLE

Operating requirement:

Symbol	Description	Min.	Max.	Unit
V_{DD}	1.0 V core supply voltage	0.9	1.1	V

EXAMPLE

Operating behavior that includes a *typical value*:

Symbol	Description	Min.	Typ.	Max.	Unit
I_{WP}	Digital I/O weak pullup/pulldown current	10	70	130	µA

EXAMPLE

9.3 Typical-value conditions

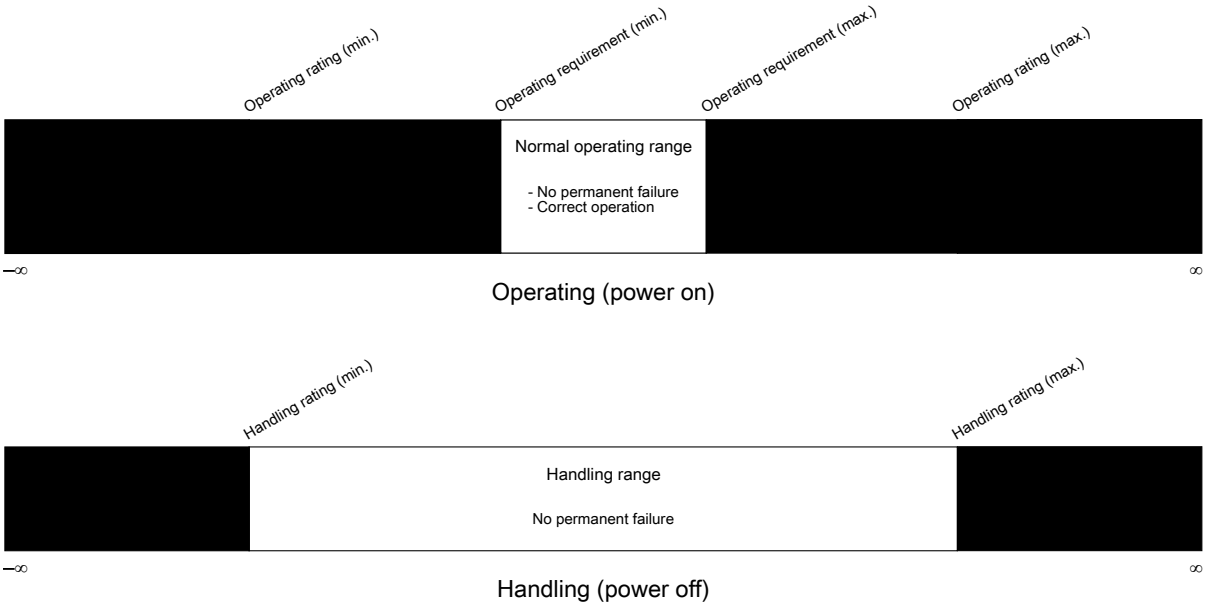
Typical values assume you meet the following conditions (or other conditions as specified):

Symbol	Description	Value	Unit
T_A	Ambient temperature	25	°C
V_{DD}	Supply voltage	3.3	V

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9.4 Relationship between ratings and operating requirements



9.5 Guidelines for ratings and operating requirements

Follow these guidelines for ratings and operating requirements:

- Never exceed any of the chip's ratings.
- During normal operation, don't exceed any of the chip's operating requirements.
- If you must exceed an operating requirement at times other than during normal operation (for example, during power sequencing), limit the duration as much as possible.

10 Abbreviations and Acronyms

The following table provides the list of abbreviations and acronyms their definitions.

Table 66. Abbreviations and Acronyms and their definition

Abbreviations and Acronyms	Definitions
ADC	Analog-to-Digital Converter
AXBS	Crossbar Switch
CMC	Core Mode Controller
CRC	Cyclic Redundancy Check
CTI	Cross Trigger Interface
DAP	Debug Access Port
DMA	Direct Memory Access
DSP	Digital Signal Processing
DWT	Data Watchpoint and Trace
EWM	External Watchdog Monitor

Table continues on the next page...

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Table 66. Abbreviations and Acronyms and their definition...*continued*

Abbreviations and Acronyms	Definitions
FRO	Free Running Oscillator
FMC	Flash Memory Controller
FPU	Floating Point Unit
GPIO	General-purpose Input and Output
I3C	Improved Inter-Integrated Circuit
ITM	Instruction Trace Macrocell
LPCMP	Low Power Comparator
LPI2C	Low Power Inter-Integrated Circuit
LPIT	Low Power Periodic Interrupt Timer
LPSPI	Low Power Serial Peripheral Interface
LPTMR	Low-Power Timer
LPUART	Low Power Universal Asynchronous Receiver/ Transmitter
MPU	Memory Protection Unit
MRCC	Module Reset and Clock Control
MSCM	Miscellaneous System Control Module
MU	Messaging Unit
NBU	Narrowband Unit
NPX	FMC with NVM PRINCE Encryption and Decryption
NVIC	Nested Vectored Interrupt Controller
NVM	Non-Volatile Memory
OSC	Oscillator
RFMC	Radio Mode Controller
RTC	Real Time Clock
SEMA42	Semaphore Module
SCG	System Clock Generator
SFA	Signal Frequency Analyzer
SMSCM	Secure Miscellaneous System Control Module
SPC	System Power Controller
SWD	Serial Wire Debug
TPIU	Trace Port Interface Unit
TPM	Timer/PWM Module
TRDC	Trusted Resource Domain Controller

Table continues on the next page...

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Table 66. Abbreviations and Acronyms and their definition...*continued*

Abbreviations and Acronyms	Definitions
TRNG	True Random Number Generator
TRGMUX	Trigger Multiplexer
TSTMR	Time Stamp Timer
VREF	Voltage Reference
WDOG	Watchdog
WUU	Wake-Up Unit

11 Revision history

The following table provides a revision history for this document.

Table 67. Revision History

Document ID	Release date	Description
MCXW71 v.3.0	29 September 2026	• Updated the description in Introduction • Updated the VDD_CORE value in Voltage and current operating requirements • Updated the C_{OUT} value in LDO_SYS electrical specifications • Changed the description of IDD_ACT16 in Power consumption operating behaviors • Added symbol name in Reference oscillator specification, Receiver feature summary and Transmit and PLL feature summary • Changed the Bluetooth version to 6.3 • Added the description about NBU in Introduction
MCXW71 v.2.0	01 September 2024	• Initial release

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Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[1] Please consult the most recently issued document before initiating or completing a design.
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